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Continuity of ordering part numbers

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.



CY9B320TA Series

32-bit Arm® Cortex®-M3 FM3 Microcontroller

The CY9B320TA Series are highly integrated 32-bit microcontrollers dedicated for embedded controllers with low-power consumption mode and competitive cost.

These series are based on the Arm® Cortex®-M3 Processor with on-chip Flash memory and SRAM, and have peripheral functions such as various timers, ADCs, DACs and Communication Interfaces (USB, UART, CSIO, I²C, LIN).

The products which are described in this data sheet are placed into TYPE12 product categories in “FM3 Family PERIPHERAL MANUAL”.

Features

32-bit Arm® Cortex®-M3 Core

- Processor version: r2p1
- Up to 60 MHz Frequency Operation
- Integrated Nested Vectored Interrupt Controller (NVIC): 1 NMI (non-maskable interrupt) and 48 peripheral interrupts and 16 priority levels
- 24-bit System timer (Sys Tick): System timer for OS task management

On-chip Memories

[Flash memory]

- Dual operation Flash memory
 - Main area:
 - Up to 1.5 Mbytes (1008 Kbytes(ROM0) + 512 Kbytes (ROM1) of Upper bank and 16 Kbytes(ROM0) of Lower bank.)
 - Work area
 - 64 Kbytes(ROM1) of Lower bank
- Read cycle: 0 wait-cycle
- Security function for code protection

[SRAM]

This Series on-chip SRAM is composed of two independent SRAM (SRAM0, SRAM1). SRAM0 is connected to I-code bus and D-code bus of Cortex-M3 core. SRAM1 is connected to System bus.

- SRAM0: Up to 96 Kbytes
- SRAM1: Up to 96 Kbytes

External Bus Interface

- Supports SRAM, NOR NAND Flash memory device
- Up to 8 chip selects
- 8-/16-bit Data width
- Up to 25-bit Address bit
- Maximum area size: Up to 256 Mbytes
- Supports Address/Data multiplex
- Supports external RDY function

USB Interface

The USB interface is composed of Device and Host. PLL for USB is built-in, USB clock can be generated by multiplication of Main clock.

[USB Device]

- USB2.0 Full-Speed supported
- Max 6 EndPoint supported
 - EndPoint 0 is control transfer
 - EndPoint 1, 2 can select Bulk-transfer, Interrupt-transfer or Isochronous-transfer
 - EndPoint 3 to 5 can select Bulk-transfer or Interrupt-transfer
 - EndPoint 1 to 5 are comprised of Double Buffers.
 - The size of each EndPoint is as follows.
 - EndPoint 0, 2 to 5: 64 bytes
 - EndPoint 1: 256 bytes

[USB host]

- USB2.0 Full/Low-speed supported
- Bulk-transfer, interrupt-transfer and Isochronous-transfer support
- USB Device connected/dis-connected automatic detection
- Automatic processing of the IN/OUT token handshake packet
- Max 256-byte packet-length supported
- Wake-up function supported

Multi-function Serial Interface (Max 16channels)

- 16 channels with 16 steps×9-bit FIFO
- Operation mode is selectable from the followings for each channel.
 - UART
 - CSIO
 - LIN
 - I²C

[UART]

- Full duplex double buffer
- Selection with or without parity supported
- Built-in dedicated baud rate generator
- External clock available as a serial clock
- Hardware Flow control: Automatically control the transmission/reception by CTS/RTS (only ch.4)
- Various error detection functions available (parity errors, framing errors, and overrun errors)

[CSIO]

- Full duplex double buffer
- Built-in dedicated baud rate generator
- Overrun error detection function available

[LIN]

- LIN protocol Rev.2.1 supported
- Full duplex double buffer
- Master/Slave mode supported
- LIN break field generation (can be changed to 13 to 16-bit length)
- LIN break delimiter generation (can be changed to 1 to 4-bit length)
- Various error detection functions available (parity errors, framing errors, and overrun errors)

[I²C]

Standard - mode (Max 100 kbps) / Fast - mode (Max 400 kbps) supported

DMA Controller (8channels)

The DMA Controller has an independent bus from the CPU, so CPU and DMA Controller can process simultaneously.

- 8 independently configured and operated channels
- Transfer can be started by software or request from the built-in peripherals
- Transfer address area: 32-bit (4 Gbytes)
- Transfer mode: Block transfer/Burst transfer/Demand transfer
- Transfer data type: byte/half-word/word
- Transfer block count: 1 to 16
- Number of transfers: 1 to 65536

A/D Converter (Max 24channels)**[12-bit A/D Converter]**

- Successive Approximation type
- Built-in 2 units
- Conversion time: 1.0 μs @ 2.7 V to 5.5 V
- Priority conversion available (priority at 2levels)
- Scanning conversion mode
- Built-in FIFO for conversion data storage (for SCAN conversion: 16 steps, for Priority conversion: 4 steps)

D/A Converter (Max 2channels)

- R-2R type
- 10-bit resolution

Base Timer (Max 16channels)

Operation mode is selectable from the followings for each channel.

- 16-bit PWM timer
- 16-bit PPG timer
- 16-/32-bit reload timer
- 16-/32-bit PWC timer

General-Purpose I/O Port

This series can use its pins as general-purpose I/O ports when they are not used for external bus or peripherals. Moreover, the port relocate function is built in. It can set which I/O port the peripheral function can be allocated to.

- Capable of pull-up control per pin
- Capable of reading pin level directly
- Built-in the port relocate function
- Up to 154 high-speed general-purpose I/O Ports@176 pin Package
- Some ports are 5V tolerant.
See "List of Pin Functions" and "I/O Circuit Type" to confirm the corresponding pins.

Dual Timer (32-/16-bit Down Counter)

The Dual Timer consists of two programmable 32-/16-bit down counters.
Operation mode is selectable from the followings for each channel.

- Free-running
- Periodic (=Reload)
- One-shot

Quadrature Position/Revolution Counter (QPRC) (Max 2channels)

The Quadrature Position/Revolution Counter (QPRC) is used to measure the position of the position encoder. Moreover, it is possible to use as the up/down counter.

- The detection edge of the three external event input pins AIN, BIN and ZIN is configurable.
- 16-bit position counter
- 16-bit revolution counter
- Two 16-bit compare registers

HDMI-CEC/Remote Control Reception (Up to 2channels)

- HDMI-CEC transmission
 - Header block automatic transmission by judging Signal free
 - Generating status interrupt by detecting Arbitration lost
 - Generating START, EOM, ACK automatically to output CEC transmission by setting 1 byte data
 - Generating transmission status interrupt when transmitting 1 block (1 byte data and EOM/ACK)
- HDMI-CEC reception
 - Automatic ACK reply function available
 - Line error detection function available
- Remote control reception
 - 4 bytes reception buffer
 - Repeat code detection function available

Multi-function Timer

The Multi-function timer is composed of the following blocks.

- 16-bit free-run timer × 3 ch./unit
- Input capture × 4 ch./unit
- Output compare × 6 ch./unit
- A/D activation compare × 2 ch./unit
- Waveform generator × 3 ch./unit
- 16-bit PPG timer × 3 ch./unit

The following function can be used to achieve the motor control.

- PWM signal output function
- DC chopper waveform output function
- Dead time function
- Input capture function
- A/D convertor activate function
- DTIF (Motor emergency stop) interrupt function

Real-time clock (RTC)

The Real-time clock can count
Year/Month/Day/Hour/Minute/Second/A day of the week from 00 to 99.

- The interrupt function with specifying date and time (Year/Month/Day/Hour/Minute.) is available. This function is also available by specifying only Year, Month, Day, Hour or Minute.
- Timer interrupt function after set time or each set time.
- Capable of rewriting the time with continuing the time count.
- Leap year automatic count is available.

Watch Counter

The Watch counter is used for wake up from sleep and timer mode.

Interval timer: up to 64 s (Max) @ Sub Clock: 32.768 kHz

External Interrupt Controller Unit

- Up to 32 external interrupt input pins @ 176 pin Package
- Include one non-maskable interrupt (NMI) input pin

Watchdog Timer (2channels)

A watchdog timer can generate interrupts or a reset when a time-out value is reached.

This series consists of two different watchdogs, a "Hardware" watchdog and a "Software" watchdog.

The "Hardware" watchdog timer is clocked by the built-in low-speed CR oscillator. Therefore, the "Hardware" watchdog is active in any low-power consumption modes except RTC, STOP, Deep standby RTC, Deep standby STOP modes.

CRC (Cyclic Redundancy Check) Accelerator

The CRC accelerator calculates the CRC which has a heavy software processing load, and achieves a reduction of the integrity check processing load for reception data and storage.

CCITT CRC16 and IEEE-802.3 CRC32 are supported.

■ CCITT CRC16 Generator Polynomial: 0x1021

■ IEEE-802.3 CRC32 Generator Polynomial: 0x04C11DB7

Clock and Reset

[Clocks]

Selectable from five clock sources (2 external oscillators, 2 built-in CR oscillators, and Main PLL).

■ Main Clock: 4 MHz to 48 MHz

■ Sub Clock: 32.768 kHz

■ Built-in high-speed CR Clock: 4 MHz

■ Built-in low-speed CR Clock: 100 kHz

■ Main PLL Clock

[Resets]

■ Reset requests from INITX pin

■ Power-on reset

■ Software reset

■ Watchdog timers reset

■ Low-voltage detection reset

■ Clock Super Visor reset

Clock Super Visor (CSV)

Clocks generated by built-in CR oscillators are used to supervise abnormality of the external clocks.

■ If external clock failure (clock stop) is detected, reset is asserted.

■ If external frequency anomaly is detected, interrupt or reset is asserted.

Low-Voltage Detector (LVD)

This Series includes 2-stage monitoring of voltage on the VCC pins. When the voltage falls below the voltage that has been set, Low-Voltage Detector generates an interrupt or reset.

■ LVD1: error reporting via interrupt

■ LVD2: auto-reset operation

Low-Power Consumption Mode

Six low-power consumption modes supported.

■ SLEEP

■ TIMER

■ RTC

■ STOP

■ Deep standby RTC (selectable between keeping the value of RAM and not)

■ Deep standby STOP (selectable between keeping the value of RAM and not)

Debug

■ Serial Wire JTAG Debug Port (SWJ-DP)

■ Embedded Trace Macrocell (ETM)

Unique ID

Unique value of the device (41-bit) is set.

Power Supply

Wide range voltage:

VCC = 2.7 V to 5.5 V

USBVCC = 3.0 V to 3.6 V (when USB is used)

= 2.7 V to 5.5 V (when GPIO is used)

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1. Product Lineup

Memory size

Product name		CY9BF328SA	CY9BF329TA
On-chip Flash memory	Main area	1 Mbytes	1.5 Mbytes
	Work area	64 Kbytes	64 Kbytes
On-chip SRAM	SRAM0	80 Kbytes	96 Kbytes
	SRAM1	80 Kbytes	96 Kbytes
	Total	160 Kbytes	192 Kbytes

Function

Product name			CY9BF328SA	CY9BF329TA
Pin count			144	192
CPU			Cortex-M3	
Freq.			60 MHz	
Power supply voltage range			2.7 V to 5.5 V	
USB2.0 (Device/Host)			1 ch.	
DMAC			8 ch.	
External Bus Interface			Addr: 25-bit (Max) R/Wdata : 8-/16-bit (Max) CS: 8 (Max) SRAM , NOR Flash memory , NAND Flash memory	
Multi-function Serial Interface (UART/CSIO/LIN/I ² C)			16 ch. (Max) with 16steps×9-bit FIFO	
Base Timer (PWC/Reload timer/PWM/PPG)			16 ch. (Max)	
MF-Timer	A/D activation compare	2 ch.	1 unit	
	Input capture	4 ch.		
	Free-run timer	3 ch.		
	Output compare	6 ch.		
	Waveform generator	3 ch.		
	PPG	3 ch.		
QPRC			1 ch. (Max)	2 ch. (Max)
Dual Timer			1 unit	
HDMI-CEC/ Remote Control Reception			2 ch. (Max)	
Real-Time Clock			1 unit	
Watch Counter			1 unit	
CRC Accelerator			Yes	
Watchdog timer			1 ch. (SW) + 1 ch. (HW)	
External Interrupts			32 pins (Max) + NMI × 1	
I/O ports			122 pins (Max)	154 pins (Max)
12-bit A/D converter			24 ch. (2 units)	
10-bit D/A converter			2 ch. (Max)	
CSV (Clock Super Visor)			Yes	
LVD (Low-Voltage Detector)			2 ch.	
Built-in CR	High-speed		4 MHz	
	Low-speed		100 kHz	
Debug Function			SWJ-DP / ETM	
Unique ID			Yes	

Note:

- All signals of the peripheral function in each product cannot be allocated by limiting the pins of package. It is necessary to use the port relocate function of the I/O port according to your function use. See "Electrical Characteristics 12.4 AC Characteristics 12.4.3 Built-in CR Oscillation Characteristics" for accuracy of built-in CR.

2. Packages

Product name		CY9BF328SA	CY9BF329TA
Package			
LQFP:	LQS144 (0.5 mm pitch)	○	-
BGA:	LBE192 (0.8 mm pitch)	-	○

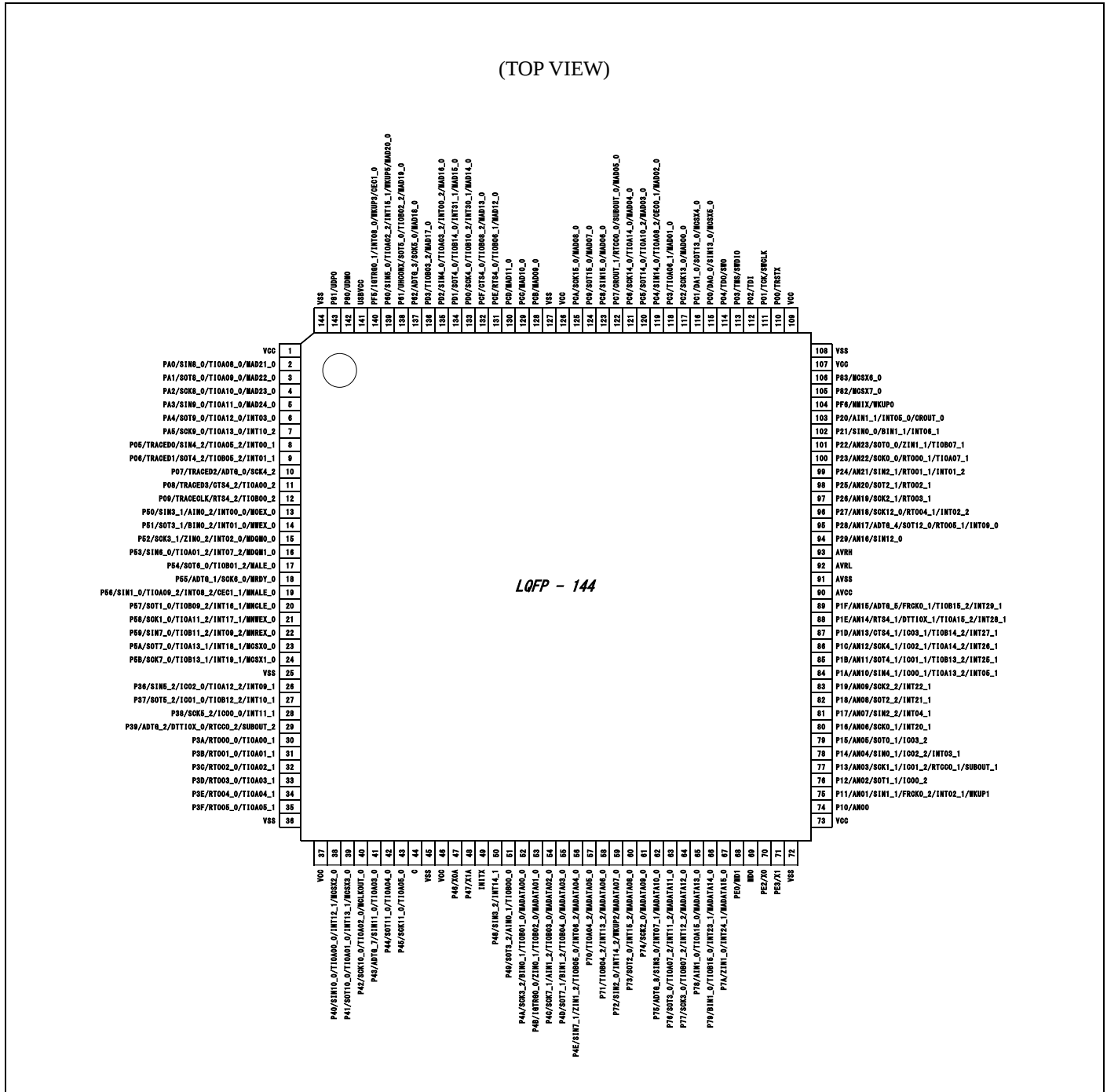
○: Supported

Note:

- See "Package Dimensions" for detailed information on each package.

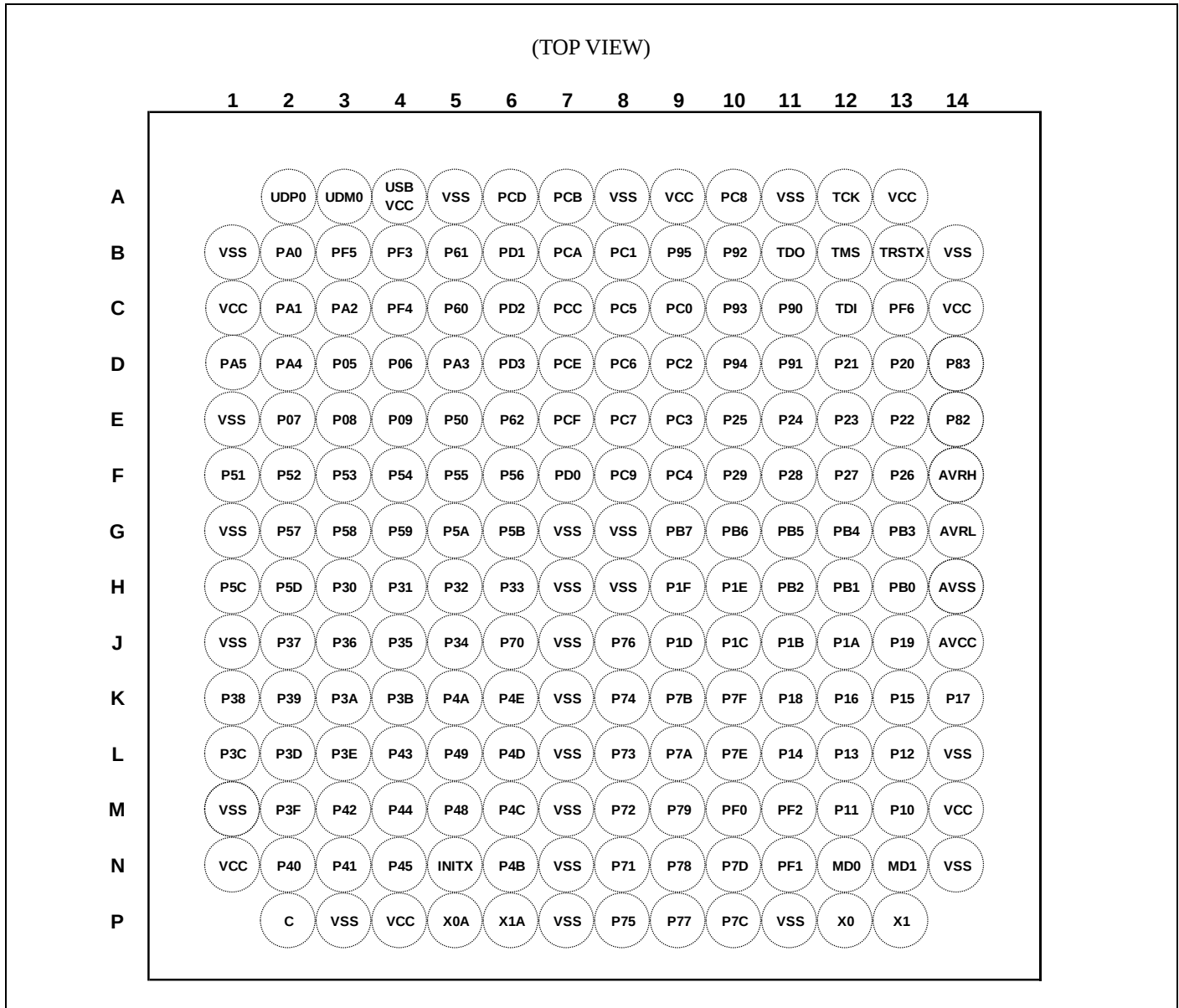
3. Pin Assignment

LQS144



Note:

- The number after the underscore ("_") in pin names such as XXX_1 and XXX_2 indicates the relocated port number. For these pins, there are multiple pins that provide the same function for the same channel. Use the extended port function register (EPFR) to select the pin.

LBE192

Note:

- The number after the underscore ("_") in pin names such as XXX_1 and XXX_2 indicates the relocated port number. For these pins, there are multiple pins that provide the same function for the same channel. Use the extended port function register (EPFR) to select the pin.

4. List of Pin Functions

List of pin numbers

The number after the underscore (" _") in pin names such as XXX_1 and XXX_2 indicates the relocated port number. For these pins, there are multiple pins that provide the same function for the same channel. Use the extended port function register (EPFR) to select the pin.

Pin No		Pin Name	I/O circuit type	Pin state type
LQFP-144	BGA-192			
1	C1	VCC	-	
2	B2	PA0	I*	J
		SIN8_0		
		TIOA08_0		
		MAD21_0		
3	C2	PA1	I*	J
		SOT8_0		
		TIOA09_0		
		MAD22_0		
4	C3	PA2	I*	J
		SCK8_0		
		TIOA10_0		
		MAD23_0		
5	D5	PA3	I*	J
		SIN9_0		
		TIOA11_0		
		MAD24_0		
6	D2	PA4	I*	K
		SOT9_0		
		TIOA12_0		
		INT03_0		
7	D1	PA5	I*	K
		SCK9_0		
		TIOA13_0		
		INT10_2		
8	D3	P05	E	Q
		TRACED0		
		SIN4_2		
		TIOA05_2		
		INT00_1		
9	D4	P06	E	Q
		TRACED1		
		SOT4_2		
		TIOB05_2		
		INT01_1		

Pin No		Pin Name	I/O circuit type	Pin state type
LQFP-144	BGA-192			
10	E2	P07	E	P
		TRACED2		
		ADTG_0		
		SCK4_2		
11	E3	P08	E	P
		TRACED3		
		CTS4_2		
		TIOA00_2		
12	E4	P09	E	P
		TRACECLK		
		RTS4_2		
		TIOB00_2		
13	E5	P50	E	K
		SIN3_1		
		AIN0_2		
		INT00_0		
		MOEX_0		
14	F1	P51	E	K
		SOT3_1		
		BIN0_2		
		INT01_0		
		MWEX_0		
15	F2	P52	E	K
		SCK3_1		
		ZIN0_2		
		INT02_0		
		MDQM0_0		

Pin No		Pin Name	I/O circuit type	Pin state type
LQFP-144	BGA-192			
16	F3	P53	E	K
		SIN6_0		
		TIOA01_2		
		INT07_2		
		MDQM1_0		
17	F4	P54	E	J
		SOT6_0		
		TIOB01_2		
		MALE_0		
18	F5	P55	E	J
		ADTG_1		
		SCK6_0		
		MRDY_0		
19	F6	P56	I*	S
		SIN1_0		
		TIOA09_2		
		INT08_2		
		CEC1_1		
		MNALE_0		
20	G2	P57	I*	K
		SOT1_0		
		TIOB09_2		
		INT16_1		
		MNCLE_0		
21	G3	P58	I*	K
		SCK1_0		
		TIOA11_2		
		INT17_1		
		MNWEX_0		
22	G4	P59	E	K
		SIN7_0		
		TIOB11_2		
		INT09_2		
		MNREX_0		

Pin No		Pin name	I/O circuit type	Pin state type
LQFP-144	BGA-192			
23	G5	P5A	E	K
		SOT7_0		
		TIOA13_1		
		INT18_1		
		MCSX0_0		
24	G6	P5B	E	K
		SCK7_0		
		TIOB13_1		
		INT19_1		
		MCSX1_0		
-	H1	P5C	E	K
		TIOA06_2		
		INT28_0		
-	H2	P5D	E	K
		TIOB06_2		
		INT29_0		
25	A5	VSS	-	
-	H3	P30	E	U
		AIN0_0		
		TIOB00_1		
		INT03_2		
		WKUP4		
-	H4	P31	E	K
		SCK6_1		
		BIN0_0		
		TIOB01_1		
		INT04_2		
-	H5	P32	E	K
		SOT6_1		
		ZIN0_0		
		TIOB02_1		
		INT05_2		
-	H6	P33	E	K
		ADTG_6		
		SIN6_1		
		TIOB03_1		
		INT04_0		

Pin No		Pin name	I/O circuit type	Pin state type
LQFP-144	BGA-192			
-	J5	P34	E	J
		FRCK0_0		
		TIOB04_1		
-	J4	P35	E	K
		IC03_0		
		TIOB05_1		
		INT08_1		
26	J3	P36	E	K
		SIN5_2		
		IC02_0		
		TIOA12_2		
		INT09_1		
27	J2	P37	E	K
		SOT5_2		
		IC01_0		
		TIOB12_2		
		INT10_1		
28	K1	P38	E	K
		SCK5_2		
		IC00_0		
		INT11_1		
29	K2	P39	E	J
		ADTG_2		
		DTTIOX_0		
		RTCCO_2		
		SUBOUT_2		
30	K3	P3A	F	J
		RTO00_0		
		TIOA00_1		
31	K4	P3B	F	J
		RTO01_0		
		TIOA01_1		
32	L1	P3C	F	J
		RTO02_0		
		TIOA02_1		

Pin No		Pin name	I/O circuit type	Pin state type
LQFP-144	BGA-192			
33	L2	P3D	F	J
		RTO03_0		
		TIOA03_1		
34	L3	P3E	F	J
		RTO04_0		
		TIOA04_1		
35	M2	P3F	F	J
		RTO05_0		
		TIOA05_1		
36	A8	VSS	-	
37	N1	VCC	-	
38	N2	P40	E	K
		SIN10_0		
		TIOA00_0		
		INT12_1		
		MCSX2_0		
39	N3	P41	E	K
		SOT10_0		
		TIOA01_0		
		INT13_1		
		MCSX3_0		
40	M3	P42	E	J
		SCK10_0		
		TIOA02_0		
		MCLKOUT_0		
41	L4	P43	I*	J
		ADTG_7		
		SIN11_0		
		TIOA03_0		
42	M4	P44	I*	J
		SOT11_0		
		TIOA04_0		
43	N4	P45	I*	J
		SCK11_0		
		TIOA05_0		
44	P2	C	-	
45	A11	VSS	-	
46	P4	VCC	-	
47	P5	P46	D	F
		X0A		
48	P6	P47	D	G
		X1A		
49	N5	INITX	B	C
50	M5	P48	E	K
		SIN3_2		
		INT14_1		

Pin No		Pin name	I/O circuit type	Pin state type
LQFP-144	BGA-192			
51	L5	P49	E	J
		SOT3_2		
		AIN0_1		
		TIOB00_0		
52	K5	P4A	E	J
		SCK3_2		
		BIN0_1		
		TIOB01_0		
		MADATA00_0		
53	N6	P4B	E	J
		IGTRG0_0		
		ZIN0_1		
		TIOB02_0		
		MADATA01_0		
54	M6	P4C	E	J
		SCK7_1		
		AIN1_2		
		TIOB03_0		
		MADATA02_0		
55	L6	P4D	E	J
		SOT7_1		
		BIN1_2		
		TIOB04_0		
		MADATA03_0		
56	K6	P4E	E	K
		SIN7_1		
		ZIN1_2		
		TIOB05_0		
		INT06_2		
		MADATA04_0		
57	J6	P70	E	J
		TIOA04_2		
		MADATA05_0		
58	N8	P71	E	K
		TIOB04_2		
		INT13_2		
		MADATA06_0		

Pin No		Pin name	I/O circuit type	Pin state type
LQFP-144	BGA-192			
59	M8	P72	E	U
		SIN2_0		
		INT14_2		
		WKUP2		
		MADATA07_0		
60	L8	P73	E	K
		SOT2_0		
		INT15_2		
		MADATA08_0		
61	K8	P74	E	J
		SCK2_0		
		MADATA09_0		
62	P8	P75	E	K
		ADTG_8		
		SIN3_0		
		INT07_1		
		MADATA10_0		
63	J8	P76	E	K
		SOT3_0		
		TIOA07_2		
		INT11_2		
		MADATA11_0		
64	P9	P77	E	K
		SCK3_0		
		TIOB07_2		
		INT12_2		
		MADATA12_0		
65	N9	P78	E	J
		AIN1_0		
		TIOA15_0		
		MADATA13_0		
66	M9	P79	E	K
		BIN1_0		
		TIOB15_0		
		INT23_1		
		MADATA14_0		
-	M1	VSS	-	
-	P3	VSS	-	

Pin No		Pin name	I/O circuit type	Pin state type
LQFP-144	BGA-192			
67	L9	P7A	E	K
		ZIN1_0		
		INT24_1		
		MADATA15_0		
-	K9	P7B	E	K
		TIOB07_0		
		INT10_0		
-	P10	P7C	E	K
		TIOA07_0		
		INT11_0		
-	N10	P7D	E	K
		TIOA14_1		
		INT12_0		
-	L10	P7E	E	K
		TIOB14_1		
		INT24_0		
-	K10	P7F	E	K
		TIOA15_1		
		INT25_0		
-	M10	PF0	I*	S
		SIN1_2		
		TIOB15_1		
		INT13_0		
		CEC0_0		
-	N11	PF1	I*	K
		SOT1_2		
		TIOA08_1		
		INT14_0		
-	M11	PF2	I*	K
		SCK1_2		
		TIOB08_1		
		INT15_0		
68	N13	PE0	C	E
		MD1		
69	N12	MD0	J	D
70	P12	PE2	A	A
		X0		
71	P13	PE3	A	B
		X1		
72	E1	VSS	-	
73	M14	VCC	-	
-	P7	VSS	-	
-	N7	VSS	-	

Pin No		Pin name	I/O circuit type	Pin state type
LQFP-144	BGA-192			
74	M13	P10	G	L
		AN00		
75	M12	P11	G	N
		AN01		
		SIN1_1		
		FRCK0_2		
		INT02_1		
		WKUP1		
76	L13	P12	G	L
		AN02		
		SOT1_1		
		IC00_2		
77	L12	P13	G	L
		AN03		
		SCK1_1		
		IC01_2		
		RTCCO_1		
		SUBOUT_1		
78	L11	P14	G	M
		AN04		
		SIN0_1		
		IC02_2		
		INT03_1		
79	K13	P15	G	L
		AN05		
		SOT0_1		
		IC03_2		
80	K12	P16	G	M
		AN06		
		SCK0_1		
		INT20_1		
81	K14	P17	G	M
		AN07		
		SIN2_2		
		INT04_1		
-	M7	VSS	-	
-	L7	VSS	-	
-	K7	VSS	-	

Pin No		Pin name	I/O circuit type	Pin state type
LQFP-144	BGA-192			
82	K11	P18	G	M
		AN08		
		SOT2_2		
		INT21_1		
83	J13	P19	G	M
		AN09		
		SCK2_2		
		INT22_1		
84	J12	P1A	G	M
		AN10		
		SIN4_1		
		IC00_1		
		TIOA13_2		
		INT05_1		
85	J11	P1B	G	M
		AN11		
		SOT4_1		
		IC01_1		
		TIOB13_2		
		INT25_1		
86	J10	P1C	G	M
		AN12		
		SCK4_1		
		IC02_1		
		TIOA14_2		
		INT26_1		
87	J9	P1D	G	M
		AN13		
		CTS4_1		
		IC03_1		
		TIOB14_2		
		INT27_1		
88	H10	P1E	G	M
		AN14		
		RTS4_1		
		DTTIOX_1		
		TIOA15_2		
		INT28_1		

Pin No		Pin name	I/O circuit type	Pin state type
LQFP-144	BGA-192			
89	H9	P1F	G	M
		AN15		
		ADTG_5		
		FRCK0_1		
		TIOB15_2		
		INT29_1		
-	H13	PB0	E	K
		SIN7_2		
		TIOA09_1		
		INT16_0		
-	H12	PB1	E	K
		SOT7_2		
		TIOB09_1		
		INT17_0		
-	H11	PB2	E	K
		SCK7_2		
		TIOA10_1		
		INT18_0		
-	G13	PB3	E	K
		TIOB10_1		
		INT19_0		
-	G12	PB4	E	K
		SIN0_2		
		TIOA11_1		
		INT20_0		
-	G11	PB5	E	K
		SOT0_2		
		TIOB11_1		
		INT21_0		
-	G10	PB6	E	K
		SCK0_2		
		TIOA12_1		
		INT22_0		
-	G9	PB7	E	K
		TIOB12_1		
		INT23_0		
90	J14	AVCC	-	
91	H14	AVSS	-	
-	J7	VSS	-	
-	P11	VSS	-	

Pin No		Pin name	I/O circuit type	Pin state type
LQFP-144	BGA-192			
92	G14	AVRL	-	
93	F14	AVRH	-	
94	F10	P29	G	L
		AN16		
		SIN12_0		
95	F11	P28	G	M
		AN17		
		ADTG_4		
		SOT12_0		
		RTO05_1		
		INT09_0		
96	F12	P27	G	M
		AN18		
		SCK12_0		
		RTO04_1		
		INT02_2		
97	F13	P26	G	L
		AN19		
		SCK2_1		
		RTO03_1		
98	E10	P25	G	L
		AN20		
		SOT2_1		
		RTO02_1		
99	E11	P24	G	M
		AN21		
		SIN2_1		
		RTO01_1		
		INT01_2		

Pin No		Pin name	I/O circuit type	Pin state type
LQFP-144	BGA-192			
100	E12	P23	G	L
		AN22		
		SCK0_0		
		RTO00_1		
		TIOA07_1		
101	E13	P22	G	L
		AN23		
		SOT0_0		
		ZIN1_1		
		TIOB07_1		
102	D12	P21	E	K
		SIN0_0		
		BIN1_1		
		INT06_1		
103	D13	P20	E	K
		AIN1_1		
		INT05_0		
		CROUT_0		
104	C13	PF6	I*	H
		NMIX		
		WKUP0		
105	E14	P82	E	J
		MCSX7_0		
106	D14	P83	E	J
		MCSX6_0		
107	C14	VCC	-	
108	G7	VSS	-	
109	A13	VCC	-	
110	B13	P00	E	I
		TRSTX		
111	A12	P01	E	I
		TCK		
		SWCLK		
112	C12	P02	E	I
		TDI		
113	B12	P03	E	I
		TMS		
		SWDIO		
114	B11	P04	E	I
		TDO		
		SWO		
-	C11	P90	E	K
		TIOB08_0		
		INT30_0		
-	N14	VSS	-	

Pin No		Pin name	I/O circuit type	Pin state type
LQFP-144	BGA-192			
-	D11	P91	E	K
		TIOB09_0		
		INT31_0		
-	B10	P92	E	J
		SIN5_1		
		TIOB10_0		
-	C10	P93	E	J
		SOT5_1		
		TIOB11_0		
-	D10	P94	E	K
		SCK5_1		
		TIOB12_0		
		INT26_0		
-	B9	P95	E	K
		TIOB13_0		
		INT27_0		
115	C9	PC0	H	O
		DA0_0		
		SIN13_0		
		MCSX5_0		
116	B8	PC1	H	O
		DA1_0		
		SOT13_0		
		MCSX4_0		
117	D9	PC2	E	J
		SCK13_0		
		MAD00_0		
118	E9	PC3	E	J
		TIOA06_1		
		MAD01_0		
119	F9	PC4	I*	R
		SIN14_0		
		TIOA08_2		
		CEC0_1		
		MAD02_0		
120	C8	PC5	I*	J
		SOT14_0		
		TIOA10_2		
		MAD03_0		
-	L14	VSS	-	

Pin No		Pin name	I/O circuit type	Pin state type
LQFP-144	BGA-192			
121	D8	PC6	I*	J
		SCK14_0		
		TIOA14_0		
		MAD04_0		
122	E8	PC7	E	J
		CROUT_1		
		RTCCO_0		
		SUBOUT_0		
		MAD05_0		
123	A10	PC8	E	J
		SIN15_0		
		MAD06_0		
124	F8	PC9	E	J
		SOT15_0		
		MAD07_0		
125	B7	PCA	E	J
		SCK15_0		
		MAD08_0		
126	A9	VCC	-	
127	G8	VSS	-	
128	A7	PCB	E	J
		MAD09_0		
129	C7	PCC	E	J
		MAD10_0		
130	A6	PCD	E	J
		MAD11_0		
131	D7	PCE	E	J
		RTS4_0		
		TIOB06_1		
		MAD12_0		
132	E7	PCF	E	J
		CTS4_0		
		TIOB08_2		
		MAD13_0		
133	F7	PD0	E	K
		SCK4_0		
		TIOB10_2		
		INT30_1		
		MAD14_0		
134	B6	PD1	E	K
		SOT4_0		
		TIOB14_0		
		INT31_1		
		MAD15_0		
-	B14	VSS	-	
-	H7	VSS	-	
-	B1	VSS	-	
-	G1	VSS	-	

Pin No		Pin name	I/O circuit type	Pin state type
LQFP-144	BGA-192			
135	C6	PD2	E	K
		SIN4_0		
		TIOA03_2		
		INT00_2		
		MAD16_0		
136	D6	PD3	E	J
		TIOB03_2		
		MAD17_0		
137	E6	P62	E	J
		ADTG_3		
		SCK5_0		
		MAD18_0		
138	B5	P61	E	J
		UHCONX		
		SOT5_0		
		TIOB02_2		
		MAD19_0		
139	C5	P60	E	U
		SIN5_0		
		TIOA02_2		
		INT15_1		
		WKUP5		
		MAD20_0		
-	B4	PF3	I*	K
		SIN6_2		
		TIOA06_0		
		INT06_0		
-	C4	PF4	I*	K
		SOT6_2		
		TIOB06_0		
		INT07_0		
140	B3	PF5	I*	T
		IGTRG0_1		
		INT08_0		
		WKUP3		
		CEC1_0		
-		SCK6_2		
141	A4	USBVCC	-	
142	A3	P80	K	V
		UDM0		
143	A2	P81	K	V
		UDP0		
144	H8	VSS	-	
-	J1	VSS	-	

List of pin functions

The number after the underscore (" _") in pin names such as XXX_1 and XXX_2 indicates the relocated port number. For these pins, there are multiple pins that provide the same function for the same channel. Use the extended port function register (EPFR) to select the pin.

Pin function	Pin name	Function description	Pin No	
			LQFP-144	BGA-192
ADC	ADTG_0	A/D converter external trigger input pin	10	E2
	ADTG_1		18	F5
	ADTG_2		29	K2
	ADTG_3		137	E6
	ADTG_4		95	F11
	ADTG_5		89	H9
	ADTG_6		-	H6
	ADTG_7		41	L4
	ADTG_8		62	P8
	AN00	A/D converter analog input pin. ANxx describes ADC ch.xx.	74	M13
	AN01		75	M12
	AN02		76	L13
	AN03		77	L12
	AN04		78	L11
	AN05		79	K13
	AN06		80	K12
	AN07		81	K14
	AN08		82	K11
	AN09		83	J13
	AN10		84	J12
	AN11		85	J11
	AN12		86	J10
	AN13		87	J9
	AN14		88	H10
	AN15		89	H9
	AN16		94	F10
	AN17		95	F11
	AN18		96	F12
	AN19		97	F13
	AN20		98	E10
	AN21		99	E11
	AN22		100	E12
	AN23		101	E13

Pin function	Pin name	Function description	Pin No	
			LQFP-144	BGA-192
Base Timer 0	TIOA00_0	Base timer ch.0 TIOA pin	38	N2
	TIOA00_1		30	K3
	TIOA00_2		11	E3
	TIOB00_0	Base timer ch.0 TIOB pin	51	L5
	TIOB00_1		-	H3
	TIOB00_2		12	E4
Base Timer 1	TIOA01_0	Base timer ch.1 TIOA pin	39	N3
	TIOA01_1		31	K4
	TIOA01_2		16	F3
	TIOB01_0	Base timer ch.1 TIOB pin	52	K5
	TIOB01_1		-	H4
	TIOB01_2		17	F4
Base Timer 2	TIOA02_0	Base timer ch.2 TIOA pin	40	M3
	TIOA02_1		32	L1
	TIOA02_2		139	C5
	TIOB02_0	Base timer ch.2 TIOB pin	53	N6
	TIOB02_1		-	H5
	TIOB02_2		138	B5
Base Timer 3	TIOA03_0	Base timer ch.3 TIOA pin	41	L4
	TIOA03_1		33	L2
	TIOA03_2		135	C6
	TIOB03_0	Base timer ch.3 TIOB pin	54	M6
	TIOB03_1		-	H6
	TIOB03_2		136	D6
Base Timer 4	TIOA04_0	Base timer ch.4 TIOA pin	42	M4
	TIOA04_1		34	L3
	TIOA04_2		57	J6
	TIOB04_0	Base timer ch.4 TIOB pin	55	L6
	TIOB04_1		-	J5
	TIOB04_2		58	N8
Base Timer 5	TIOA05_0	Base timer ch.5 TIOA pin	43	N4
	TIOA05_1		35	M2
	TIOA05_2		8	D3
	TIOB05_0	Base timer ch.5 TIOB pin	56	K6
	TIOB05_1		-	J4
	TIOB05_2		9	D4
Base Timer 6	TIOA06_0	Base timer ch.6 TIOA pin	-	B4
	TIOA06_1		118	E9
	TIOA06_2		-	H1
	TIOB06_0	Base timer ch.6 TIOB pin	-	C4
	TIOB06_1		131	D7
	TIOB06_2		-	H2

Pin function	Pin name	Function description	Pin No	
			LQFP-144	BGA-192
Base Timer 7	TIOA07_0	Base timer ch.7 TIOA pin	-	P10
	TIOA07_1		100	E12
	TIOA07_2		63	J8
	TIOB07_0	Base timer ch.7 TIOB pin	-	K9
	TIOB07_1		101	E13
	TIOB07_2		64	P9
Base Timer 8	TIOA08_0	Base timer ch.8 TIOA pin	2	B2
	TIOA08_1		-	N11
	TIOA08_2		119	F9
	TIOB08_0	Base timer ch.8 TIOB pin	-	C11
	TIOB08_1		-	M11
	TIOB08_2		132	E7
Base Timer 9	TIOA09_0	Base timer ch.9 TIOA pin	3	C2
	TIOA09_1		-	H13
	TIOA09_2		19	F6
	TIOB09_0	Base timer ch.9 TIOB pin	-	D11
	TIOB09_1		-	H12
	TIOB09_2		20	G2
Base Timer 10	TIOA10_0	Base timer ch.10 TIOA pin	4	C3
	TIOA10_1		-	H11
	TIOA10_2		120	C8
	TIOB10_0	Base timer ch.10 TIOB pin	-	B10
	TIOB10_1		-	G13
	TIOB10_2		133	F7
Base Timer 11	TIOA11_0	Base timer ch.11 TIOA pin	5	D5
	TIOA11_1		-	G12
	TIOA11_2		21	G3
	TIOB11_0	Base timer ch.11 TIOB pin	-	C10
	TIOB11_1		-	G11
	TIOB11_2		22	G4
Base Timer 12	TIOA12_0	Base timer ch.12 TIOA pin	6	D2
	TIOA12_1		-	G10
	TIOA12_2		26	J3
	TIOB12_0	Base timer ch.12 TIOB pin	-	D10
	TIOB12_1		-	G9
	TIOB12_2		27	J2
Base Timer 13	TIOA13_0	Base timer ch.13 TIOA pin	7	D1
	TIOA13_1		23	G5
	TIOA13_2		84	J12
	TIOB13_0	Base timer ch.13 TIOB pin	-	B9
	TIOB13_1		24	G6
	TIOB13_2		85	J11

Pin function	Pin name	Function description	Pin No	
			LQFP-144	BGA-192
Base Timer 14	TIOA14_0	Base timer ch.14 TIOA pin	121	D8
	TIOA14_1		-	N10
	TIOA14_2		86	J10
	TIOB14_0	Base timer ch.14 TIOB pin	134	B6
	TIOB14_1		-	L10
	TIOB14_2		87	J9
Base Timer 15	TIOA15_0	Base timer ch.15 TIOA pin	65	N9
	TIOA15_1		-	K10
	TIOA15_2		88	H10
	TIOB15_0	Base timer ch.15 TIOB pin	66	M9
	TIOB15_1		-	M10
	TIOB15_2		89	H9
Debugger	SWCLK	Serial wire debug interface clock input	111	A12
	SWDIO	Serial wire debug interface data input / output	113	B12
	SWO	Serial wire viewer output	114	B11
	TCK	JTAG test clock input	111	A12
	TDI	JTAG test data input	112	C12
	TDO	JTAG debug data output	114	B11
	TMS	JTAG test mode state input/output	113	B12
	TRACECLK	Trace CLK output of ETM	12	E4
	TRACED0	Trace data output of ETM	8	D3
	TRACED1		9	D4
	TRACED2		10	E2
	TRACED3		11	E3
	TRSTX	JTAG test reset Input	110	B13

Pin function	Pin name	Function description	Pin No	
			LQFP-144	BGA-192
External Bus	MAD00_0	External bus interface address bus	117	D9
	MAD01_0		118	E9
	MAD02_0		119	F9
	MAD03_0		120	C8
	MAD04_0		121	D8
	MAD05_0		122	E8
	MAD06_0		123	A10
	MAD07_0		124	F8
	MAD08_0		125	B7
	MAD09_0		128	A7
	MAD10_0		129	C7
	MAD11_0		130	A6
	MAD12_0		131	D7
	MAD13_0		132	E7
	MAD14_0		133	F7
	MAD15_0		134	B6
	MAD16_0		135	C6
	MAD17_0		136	D6
	MAD18_0		137	E6
	MAD19_0		138	B5
	MAD20_0		139	C5
	MAD21_0		2	B2
	MAD22_0		3	C2
	MAD23_0		4	C3
	MAD24_0		5	D5
	MCSX0_0	External bus interface chip select output pin	23	G5
	MCSX1_0		24	G6
	MCSX2_0		38	N2
	MCSX3_0		39	N3
	MCSX4_0		116	B8
	MCSX5_0		115	C9
	MCSX6_0		106	D14
	MCSX7_0		105	E14
	MDQM0_0	External bus interface byte mask signal output	15	F2
	MDQM1_0		16	F3
	MOEX_0	External bus interface read enable signal for SRAM	13	E5
	MWEX_0	External bus interface write enable signal for SRAM	14	F1

Pin function	Pin name	Function description	Pin No	
			LQFP-144	BGA-192
External Bus	MNALE_0	External bus interface ALE signal to control NAND Flash output pin	19	F6
	MNCLE_0	External bus interface CLE signal to control NAND Flash output pin	20	G2
	MNREX_0	External bus interface read enable signal to control NAND Flash	22	G4
	MNWEX_0	External bus interface write enable signal to control NAND Flash	21	G3
	MADATA00_0	External bus interface data bus (Address / data multiplex bus)	52	K5
	MADATA01_0		53	N6
	MADATA02_0		54	M6
	MADATA03_0		55	L6
	MADATA04_0		56	K6
	MADATA05_0		57	J6
	MADATA06_0		58	N8
	MADATA07_0		59	M8
	MADATA08_0		60	L8
	MADATA09_0		61	K8
	MADATA10_0		62	P8
	MADATA11_0		63	J8
	MADATA12_0		64	P9
	MADATA13_0		65	N9
	MADATA14_0		66	M9
	MADATA15_0		67	L9
	MALE_0	External bus interface Address Latch enable output signal for multiplex	17	F4
	MRDY_0	External bus interface external RDY input signal	18	F5
	MCLKOUT_0	External bus interface external clock output	40	M3

Pin function	Pin name	Function description	Pin No	
			LQFP-144	BGA-192
External Interrupt	INT00_0	External interrupt request 00 input pin	13	E5
	INT00_1		8	D3
	INT00_2		135	C6
	INT01_0	External interrupt request 01 input pin	14	F1
	INT01_1		9	D4
	INT01_2		99	E11
	INT02_0	External interrupt request 02 input pin	15	F2
	INT02_1		75	M12
	INT02_2		96	F12
	INT03_0	External interrupt request 03 input pin	6	D2
	INT03_1		78	L11
	INT03_2		-	H3
	INT04_0	External interrupt request 04 input pin	-	H6
	INT04_1		81	K14
	INT04_2		-	H4
	INT05_0	External interrupt request 05 input pin	103	D13
	INT05_1		84	J12
	INT05_2		-	H5
	INT06_0	External interrupt request 06 input pin	-	B4
	INT06_1		102	D12
	INT06_2		56	K6
	INT07_0	External interrupt request 07 input pin	-	C4
	INT07_1		62	P8
	INT07_2		16	F3
	INT08_0	External interrupt request 08 input pin	140	B3
	INT08_1		-	J4
	INT08_2		19	F6
	INT09_0	External interrupt request 09 input pin	95	F11
	INT09_1		26	J3
	INT09_2		22	G4
	INT10_0	External interrupt request 10 input pin	-	K9
	INT10_1		27	J2
	INT10_2		7	D1
	INT11_0	External interrupt request 11 input pin	-	P10
	INT11_1		28	K1
	INT11_2		63	J8
	INT12_0	External interrupt request 12 input pin	-	N10
	INT12_1		38	N2
	INT12_2		64	P9
	INT13_0	External interrupt request 13 input pin	-	M10
	INT13_1		39	N3
	INT13_2		58	N8
	INT14_0	External interrupt request 14 input pin	-	N11
	INT14_1		50	M5
	INT14_2		59	M8

Pin function	Pin name	Function description	Pin No	
			LQFP-144	BGA-192
External Interrupt	INT15_0	External interrupt request 15 input pin	-	M11
	INT15_1		139	C5
	INT15_2		60	L8
	INT16_0	External interrupt request 16 input pin	-	H13
	INT16_1		20	G2
	INT17_0		-	H12
	INT17_1	External interrupt request 17 input pin	21	G3
	INT18_0		-	H11
	INT18_1	External interrupt request 18 input pin	23	G5
	INT19_0		-	G13
	INT19_1	External interrupt request 19 input pin	24	G6
	INT20_0		-	G12
	INT20_1	External interrupt request 20 input pin	80	K12
	INT21_0		-	G11
	INT21_1	External interrupt request 21 input pin	82	K11
	INT22_0		-	G10
	INT22_1	External interrupt request 22 input pin	83	J13
	INT23_0		-	G9
	INT23_1	External interrupt request 23 input pin	66	M9
	INT24_0		-	L10
	INT24_1	External interrupt request 24 input pin	67	L9
	INT25_0		-	K10
	INT25_1	External interrupt request 25 input pin	85	J11
	INT26_0		-	D10
	INT26_1	External interrupt request 26 input pin	86	J10
	INT27_0		-	B9
	INT27_1	External interrupt request 27 input pin	87	J9
	INT28_0		-	H1
	INT28_1	External interrupt request 28 input pin	88	H10
	INT29_0		-	H2
	INT29_1	External interrupt request 29 input pin	89	H9
	INT30_0		-	C11
	INT30_1	External interrupt request 30 input pin	133	F7
	INT31_0		-	D11
	INT31_1	External interrupt request 31 input pin	134	B6
	NMIX		104	C13
		Non-Maskable Interrupt input		

Pin function	Pin name	Function description	Pin No	
			LQFP-144	BGA-192
GPIO	P00	General-purpose I/O port 0	110	B13
	P01		111	A12
	P02		112	C12
	P03		113	B12
	P04		114	B11
	P05		8	D3
	P06		9	D4
	P07		10	E2
	P08		11	E3
	P09		12	E4
	P10	General-purpose I/O port 1	74	M13
	P11		75	M12
	P12		76	L13
	P13		77	L12
	P14		78	L11
	P15		79	K13
	P16		80	K12
	P17		81	K14
	P18		82	K11
	P19		83	J13
	P1A		84	J12
	P1B		85	J11
	P1C		86	J10
	P1D		87	J9
	P1E		88	H10
	P1F		89	H9
	P20	General-purpose I/O port 2	103	D13
	P21		102	D12
	P22		101	E13
	P23		100	E12
	P24		99	E11
	P25		98	E10
	P26		97	F13
	P27		96	F12
	P28		95	F11
	P29		94	F10

Pin function	Pin name	Function description	Pin No	
			LQFP-144	BGA-192
GPIO	P30	General-purpose I/O port 3	-	H3
	P31		-	H4
	P32		-	H5
	P33		-	H6
	P34		-	J5
	P35		-	J4
	P36		26	J3
	P37		27	J2
	P38		28	K1
	P39		29	K2
	P3A		30	K3
	P3B		31	K4
	P3C		32	L1
	P3D		33	L2
	P3E		34	L3
	P3F		35	M2
	P40	General-purpose I/O port 4	38	N2
	P41		39	N3
	P42		40	M3
	P43		41	L4
	P44		42	M4
	P45		43	N4
	P46		47	P5
	P47		48	P6
	P48		50	M5
	P49		51	L5
	P4A		52	K5
	P4B		53	N6
	P4C		54	M6
	P4D		55	L6
	P4E		56	K6
	P50	General-purpose I/O port 5	13	E5
	P51		14	F1
	P52		15	F2
	P53		16	F3
	P54		17	F4
	P55		18	F5
	P56		19	F6
	P57		20	G2
	P58		21	G3
	P59		22	G4
	P5A		23	G5
	P5B		24	G6
	P5C		-	H1
	P5D		-	H2

Pin function	Pin name	Function description	Pin No	
			LQFP-144	BGA-192
GPIO	P60	General-purpose I/O port 6	139	C5
	P61		138	B5
	P62		137	E6
	P70	General-purpose I/O port 7	57	J6
	P71		58	N8
	P72		59	M8
	P73		60	L8
	P74		61	K8
	P75		62	P8
	P76		63	J8
	P77		64	P9
	P78		65	N9
	P79		66	M9
	P7A		67	L9
	P7B		-	K9
	P7C		-	P10
	P7D		-	N10
	P7E		-	L10
	P7F		-	K10
	P80	General-purpose I/O port 8	142	A3
	P81		143	A2
	P82		105	E14
	P83		106	D14
	P90	General-purpose I/O port 9	-	C11
	P91		-	D11
	P92		-	B10
	P93		-	C10
	P94		-	D10
	P95	General-purpose I/O port A	-	B9
	PA0		2	B2
	PA1		3	C2
	PA2		4	C3
	PA3		5	D5
	PA4		6	D2
	PA5		7	D1
	PB0	General-purpose I/O port B	-	H13
	PB1		-	H12
	PB2		-	H11
	PB3		-	G13
	PB4		-	G12
	PB5		-	G11
	PB6		-	G10
	PB7		-	G9

Pin function	Pin name	Function description	Pin No	
			LQFP-144	BGA-192
GPIO	PC0	General-purpose I/O port C	115	C9
	PC1		116	B8
	PC2		117	D9
	PC3		118	E9
	PC4		119	F9
	PC5		120	C8
	PC6		121	D8
	PC7		122	E8
	PC8		123	A10
	PC9		124	F8
	PCA		125	B7
	PCB		128	A7
	PCC		129	C7
	PCD		130	A6
	PCE		131	D7
	PCF		132	E7
	PD0	General-purpose I/O port D	133	F7
	PD1		134	B6
	PD2		135	C6
	PD3		136	D6
	PE0	General-purpose I/O port E	68	N13
	PE2		70	P12
	PE3		71	P13
	PF0	General-purpose I/O port F*	-	M10
	PF1		-	N11
	PF2		-	M11
	PF3		-	B4
	PF4		-	C4
	PF5		140	B3
	PF6		104	C13

Pin function	Pin name	Function description	Pin No	
			LQFP-144	BGA-192
Multi Function Serial 0	SIN0_0	Multifunction serial interface ch.0 input pin	102	D12
	SIN0_1		78	L11
	SIN0_2		-	G12
	SOT0_0 (SDA0_0)	Multifunction serial interface ch.0 output pin. This pin operates as SOT0 when it is used in a UART/CSIO/LIN (operation modes 0 to 3) and as SDA0 when it is used in an I ² C (operation mode 4).	101	E13
	SOT0_1 (SDA0_1)		79	K13
	SOT0_2 (SDA0_2)		-	G11
	SCK0_0 (SCL0_0)	Multifunction serial interface ch.0 clock I/O pin. This pin operates as SCK0 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL0 when it is used in an I ² C (operation mode 4).	100	E12
	SCK0_1 (SCL0_1)		80	K12
	SCK0_2 (SCL0_2)		-	G10
Multi Function Serial 1	SIN1_0	Multifunction serial interface ch.1 input pin	19	F6
	SIN1_1		75	M12
	SIN1_2		-	M10
	SOT1_0 (SDA1_0)	Multifunction serial interface ch.1 output pin. This pin operates as SOT1 when it is used in a UART/CSIO/LIN (operation modes 0 to 3) and as SDA1 when it is used in an I ² C (operation mode 4).	20	G2
	SOT1_1 (SDA1_1)		76	L13
	SOT1_2 (SDA1_2)		-	N11
	SCK1_0 (SCL1_0)	Multifunction serial interface ch.1 clock I/O pin. This pin operates as SCK1 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL1 when it is used in an I ² C (operation mode 4).	21	G3
	SCK1_1 (SCL1_1)		77	L12
	SCK1_2 (SCL1_2)		-	M11

Pin function	Pin name	Function description	Pin No	
			LQFP-144	BGA-192
Multi Function Serial 2	SIN2_0	Multifunction serial interface ch.2 input pin	59	M8
	SIN2_1		99	E11
	SIN2_2		81	K14
	SOT2_0 (SDA2_0)	Multifunction serial interface ch.2 output pin. This pin operates as SOT2 when it is used in a UART/CSIO/LIN (operation modes 0 to 3) and as SDA2 when it is used in an I ² C (operation mode 4).	60	L8
	SOT2_1 (SDA2_1)		98	E10
	SOT2_2 (SDA2_2)		82	K11
	SCK2_0 (SCL2_0)	Multifunction serial interface ch.2 clock I/O pin. This pin operates as SCK2 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL2 when it is used in an I ² C (operation mode 4).	61	K8
	SCK2_1 (SCL2_1)		97	F13
	SCK2_2 (SCL2_2)		83	J13
Multi Function Serial 3	SIN3_0	Multifunction serial interface ch.3 input pin	62	P8
	SIN3_1		13	E5
	SIN3_2		50	M5
	SOT3_0 (SDA3_0)	Multifunction serial interface ch.3 output pin. This pin operates as SOT3 when it is used in a UART/CSIO/LIN (operation modes 0 to 3) and as SDA3 when it is used in an I ² C (operation mode 4).	63	J8
	SOT3_1 (SDA3_1)		14	F1
	SOT3_2 (SDA3_2)		51	L5
	SCK3_0 (SCL3_0)	Multifunction serial interface ch.3 clock I/O pin. This pin operates as SCK3 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL3 when it is used in an I ² C (operation mode 4).	64	P9
	SCK3_1 (SCL3_1)		15	F2
	SCK3_2 (SCL3_2)		52	K5

Pin function	Pin name	Function description	Pin No	
			LQFP-144	BGA-192
Multi Function Serial 4	SIN4_0	Multifunction serial interface ch.4 input pin	135	C6
	SIN4_1		84	J12
	SIN4_2		8	D3
	SOT4_0 (SDA4_0)	Multifunction serial interface ch.4 output pin. This pin operates as SOT4 when it is used in a UART/CSIO/LIN (operation modes 0 to 3) and as SDA4 when it is used in an I ² C (operation mode 4).	134	B6
	SOT4_1 (SDA4_1)		85	J11
	SOT4_2 (SDA4_2)		9	D4
	SCK4_0 (SCL4_0)	Multifunction serial interface ch.4 clock I/O pin. This pin operates as SCK4 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL4 when it is used in an I ² C (operation mode 4).	133	F7
	SCK4_1 (SCL4_1)		86	J10
	SCK4_2 (SCL4_2)		10	E2
	RTS4_0	Multifunction serial interface ch.4 RTS output pin	131	D7
	RTS4_1		88	H10
	RTS4_2		12	E4
	CTS4_0	Multifunction serial interface ch.4 CTS input pin	132	E7
	CTS4_1		87	J9
	CTS4_2		11	E3
Multi Function Serial 5	SIN5_0	Multifunction serial interface ch.5 input pin	139	C5
	SIN5_1		-	B10
	SIN5_2		26	J3
	SOT5_0 (SDA5_0)	Multifunction serial interface ch.5 output pin. This pin operates as SOT5 when it is used in a UART/CSIO/LIN (operation modes 0 to 3) and as SDA5 when it is used in an I ² C (operation mode 4).	138	B5
	SOT5_1 (SDA5_1)		-	C10
	SOT5_2 (SDA5_2)		27	J2
	SCK5_0 (SCL5_0)	Multifunction serial interface ch.5 clock I/O pin. This pin operates as SCK5 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL5 when it is used in an I ² C (operation mode 4).	137	E6
	SCK5_1 (SCL5_1)		-	D10
	SCK5_2 (SCL5_2)		28	K1

Pin function	Pin name	Function description	Pin No	
			LQFP-144	BGA-192
Multi Function Serial 6	SIN6_0	Multifunction serial interface ch.6 input pin	16	F3
	SIN6_1		-	H6
	SIN6_2		-	B4
	SOT6_0 (SDA6_0)	Multifunction serial interface ch.6 output pin. This pin operates as SOT6 when it is used in a UART/CSIO/LIN (operation modes 0 to 3) and as SDA6 when it is used in an I ² C (operation mode 4).	17	F4
	SOT6_1 (SDA6_1)		-	H5
	SOT6_2 (SDA6_2)		-	C4
	SCK6_0 (SCL6_0)	Multifunction serial interface ch.6 clock I/O pin. This pin operates as SCK6 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL6 when it is used in an I ² C (operation mode 4).	18	F5
	SCK6_1 (SCL6_1)		-	H4
	SCK6_2 (SCL6_2)		-	B3
Multi Function Serial 7	SIN7_0	Multifunction serial interface ch.7 input pin	22	G4
	SIN7_1		56	K6
	SIN7_2		-	H13
	SOT7_0 (SDA7_0)	Multifunction serial interface ch.7 output pin. This pin operates as SOT7 when it is used in a UART/CSIO/LIN (operation modes 0 to 3) and as SDA7 when it is used in an I ² C (operation mode 4).	23	G5
	SOT7_1 (SDA7_1)		55	L6
	SOT7_2 (SDA7_2)		-	H12
	SCK7_0 (SCL7_0)	Multifunction serial interface ch.7 clock I/O pin. This pin operates as SCK7 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL7 when it is used in an I ² C (operation mode 4).	24	G6
	SCK7_1 (SCL7_1)		54	M6
	SCK7_2 (SCL7_2)		-	H11

Pin function	Pin name	Function description	Pin No	
			LQFP-144	BGA-192
Multi Function Serial 8	SIN8_0	Multifunction serial interface ch.8 input pin	2	B2
	SOT8_0 (SDA8_0)	Multifunction serial interface ch.6 output pin. This pin operates as SOT8 when it is used in a UART/CSIO/LIN (operation modes 0 to 3) and as SDA8 when it is used in an I ² C (operation mode 4).	3	C2
	SCK8_0 (SCL8_0)	Multifunction serial interface ch.7 clock I/O pin. This pin operates as SCK8 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL8 when it is used in an I ² C (operation mode 4).	4	C3
Multi Function Serial 9	SIN9_0	Multifunction serial interface ch.9 input pin	5	D5
	SOT9_0 (SDA9_0)	Multifunction serial interface ch.9 output pin. This pin operates as SOT9 when it is used in a UART/CSIO/LIN (operation modes 0 to 3) and as SDA9 when it is used in an I ² C (operation mode 4).	6	D2
	SCK9_0 (SCL9_0)	Multifunction serial interface ch.9 clock I/O pin. This pin operates as SCK9 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL9 when it is used in an I ² C (operation mode 4).	7	D1

Pin function	Pin name	Function description	Pin No	
			LQFP-144	BGA-192
Multi Function Serial 10	SIN10_0	Multifunction serial interface ch.10 input pin	38	N2
	SOT10_0 (SDA10_0)	Multifunction serial interface ch.10 output pin. This pin operates as SOT10 when it is used in a UART/CSIO/LIN (operation modes 0 to 3) and as SDA10 when it is used in an I ² C (operation mode 4).	39	N3
	SCK10_0 (SCL10_0)	Multifunction serial interface ch.10 clock I/O pin. This pin operates as SCK10 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL10 when it is used in an I ² C (operation mode 4).	40	M3
Multi Function Serial 11	SIN11_0	Multifunction serial interface ch.11 input pin	41	L4
	SOT11_0 (SDA11_0)	Multifunction serial interface ch.11 output pin. This pin operates as SOT11 when it is used in a UART/CSIO/LIN (operation modes 0 to 3) and as SDA11 when it is used in an I ² C (operation mode 4).	42	M4
	SCK11_0 (SCL11_0)	Multifunction serial interface ch.11 clock I/O pin. This pin operates as SCK11 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL11 when it is used in an I ² C (operation mode 4).	43	N4

Pin function	Pin name	Function description	Pin No	
			LQFP-144	BGA-192
Multi Function Serial 12	SIN12_0	Multifunction serial interface ch.12 input pin	94	F10
	SOT12_0 (SDA12_0)	Multifunction serial interface ch.12 output pin. This pin operates as SOT12 when it is used in a UART/CSIO/LIN (operation modes 0 to 3) and as SDA12 when it is used in an I ² C (operation mode 4).	95	F11
	SCK12_0 (SCL12_0)	Multifunction serial interface ch.12 clock I/O pin. This pin operates as SCK12 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL12 when it is used in an I ² C (operation mode 4).	96	F12
Multi Function Serial 13	SIN13_0	Multifunction serial interface ch.13 input pin	115	C9
	SOT13_0 (SDA13_0)	Multifunction serial interface ch.13 output pin. This pin operates as SOT13 when it is used in a UART/CSIO/LIN (operation modes 0 to 3) and as SDA13 when it is used in an I ² C (operation mode 4).	116	B8
	SCK13_0 (SCL13_0)	Multifunction serial interface ch.13 clock I/O pin. This pin operates as SCK13 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL13 when it is used in an I ² C (operation mode 4).	117	D9

Pin function	Pin name	Function description	Pin No	
			LQFP-144	BGA-192
Multi Function Serial 14	SIN14_0	Multifunction serial interface ch.14 input pin	119	F9
	SOT14_0 (SDA14_0)	Multifunction serial interface ch.14 output pin. This pin operates as SOT14 when it is used in a UART/CSIO/LIN (operation modes 0 to 3) and as SDA14 when it is used in an I ² C (operation mode 4).	120	C8
	SCK14_0 (SCL14_0)	Multifunction serial interface ch.14 clock I/O pin. This pin operates as SCK14 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL14 when it is used in an I ² C (operation mode 4).	121	D8
Multi Function Serial 15	SIN15_0	Multifunction serial interface ch.15 input pin	123	A10
	SOT15_0 (SDA15_0)	Multifunction serial interface ch.15 output pin. This pin operates as SOT15 when it is used in a UART/CSIO/LIN (operation modes 0 to 3) and as SDA15 when it is used in an I ² C (operation mode 4).	124	F8
	SCK15_0 (SCL15_0)	Multifunction serial interface ch.15 clock I/O pin. This pin operates as SCK15 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL15 when it is used in an I ² C (operation mode 4).	125	B7

Pin function	Pin name	Function description	Pin No	
			LQFP-144	BGA-192
Multi Function Timer 0	DTTIOX_0	Input signal controlling wave form generator outputs RTO00 to RTO05 of multi-function timer 0.	29	K2
	DTTIOX_1		88	H10
	FRCK0_0	16-bit free-run timer ch.0 external clock input pin	-	J5
	FRCK0_1		89	H9
	FRCK0_2		75	M12
	IC00_0	16-bit input capture ch.0 input pin of multi-function timer 0. ICxx describes channel number.	28	K1
	IC00_1		84	J12
	IC00_2		76	L13
	IC01_0		27	J2
	IC01_1		85	J11
	IC01_2		77	L12
	IC02_0		26	J3
	IC02_1		86	J10
	IC02_2		78	L11
	IC03_0		-	J4
	IC03_1		87	J9
	IC03_2		79	K13
	RTO00_0 (PPG00_0)	Wave form generator output of multi-function timer 0.	30	K3
	RTO00_1 (PPG00_1)	This pin operates as PPG00 when it is used in PPG0 output modes.	100	E12
	RTO01_0 (PPG00_0)	Wave form generator output of multi-function timer 0.	31	K4
	RTO01_1 (PPG00_1)	This pin operates as PPG00 when it is used in PPG0 output modes.	99	E11
	RTO02_0 (PPG02_0)	Wave form generator output of multi-function timer 0.	32	L1
	RTO02_1 (PPG02_1)	This pin operates as PPG02 when it is used in PPG0 output modes.	98	E10
	RTO03_0 (PPG02_0)	Wave form generator output of multi-function timer 0.	33	L2
	RTO03_1 (PPG02_1)	This pin operates as PPG02 when it is used in PPG0 output modes.	97	F13
	RTO04_0 (PPG04_0)	Wave form generator output of multi-function timer 0.	34	L3
	RTO04_1 (PPG04_1)	This pin operates as PPG04 when it is used in PPG0 output modes.	96	F12
	RTO05_0 (PPG04_0)	Wave form generator output of multi-function timer 0.	35	M2
	RTO05_1 (PPG04_1)	This pin operates as PPG04 when it is used in PPG0 output modes.	95	F11
	IGTRG0_0	PPG IGBT mode external trigger input pin	53	N6
	IGTRG0_1		140	B3

Pin function	Pin name	Function description	Pin No	
			LQFP-144	BGA-192
Quadrature Position/ Revolution Counter 0	AIN0_0	QPRC ch.0 AIN input pin	-	H3
	AIN0_1		51	L5
	AIN0_2		13	E5
	BIN0_0	QPRC ch.0 BIN input pin	-	H4
	BIN0_1		52	K5
	BIN0_2		14	F1
	ZIN0_0	QPRC ch.0 ZIN input pin	-	H5
	ZIN0_1		53	N6
	ZIN0_2		15	F2
Quadrature Position/ Revolution Counter 1	AIN1_0	QPRC ch.1 AIN input pin	65	N9
	AIN1_1		103	D13
	AIN1_2		54	M6
	BIN1_0	QPRC ch.1 BIN input pin	66	M9
	BIN1_1		102	D12
	BIN1_2		55	L6
	ZIN1_0	QPRC ch.1 ZIN input pin	67	L9
	ZIN1_1		101	E13
	ZIN1_2		56	K6
USB	UDM0	USB ch.0 Device/Host D – pin	142	A3
	UDP0	USB ch.0 Device/Host D + pin	143	A2
	UHCONX	USB ch.0 USB external pull-up control pin	138	B5
Real-time clock	RTCCO_0	0.5 seconds pulse output pin of Real-time clock	122	E8
	RTCCO_1		77	L12
	RTCCO_2		29	K2
	SUBOUT_0	Sub clock output pin	122	E8
	SUBOUT_1		77	L12
	SUBOUT_2		29	K2

Pin function	Pin name	Function description	Pin No	
			LQFP-144	BGA-192
Reset	INITX	External Reset Input. A reset is valid when INITX="L".	49	N5
Mode	MD0	Mode 0 Pin. During normal operation, MD0="L" must be input. During serial programming to Flash memory, MD0="H" must be input.	69	N12
	MD1	Mode 1 Pin. During serial programming to Flash memory, MD1="L" must be input.	68	N13
Power	VCC	Power supply Pin	1	C1
			37	N1
			46	P4
			73	M14
			107	C14
			109	A13
			126	A9
	USBVCC	3.3V Power supply port for USB I/O	141	A4
Low-Power Consumption Mode	WKUP0	Deep standby mode return signal input pin 0	104	C13
	WKUP1	Deep standby mode return signal input pin 1	75	M12
	WKUP2	Deep standby mode return signal input pin 2	59	M8
	WKUP3	Deep standby mode return signal input pin 3	140	B3
	WKUP4	Deep standby mode return signal input pin 4	-	H3
	WKUP5	Deep standby mode return signal input pin 5	139	C5
HDMI-CEC/Remote Control Reception	CEC0_0	HDMI-CEC/Remote Control Reception ch.0 input/output pin	-	M10
	CEC0_1		119	F9
	CEC1_0	HDMI-CEC/Remote Control Reception ch.1 input/output pin	140	B3
	CEC1_1		19	F6
DAC	DA0_0	D/A converter ch.0 analog output pin	115	C9
	DA1_0	D/A converter ch.1 analog output pin	116	B8

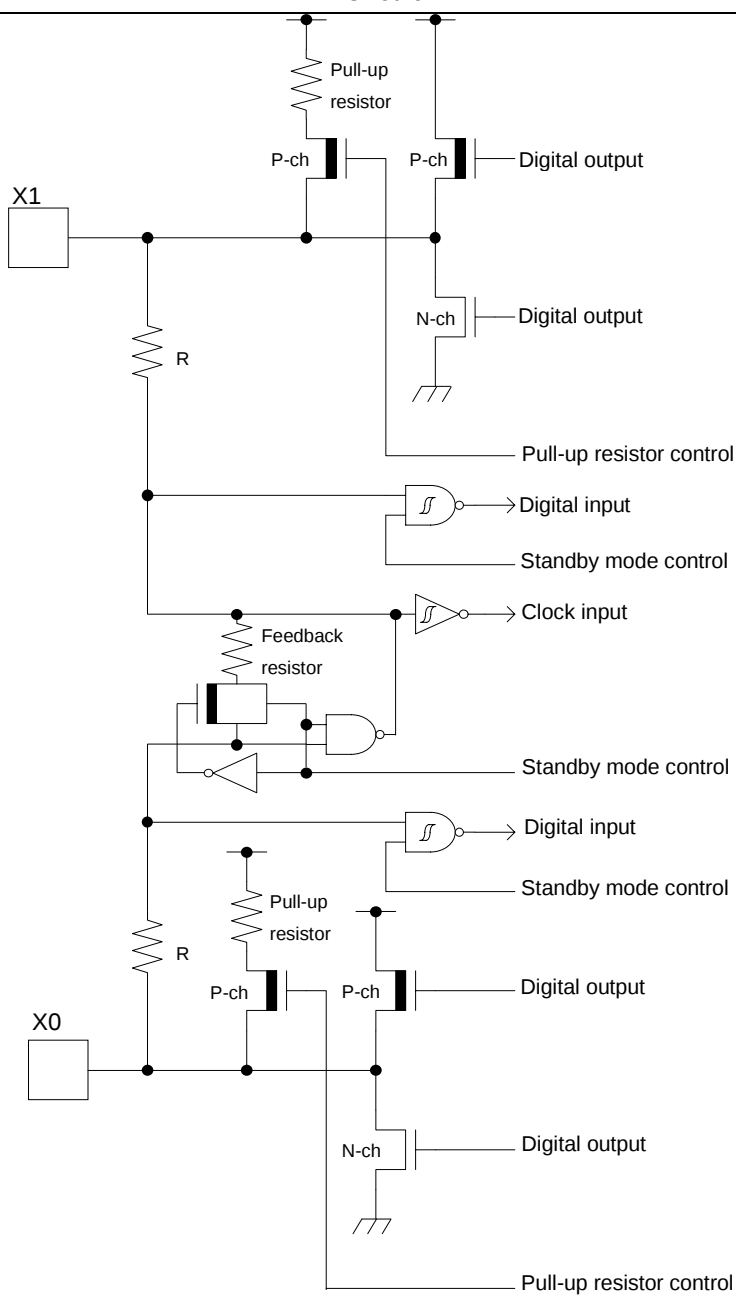
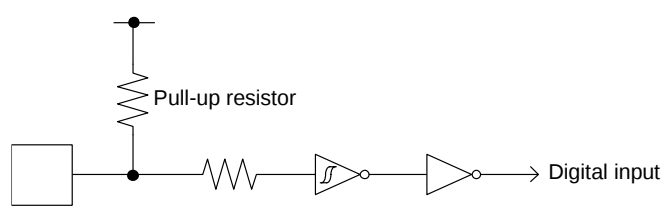
Pin function	Pin name	Function description	Pin No	
			LQFP-144	BGA-192
GND	VSS	GND Pin	25	A5
			36	A8
			45	A11
			72	E1
			108	G7
			127	G8
			144	H8
			-	M1
			-	P3
			-	P7
			-	N7
			-	M7
			-	L7
			-	K7
			-	J7
			-	P11
			-	N14
			-	L14
			-	B14
			-	H7
			-	B1
			-	G1
			-	J1
Clock	X0	Main clock (oscillation) input pin	70	P12
	X0A	Sub clock (oscillation) input pin	47	P5
	X1	Main clock (oscillation) I/O pin	71	P13
	X1A	Sub clock (oscillation) I/O pin	48	P6
	CROUT_0	Built-in high-speed CR-osc clock output port	103	D13
	CROUT_1		122	E8
Analog Power	AVCC	A/D converter, D/A converter analog power pin	90	J14
	AVRH	A/D converter analog reference voltage input pin	93	F14
Analog GND	AVSS	A/D converter, D/A converter GND pin	91	H14
	AVRL	A/D converter analog reference voltage input pin	92	G14
C pin	C	Power supply stabilization capacity pin	44	P2

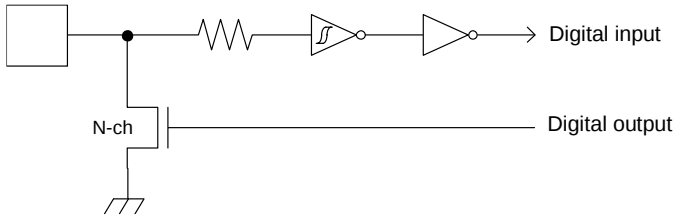
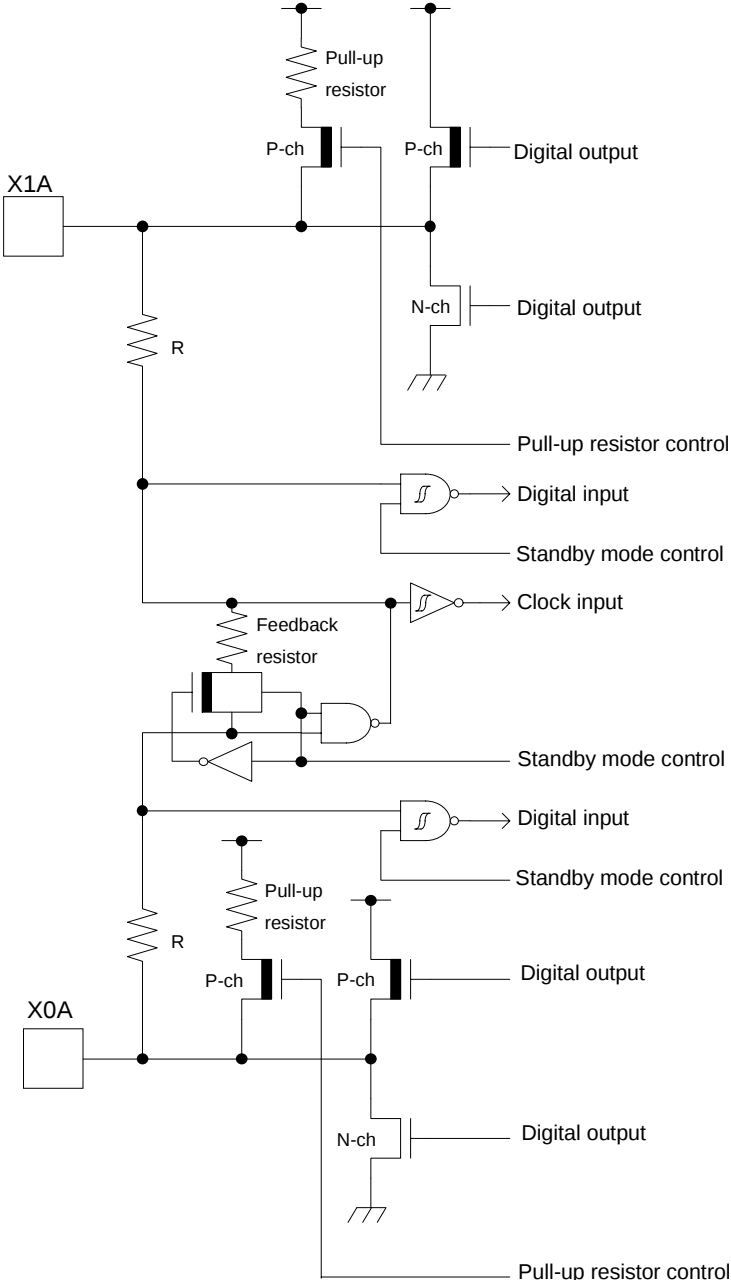
*: 5V tolerant I/O

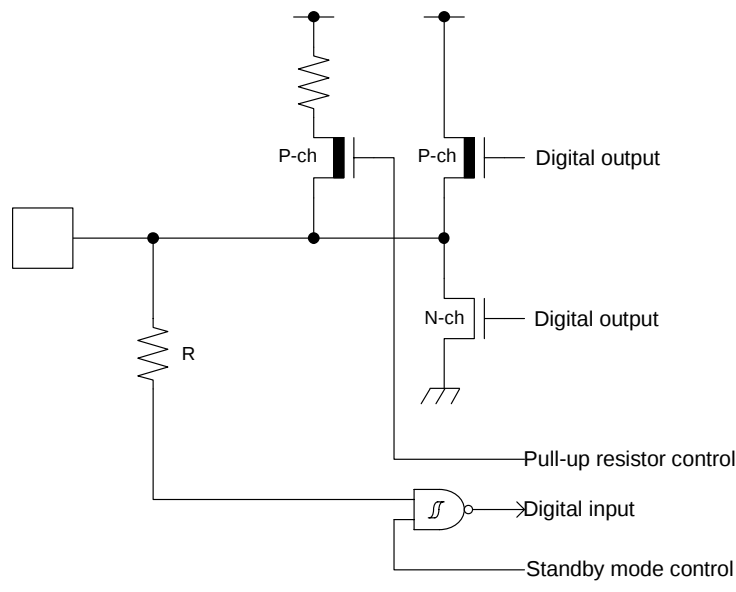
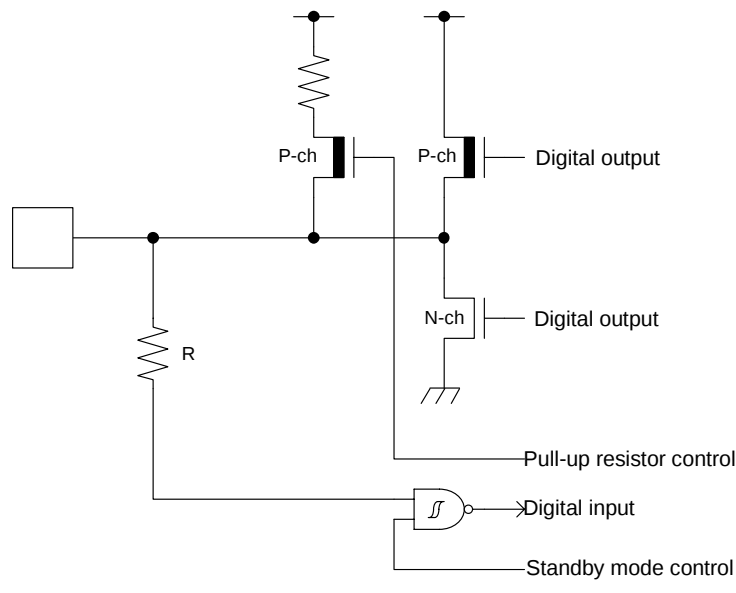
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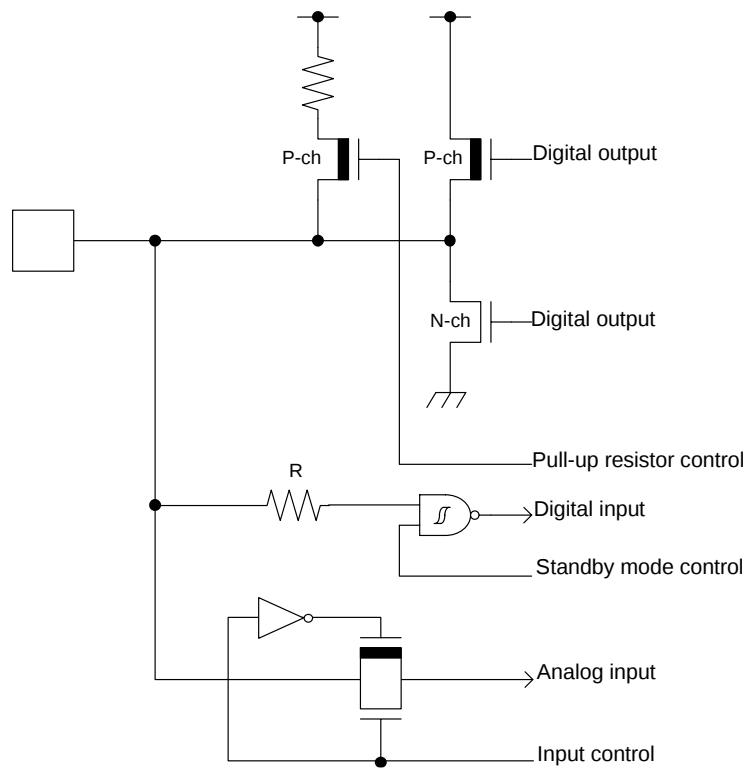
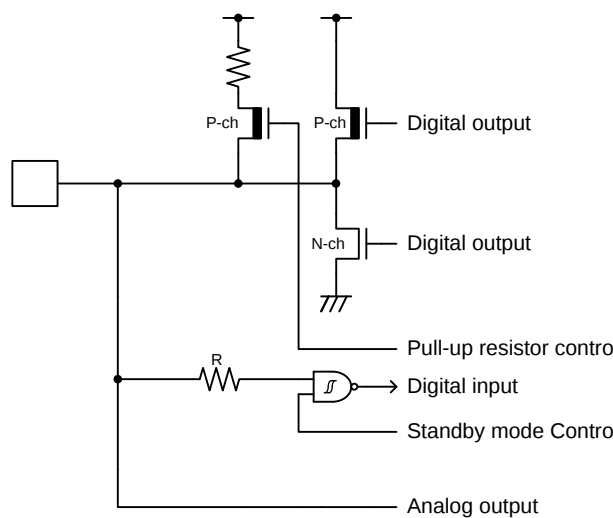
- While this device contains a Test Access Port (TAP) based on the IEEE 1149.1-2001 JTAG standard, it is not fully compliant to all requirements of that standard. This device may contain a 32-bit device ID that is the same as the 32-bit device ID in other devices with different functionality. The TAP pins may also be configurable for purposes other than access to the TAP controller.

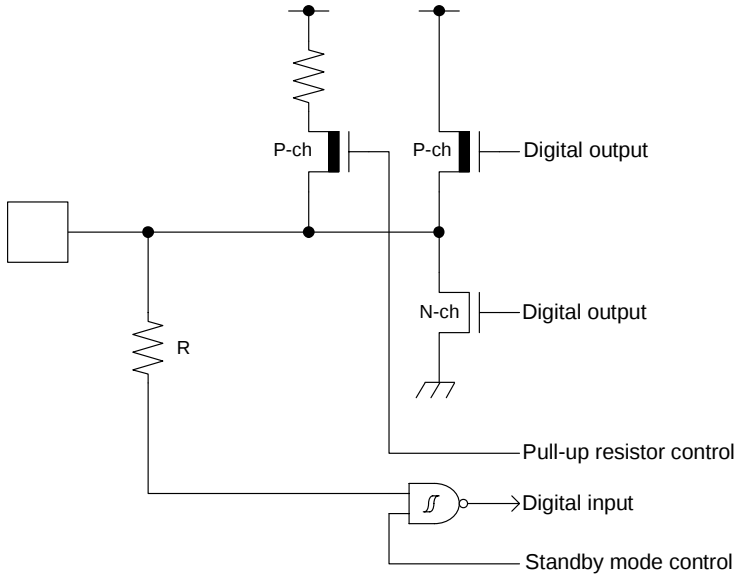
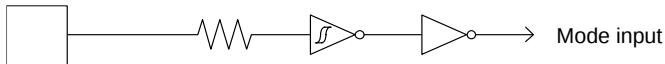
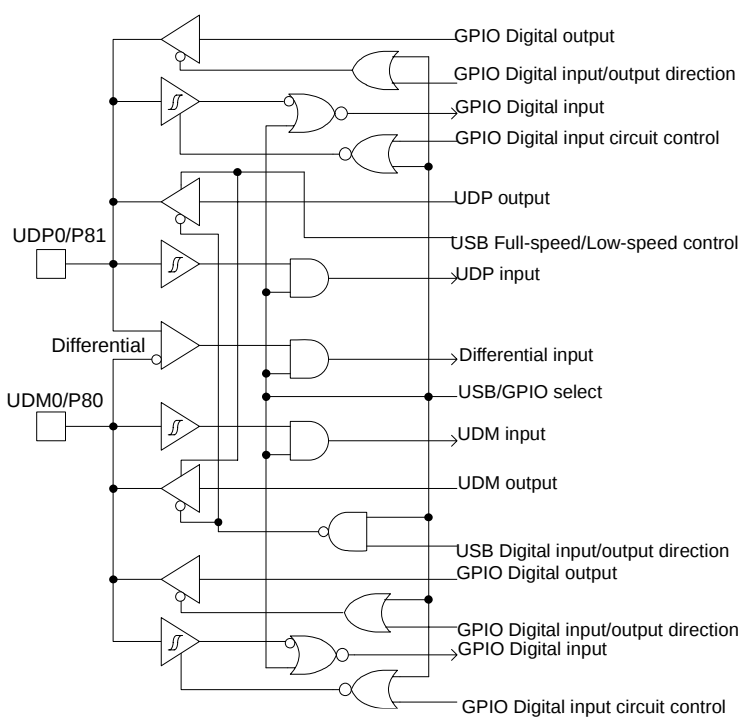
5. I/O Circuit Type

Type	Circuit	Remarks
A		It is possible to select the main oscillation / GPIO function When the main oscillation is selected. • Oscillation feedback resistor : Approximately 1 MΩ • With Standby mode control When the GPIO is selected. • CMOS level output. • CMOS level hysteresis input • With pull-up resistor control • With standby mode control • Pull-up resistor : Approximately 50 kΩ • $I_{OH} = -4$ mA, $I_{OL} = 4$ mA
B		• CMOS level hysteresis input • Pull-up resistor : Approximately 50 kΩ

Type	Circuit	Remarks
C		• Open drain output • CMOS level hysteresis input
D		It is possible to select the sub oscillation / GPIO function When the sub oscillation is selected. • Oscillation feedback resistor : Approximately 5 MΩ • With Standby mode control When the GPIO is selected. • CMOS level output. • CMOS level hysteresis input • With pull-up resistor control • With standby mode control • Pull-up resistor : Approximately 50 kΩ • I_{OH}= -4 mA, I_{OL}= 4 mA

Type	Circuit	Remarks
E		• CMOS level output • CMOS level hysteresis input • With pull-up resistor control • With standby mode control • Pull-up resistor : Approximately 50 kΩ • $I_{OH} = -4$ mA, $I_{OL} = 4$ mA • When this pin is used as an I²C pin, the digital output P-ch transistor is always off • +B input available
F		• CMOS level output • CMOS level hysteresis input • With pull-up resistor control • With standby mode control • Pull-up resistor : Approximately 50 kΩ • $I_{OH} = -12$ mA, $I_{OL} = 12$ mA • +B input available

Type	Circuit	Remarks
G		• CMOS level output • CMOS level hysteresis input • With input control • Analog input • With pull-up resistor control • With standby mode control • Pull-up resistor : Approximately 50 kΩ • $I_{OH} = -4 \text{ mA}$, $I_{OL} = 4 \text{ mA}$ • When this pin is used as an I²C pin, the digital output P-ch transistor is always off • +B input available
H		• CMOS level output • CMOS level hysteresis input • With input control • Analog output • With pull-up resistor control • With standby mode control • Pull-up resistor : Approximately 50 kΩ • $I_{OH} = -4 \text{ mA}$, $I_{OL} = 4 \text{ mA}$

Type	Circuit	Remarks
I		• CMOS level output • CMOS level hysteresis input • 5V tolerant • With pull-up resistor control • With standby mode control • Pull-up resistor : Approximately 50 kΩ • $I_{OH} = -4$ mA, $I_{OL} = 4$ mA • Available to control PZR registers. • When this pin is used as an I²C pin, the digital output P-ch transistor is always off
J		CMOS level hysteresis input
K		It is possible to select the USB I/O / GPIO function. When the USB I/O is selected. • Full-speed, Low-speed control When the GPIO is selected. • CMOS level output • CMOS level hysteresis input • With standby mode control

6. Handling Precautions

Any semiconductor devices have inherently a certain rate of failure. The possibility of failure is greatly affected by the conditions in which they are used (circuit conditions, environmental conditions, etc.). This page describes precautions that must be observed to minimize the chance of failure and to obtain higher reliability from your Cypress semiconductor devices.

6.1 Precautions for Product Design

This section describes precautions when designing electronic equipment using semiconductor devices.

Absolute Maximum Ratings

Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of certain established limits, called absolute maximum ratings. Do not exceed these ratings.

Recommended Operating Conditions

Recommended operating conditions are normal operating ranges for the semiconductor device. All the device's electrical characteristics are warranted when operated within these ranges.

Always use semiconductor devices within the recommended operating conditions. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their sales representative beforehand.

Processing and Protection of Pins

These precautions must be followed when handling the pins which connect semiconductor devices to power supply and input/output functions.

1. Preventing Over-Voltage and Over-Current Conditions

Exposure to voltage or current levels in excess of maximum ratings at any pin is likely to cause deterioration within the device, and in extreme cases leads to permanent damage of the device. Try to prevent such overvoltage or over-current conditions at the design stage.

2. Protection of Output Pins

Shorting of output pins to supply pins or other output pins, or connection to large capacitance can cause large current flows. Such conditions if present for extended periods of time can damage the device. Therefore, avoid this type of connection.

3. (Handling of Unused Input Pins

Unconnected input pins with very high impedance levels can adversely affect stability of operation. Such pins should be connected through an appropriate resistance to a power supply pin or ground pin.

Latch-up

Semiconductor devices are constructed by the formation of P-type and N-type areas on a substrate. When subjected to abnormally high voltages, internal parasitic PNPN junctions (called thyristor structures) may be formed, causing large current levels in excess of several hundred mA to flow continuously at the power supply pin. This condition is called latch-up.

CAUTION: The occurrence of latch-up not only causes loss of reliability in the semiconductor device, but can cause injury or damage from high heat, smoke or flame. To prevent this from happening, do the following:

1. Be sure that voltages applied to pins do not exceed the absolute maximum ratings. This should include attention to abnormal noise, surge levels, etc.
2. Be sure that abnormal current flows do not occur during the power-on sequence.

Observance of Safety Regulations and Standards

Most countries in the world have established standards and regulations regarding safety, protection from electromagnetic interference, etc. Customers are requested to observe applicable regulations and standards in the design of products.

Fail-Safe Design

Any semiconductor devices have inherently a certain rate of failure. You must protect against injury, damage or loss from such failures by incorporating safety design measures into your facility and equipment such as redundancy, fire protection, and prevention of over-current levels and other abnormal operating conditions.

Precautions Related to Usage of Devices

Cypress semiconductor devices are intended for use in standard applications (computers, office automation and other office equipment, industrial, communications, and measurement equipment, personal or household devices, etc.).

CAUTION: Customers considering the use of our products in special applications where failure or abnormal operation may directly affect human lives or cause physical injury or property damage, or where extremely high levels of reliability are demanded (such as aerospace systems, atomic energy controls, sea floor repeaters, vehicle operating controls, medical devices for life support, etc.) are requested to consult with sales representatives before such use. The company will not be responsible for damages arising from such use without prior approval.

6.2 Precautions for Package Mounting

Package mounting may be either lead insertion type or surface mount type. In either case, for heat resistance during soldering, you should only mount under Cypress's recommended conditions. For detailed information about mount conditions, contact your sales representative.

Lead Insertion Type

Mounting of lead insertion type packages onto printed circuit boards may be done by two methods: direct soldering on the board, or mounting by using a socket.

Direct mounting onto boards normally involves processes for inserting leads into through-holes on the board and using the flow soldering (wave soldering) method of applying liquid solder. In this case, the soldering process usually causes leads to be subjected to thermal stress in excess of the absolute ratings for storage temperature. Mounting processes should conform to Cypress recommended mounting conditions.

If socket mounting is used, differences in surface treatment of the socket contacts and IC lead surfaces can lead to contact deterioration after long periods. For this reason it is recommended that the surface treatment of socket contacts and IC leads be verified before mounting.

Surface Mount Type

Surface mount packaging has longer and thinner leads than lead-insertion packaging, and therefore leads are more easily deformed or bent. The use of packages with higher pin counts and narrower pin pitch results in increased susceptibility to open connections caused by deformed pins, or shorting due to solder bridges.

You must use appropriate mounting techniques. Cypress recommends the solder reflow method, and has established a ranking of mounting conditions for each product. Users are advised to mount packages in accordance with Cypress ranking of recommended conditions.

Lead-Free Packaging

CAUTION: When ball grid array (BGA) packages with Sn-Ag-Cu balls are mounted using Sn-Pb eutectic soldering, junction strength may be reduced under some conditions of use.

Storage of Semiconductor Devices

Because plastic chip packages are formed from plastic resins, exposure to natural environmental conditions will cause absorption of moisture. During mounting, the application of heat to a package that has absorbed moisture can cause surfaces to peel, reducing moisture resistance and causing packages to crack. To prevent, do the following:

1. Avoid exposure to rapid temperature changes, which cause moisture to condense inside the product. Store products in locations where temperature changes are slight.
2. Use dry boxes for product storage. Products should be stored below 70% relative humidity, and at temperatures between 5°C and 30°C.
When you open Dry Package that recommends humidity 40% to 70% relative humidity.
3. When necessary, Cypress packages semiconductor devices in highly moisture-resistant aluminum laminate bags, with a silica gel desiccant. Devices should be sealed in their aluminum laminate bags for storage.
4. Avoid storing packages where they are exposed to corrosive gases or high levels of dust.

Baking

Packages that have absorbed moisture may be de-moisturized by baking (heat drying). Follow the Cypress recommended conditions for baking.

Condition: 125°C/24 h

Static Electricity

Because semiconductor devices are particularly susceptible to damage by static electricity, you must take the following precautions:

1. Maintain relative humidity in the working environment between 40% and 70%. Use of an apparatus for ion generation may be needed to remove electricity.
2. Electrically ground all conveyors, solder vessels, soldering irons and peripheral equipment.
3. Eliminate static body electricity by the use of rings or bracelets connected to ground through high resistance (on the level of 1 MΩ).
Wearing of conductive clothing and shoes, use of conductive floor mats and other measures to minimize shock loads is recommended.
4. Ground all fixtures and instruments, or protect with anti-static measures.
5. Avoid the use of styrofoam or other highly static-prone materials for storage of completed board assemblies.

6.3 Precautions for Use Environment

Reliability of semiconductor devices depends on ambient temperature and other conditions as described above.

For reliable performance, do the following:

1. Humidity
Prolonged use in high humidity can lead to leakage in devices as well as printed circuit boards. If high humidity levels are anticipated, consider anti-humidity processing.
2. Discharge of Static Electricity
When high-voltage charges exist close to semiconductor devices, discharges can cause abnormal operation. In such cases, use anti-static measures or processing to prevent discharges.
3. Corrosive Gases, Dust, or Oil
Exposure to corrosive gases or contact with dust or oil may lead to chemical reactions that will adversely affect the device. If you use devices in such conditions, consider ways to prevent such exposure or to protect the devices.
4. Radiation, Including Cosmic Radiation
Most devices are not designed for environments involving exposure to radiation or cosmic radiation. Users should provide shielding as appropriate.
5. Smoke, Flame
CAUTION: Plastic molded devices are flammable, and therefore should not be used near combustible substances. If devices begin to smoke or burn, there is danger of the release of toxic gases.

Customers considering the use of Cypress products in other special environmental conditions should consult with sales representatives.

7. Handling Devices

Power supply pins

In products with multiple VCC and VSS pins, respective pins at the same potential are interconnected within the device in order to prevent malfunctions such as latch-up. However, all of these pins should be connected externally to the power supply or ground lines in order to reduce electromagnetic emission levels, to prevent abnormal operation of strobe signals caused by the rise in the ground level, and to conform to the total output current rating.

Moreover, connect the current supply source with each Power supply pin and GND pin of this device at low impedance. It is also advisable that a ceramic capacitor of approximately 0.1 μF be connected as a bypass capacitor between each Power supply pin and GND pin near this device.

Stabilizing power supply voltage

A malfunction may occur when the power supply voltage fluctuates rapidly even though the fluctuation is within the recommended operating conditions of the VCC power supply voltage. As a rule, with voltage stabilization, suppress the voltage fluctuation so that the fluctuation in VCC ripple (peak-to-peak value) at the commercial frequency (50 Hz/60 Hz) does not exceed 10% of the VCC value in the recommended operating conditions, and the transient fluctuation rate does not exceed 0.1 V/ μs when there is a momentary fluctuation on switching the power supply.

Crystal oscillator circuit

Noise near the X0/X1 and X0A/X1A pins may cause the device to malfunction. Design the printed circuit board so that X0/X1, X0A/X1A pins, the crystal oscillator, and the bypass capacitor to ground are located as close to the device as possible.

It is strongly recommended that the PC board artwork be designed such that the X0/X1 and X0A/X1A pins are surrounded by ground plane as this is expected to produce stable operation.

Evaluate oscillation of your using crystal oscillator by your mount board.

Sub crystal oscillator

This series sub oscillator circuit is low gain to keep the low current consumption. The crystal oscillator to fill the following conditions is recommended for sub crystal oscillator to stabilize the oscillation.

■ Surface mount type

Size : More than 3.2 mm $\times$ 1.5 mm
 Load capacitance : Approximately 6 pF to 7 pF

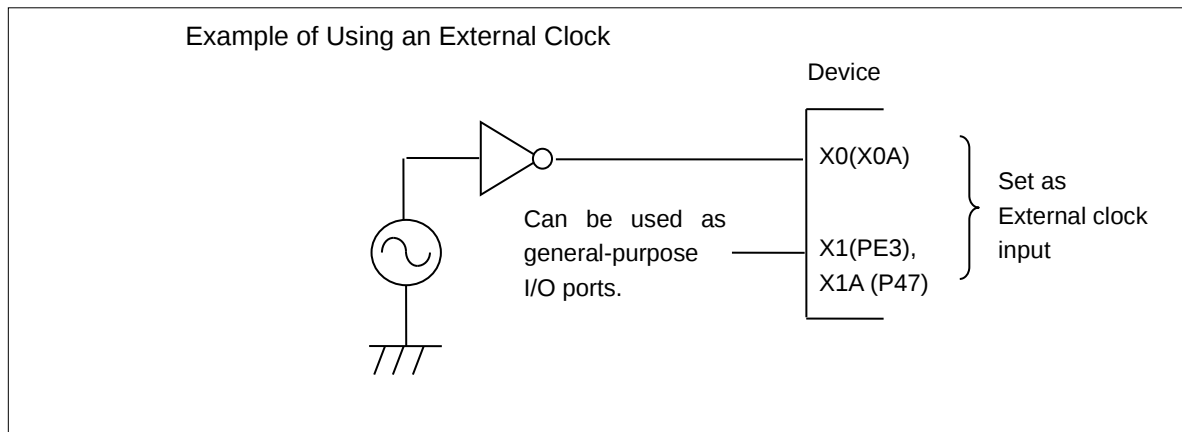
■ Lead type

Load capacitance : Approximately 6 pF to 7 pF

Using an external clock

When using an external clock as an input of the main clock, set X0/X1 to the external clock input, and input the clock to X0. X1(PE3) can be used as a general-purpose I/O port.

Similarly, when using an external clock as an input of the sub clock, set X0A/X1A to the external clock input, and input the clock to X0A. X1A (P47) can be used as a general-purpose I/O port.



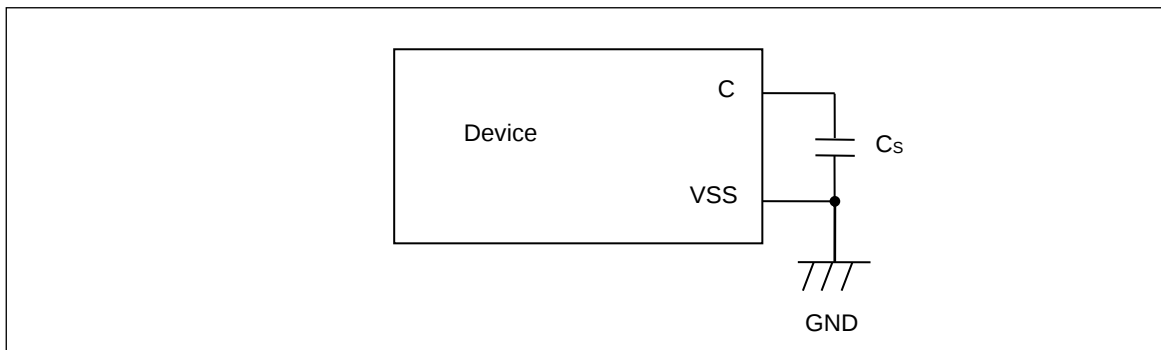
Handling when using Multi-function serial pin as I²C pin

If it is using the multi-function serial pin as I²C pins, P-ch transistor of digital output is always disabled. However, I²C pins need to keep the electrical characteristic like other pins and not to connect to the external I²C bus system with power OFF.

C Pin

This series contains the regulator. Be sure to connect a smoothing capacitor (C_s) for the regulator between the C pin and the GND pin. Please use a ceramic capacitor or a capacitor of equivalent frequency characteristics as a smoothing capacitor. However, some laminated ceramic capacitors have the characteristics of capacitance variation due to thermal fluctuation (F characteristics and Y5V characteristics). Please select the capacitor that meets the specifications in the operating conditions to use by evaluating the temperature characteristics of a capacitor.

A smoothing capacitor of about 4.7μF would be recommended for this series.



Mode pins (MD0)

Connect the MD pin (MD0) directly to VCC or VSS pins. Design the printed circuit board such that the pull-up/down resistance stays low, as well as the distance between the mode pins and VCC pins or VSS pins is as short as possible and the connection impedance is low, when the pins are pulled-up/down such as for switching the pin level and rewriting the Flash memory data. It is because of preventing the device erroneously switching to test mode due to noise.

Notes on power-on

Turn power on/off in the following order or at the same time.

If not using the A/D converter and D/A converter, connect AVCC = VCC and AVSS = VSS.

Turning on : VCC → USBVCC

VCC → AVCC → AVRH

Turning off : AVRH → AVCC → VCC

USBVCC → VCC

Serial Communication

There is a possibility to receive wrong data due to the noise or other causes on the serial communication.

Therefore, design a printed circuit board so as to avoid noise.

Consider the case of receiving wrong data due to noise, perform error detection such as by applying a checksum of data at the end.

If an error is detected, retransmit the data.

Differences in features among the products with different memory sizes and between Flash memory products and MASK products

The electric characteristics including power consumption, ESD, latch-up, noise characteristics, and oscillation characteristics among the products with different memory sizes and between Flash memory products and MASK products are different because chip layout and memory structures are different.

If you are switching to use a different product of the same series, please make sure to evaluate the electric characteristics.

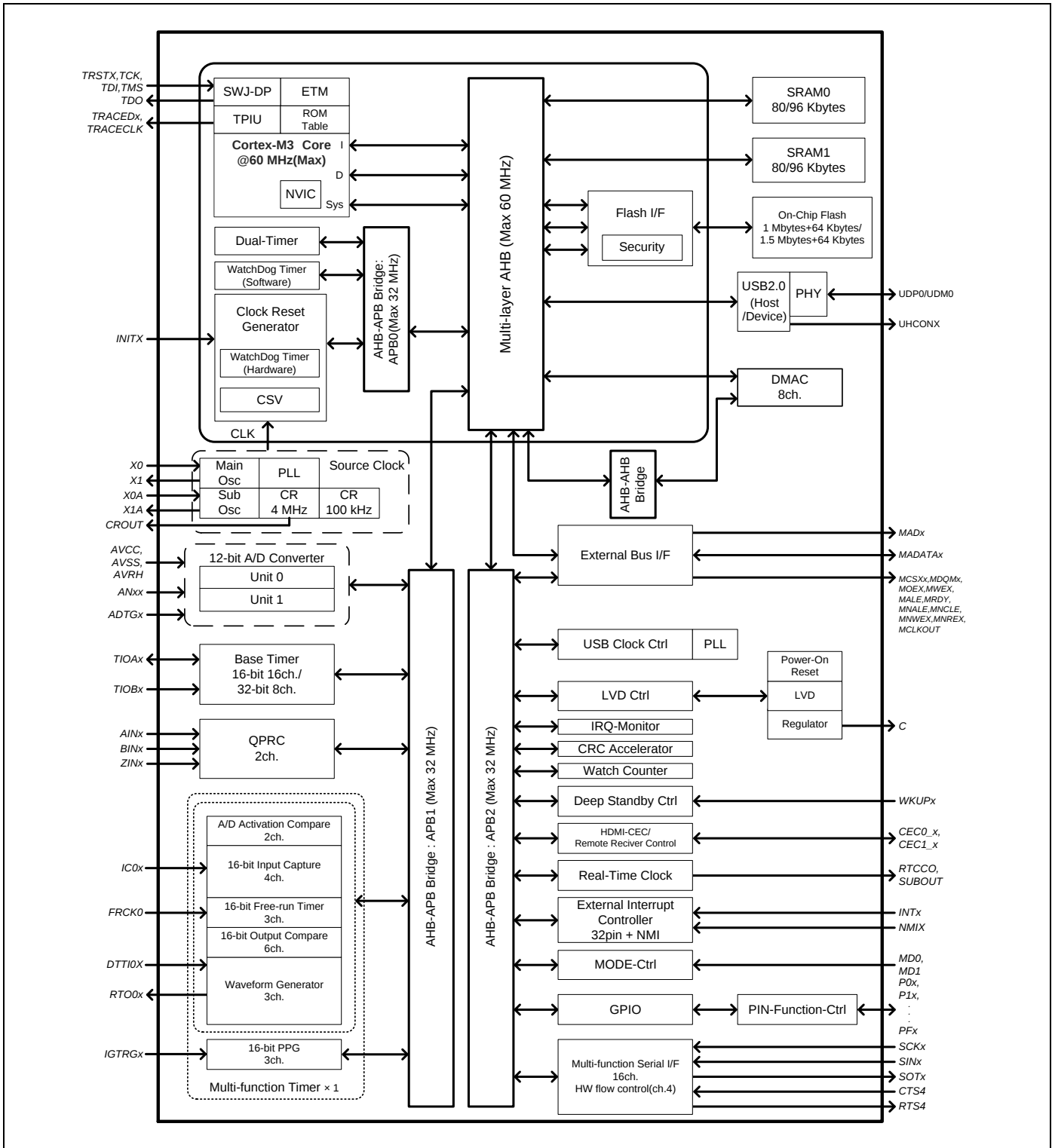
Pull-Up function of 5V tolerant I/O

Please do not input the signal more than VCC voltage at the time of Pull-Up function use of 5V tolerant I/O.

Adjoining wiring on circuit board

If wiring of the crystal oscillation circuit (X0/X1 and X0A/X1A) adjoins and also runs in parallel with the wiring of GPIO, there is a possibility that the oscillation erroneously counts because oscillation wave has noise with the change of GPIO. Keep as much distance as possible between both wirings and insert the ground pattern between them in order to avoid this possibility.

8. Block Diagram

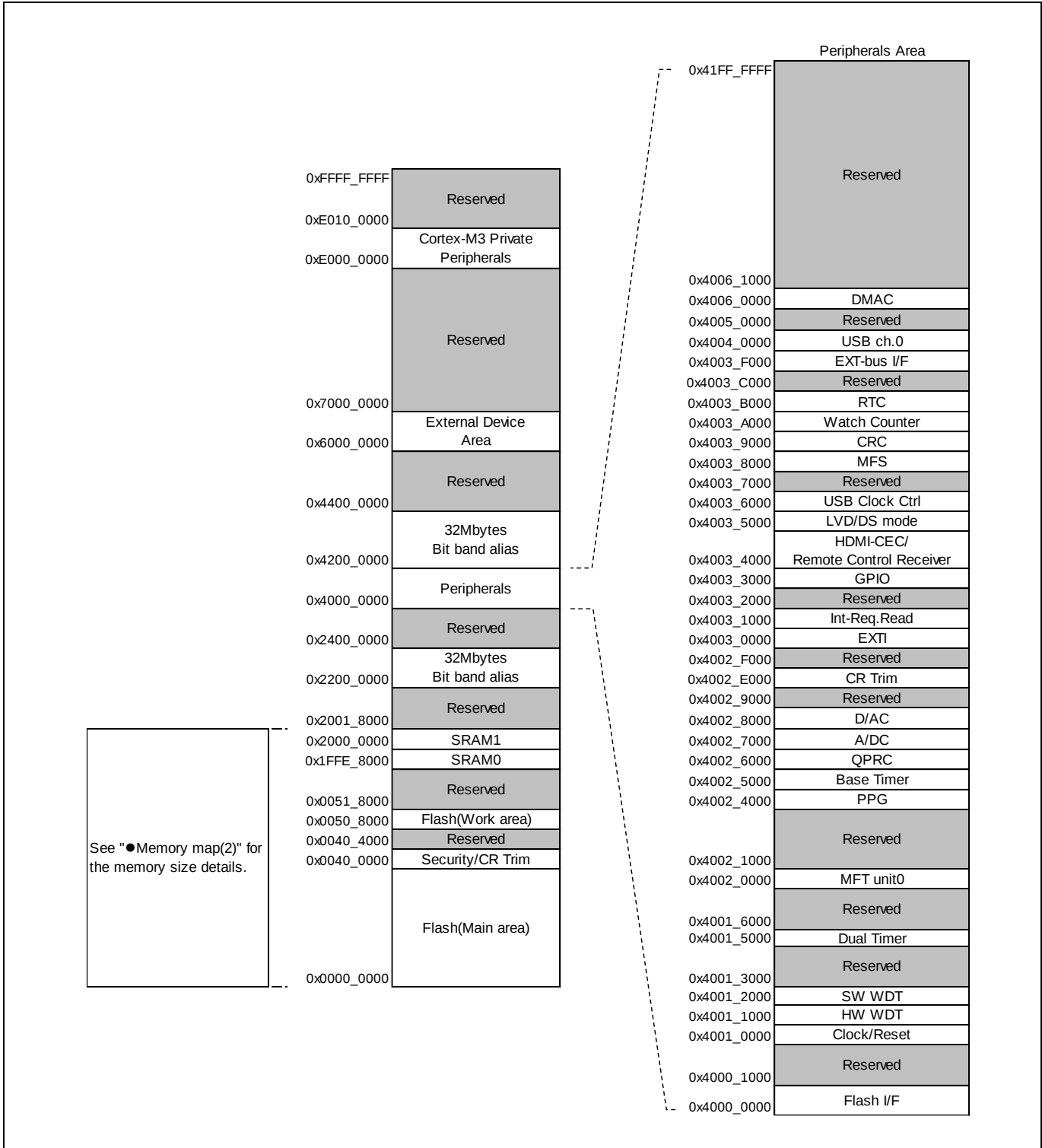


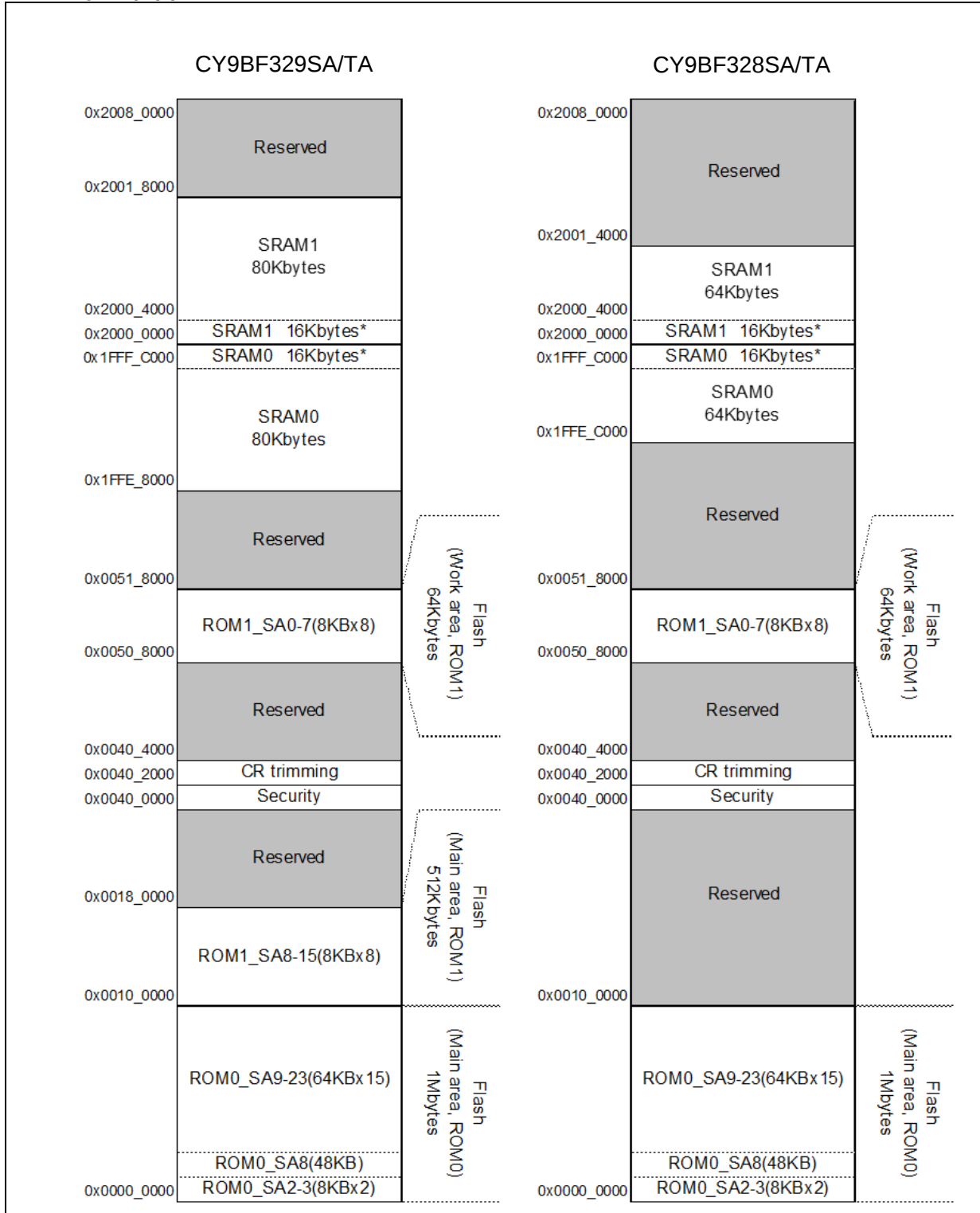
9. Memory Size

See "Memory size" in "Product Lineup" to confirm the memory size.

10. Memory Map

Memory Map (1)



Memory Map (2)


The content of SRAM can be retained at the deep standby modes by the setting of Deep Standby RAM Retention Register (DSRAMR).
 See " FM3 FAMILY CY9B520T/420T/320T/120T SERIES, FLASH PROGRAMMING SPECIFICATIONS" for sector structure of Flash.

Peripheral Address Map

Start address	End address	Bus	Peripherals
0x4000_0000	0x4000_0FFF	AHB	Flash Memory I/F register
0x4000_1000	0x4000_FFFF		Reserved
0x4001_0000	0x4001_0FFF	APB0	Clock/Reset Control
0x4001_1000	0x4001_1FFF		Hardware Watchdog timer
0x4001_2000	0x4001_2FFF		Software Watchdog timer
0x4001_3000	0x4001_4FFF		Reserved
0x4001_5000	0x4001_5FFF		Dual-Timer
0x4001_6000	0x4001_FFFF		Reserved
0x4002_0000	0x4002_0FFF	APB1	Multi-function timer unit0
0x4002_1000	0x4002_3FFF		Reserved
0x4002_4000	0x4002_4FFF		PPG
0x4002_5000	0x4002_5FFF		Base Timer
0x4002_6000	0x4002_6FFF		Quadrature Position/Revolution Counter (QPRC)
0x4002_7000	0x4002_7FFF		A/D Converter
0x4002_8000	0x4002_8FFF		D/A Converter
0x4002_9000	0x4002_DFFF		Reserved
0x4002_E000	0x4002_EFFF		Built-in CR trimming
0x4002_F000	0x4002_FFFF		Reserved
0x4003_0000	0x4003_0FFF	APB2	External Interrupt
0x4003_1000	0x4003_1FFF		Interrupt Source Check Resister
0x4003_2000	0x4003_2FFF		Reserved
0x4003_3000	0x4003_3FFF		GPIO
0x4003_4000	0x4003_4FFF		HDMI-CEC/Remote control Reception
0x4003_5000	0x4003_57FF		Low-Voltage Detector
0x4003_5800	0x4003_5FFF		Deep standby mode Controller
0x4003_6000	0x4003_6FFF		USB clock generator
0x4003_7000	0x4003_7FFF		Reserved
0x4003_8000	0x4003_8FFF		Multi-function serial Interface
0x4003_9000	0x4003_9FFF		CRC
0x4003_A000	0x4003_AFFF		Watch Counter
0x4003_B000	0x4003_BFFF		Real-time clock
0x4003_C000	0x4003_EFFF		Reserved
0x4003_F000	0x4003_FFFF		External bus interface
0x4004_0000	0x4004_FFFF	AHB	USB ch.0
0x4005_0000	0x4005_FFFF		Reserved
0x4006_0000	0x4006_0FFF		DMAC register
0x4006_1000	0x400F_FFFF		Reserved

11. Pin Status in Each CPU State

The terms used for pin status have the following meanings.

■ **INITX=0**

This is the period when the INITX pin is the "L" level.

■ **INITX=1**

This is the period when the INITX pin is the "H" level.

■ **SPL=0**

This is the status that the standby pin level setting bit (SPL) in the standby mode control register (STB_CTL) is set to "0".

■ **SPL=1**

This is the status that the standby pin level setting bit (SPL) in the standby mode control register (STB_CTL) is set to "1".

■ **Input enabled**

Indicates that the input function can be used.

■ **Internal input fixed at "0"**

This is the status that the input function cannot be used. Internal input is fixed at "L".

■ **Hi-Z**

Indicates that the pin drive transistor is disabled and the pin is put in the Hi-Z state.

■ **Setting disabled**

Indicates that the setting is disabled.

■ **Maintain previous state**

Maintains the state that was immediately prior to entering the current mode.
If a built-in peripheral function is operating, the output follows the peripheral function.
If the pin is being used as a port, that output is maintained.

■ **Analog input is enabled**

Indicates that the analog input is enabled.

■ **Trace output**

Indicates that the trace function can be used.

■ **GPIO selected**

In Deep standby mode, pins switch to the general-purpose I/O port.

List of Pin Status

Pin status type	Function group	Power-on reset or low-voltage detection state	INITX input state	Device internal reset state	Run mode or SLEEP mode state	Timer mode, RTC mode, or STOP mode state		Deep standby RTC mode or Deep standby STOP mode state		Return from Deep standby mode state
		Power supply unstable	Power supply stable		Power supply stable	Power supply stable		Power supply stable		Power supply stable
		-	INITX = 0	INITX = 1	INITX = 1	INITX = 1		INITX = 1		INITX = 1
		-	-	-	-	SPL = 0	SPL = 1	SPL = 0	SPL = 1	-
A	GPIO selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z / Internal input fixed at "0"	GPIO selected Internal input fixed at "0"	Hi-Z / Internal input fixed at "0"	GPIO selected
	Main crystal oscillator input pin/ External main clock input selected	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled
B	GPIO selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z / Internal input fixed at "0"	GPIO selected Internal input fixed at "0"	Hi-Z / Internal input fixed at "0"	GPIO selected
	External main clock input selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z / Internal input fixed at "0"	Maintain previous state	Hi-Z / Internal input fixed at "0"	Maintain previous state
	Main crystal oscillator output pin	Hi-Z / Internal input fixed at "0"/ or Input enable	Hi-Z / Internal input fixed at "0"	Hi-Z / Internal input fixed at "0"	Maintain previous state/When oscillation stops*1, Hi-Z / Internal input fixed at "0"	Maintain previous state/When oscillation stops*1, Hi-Z / Internal input fixed at "0"	Maintain previous state/When oscillation stops*1, Hi-Z / Internal input fixed at "0"	Maintain previous state/When oscillation stops*1, Hi-Z / Internal input fixed at "0"	Maintain previous state/When oscillation stops*1, Hi-Z / Internal input fixed at "0"	Maintain previous state/When oscillation stops*1, Hi-Z / Internal input fixed at "0"
C	INITX input pin	Pull-up / Input enabled	Pull-up / Input enabled	Pull-up / Input enabled	Pull-up / Input enabled	Pull-up / Input enabled	Pull-up / Input enabled	Pull-up / Input enabled	Pull-up / Input enabled	Pull-up / Input enabled
D	Mode input pin	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled

Pin status type	Function group	Power-on reset or low-voltage detection state	INITX input state	Device internal reset state	Run mode or SLEEP mode state	Timer mode, RTC mode, or STOP mode state		Deep standby RTC mode or Deep standby STOP mode state		Return from Deep standby mode state
		Power supply unstable	Power supply stable		Power supply stable	Power supply stable		Power supply stable		Power supply stable
		-	INITX = 0	INITX = 1	INITX = 1	INITX = 1		INITX = 1		INITX = 1
		-	-	-	-	SPL = 0	SPL = 1	SPL = 0	SPL = 1	-
E	Mode input pin	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled
	GPIO selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z / Input enabled	GPIO selected	Hi-Z / Input enabled	GPIO selected
F	GPIO selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z / Internal input fixed at "0"	GPIO selected Internal input fixed at "0"	Hi-Z / Internal input fixed at "0"	GPIO selected
	Sub crystal oscillator input pin / External sub clock input selected	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled
G	GPIO selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z / Internal input fixed at "0"	GPIO selected Internal input fixed at "0"	Hi-Z / Internal input fixed at "0"	GPIO selected
	External sub clock input selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z / Internal input fixed at "0"	Maintain previous state	Hi-Z / Internal input fixed at "0"	Maintain previous state
	Sub crystal oscillator output pin	Hi-Z / Internal input fixed at "0" / or Input enable	Hi-Z / Internal input fixed at "0"	Hi-Z / Internal input fixed at "0"	Maintain previous state	Maintain previous state/When oscillation stops*2, Hi-Z / Internal input fixed at "0"	Maintain previous state/When oscillation stops*2, Hi-Z / Internal input fixed at "0"	Maintain previous state/When oscillation stops*2, Hi-Z / Internal input fixed at "0"	Maintain previous state/When oscillation stops*2, Hi-Z / Internal input fixed at "0"	Maintain previous state/When oscillation stops*2, Hi-Z / Internal input fixed at "0"

Pin status type	Function group	Power-on reset or low-voltage detection state	INITX input state	Device internal reset state	Run mode or SLEEP mode state	Timer mode, RTC mode, or STOP mode state		Deep standby RTC mode or Deep standby STOP mode state		Return from Deep standby mode state
		Power supply unstable	Power supply stable		Power supply stable	Power supply stable		Power supply stable		Power supply stable
		-	INITX = 0	INITX = 1	INITX = 1	INITX = 1		INITX = 1		INITX = 1
		-	-	-	-	SPL = 0	SPL = 1	SPL = 0	SPL = 1	-
H	NMIX selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Maintain previous state	WKUP input enabled	Hi-Z / WKUP input enabled	GPIO selected
	GPIO selected	Hi-Z	Hi-Z / Input enabled	Hi-Z / Input enabled			Hi-Z / Internal input fixed at "0"			
I	JTAG selected	Hi-Z	Pull-up / Input enabled	Pull-up / Input enabled	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state
	GPIO selected	Setting disabled	Setting disabled	Setting disabled			Hi-Z / Internal input fixed at "0"	GPIO selected Internal input fixed at "0"	Hi-Z / Internal input fixed at "0"	GPIO selected
J	Resource selected	Hi-Z	Hi-Z / Input enabled	Hi-Z / Input enabled	Maintain previous state	Maintain previous state	Hi-Z / Internal input fixed at "0"	GPIO selected Internal input fixed at "0"	Hi-Z / Internal input fixed at "0"	GPIO selected
	GPIO selected									
K	External interrupt enabled selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Maintain previous state	GPIO selected Internal input fixed at "0"	Hi-Z / Internal input fixed at "0"	GPIO selected
	Resource other than above selected	Hi-Z	Hi-Z / Input enabled	Hi-Z / Input enabled			Hi-Z / Internal input fixed at "0"			
	GPIO selected									
L	Analog input selected	Hi-Z	Hi-Z / Internal input fixed at "0" / Analog input enabled	Hi-Z / Internal input fixed at "0" / Analog input enabled	Hi-Z / Internal input fixed at "0" / Analog input enabled	Hi-Z / Internal input fixed at "0" / Analog input enabled	Hi-Z / Internal input fixed at "0" / Analog input enabled	Hi-Z / Internal input fixed at "0" / Analog input enabled	Hi-Z / Internal input fixed at "0" / Analog input enabled	Hi-Z / Internal input fixed at "0" / Analog input enabled
	Resource other than above selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z / Internal input fixed at "0"	GPIO selected Internal input fixed at "0"	Hi-Z / Internal input fixed at "0"	GPIO selected
	GPIO selected									

Pin status type	Function group	Power-on reset or low-voltage detection state	INITX input state	Device internal reset state	Run mode or SLEEP mode state	Timer mode, RTC mode, or STOP mode state		Deep standby RTC mode or Deep standby STOP mode state		Return from Deep standby mode state	
		Power supply unstable	Power supply stable		Power supply stable	Power supply stable		Power supply stable		Power supply stable	
		-	INITX = 0	INITX = 1	INITX = 1	INITX = 1		INITX = 1		INITX = 1	
		-	-	-	-	SPL = 0	SPL = 1	SPL = 0	SPL = 1	-	
M	Analog input selected	Hi-Z	Hi-Z / Internal input fixed at "0" / Analog input enabled	Hi-Z / Internal input fixed at "0" / Analog input enabled	Hi-Z / Internal input fixed at "0" / Analog input enabled	Hi-Z / Internal input fixed at "0" / Analog input enabled	Hi-Z / Internal input fixed at "0" / Analog input enabled	Hi-Z / Internal input fixed at "0" / Analog input enabled	Hi-Z / Internal input fixed at "0" / Analog input enabled	Hi-Z / Internal input fixed at "0" / Analog input enabled	
	External interrupt enabled selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Maintain previous state	GPIO selected Internal input fixed at "0"	Hi-Z / Internal input fixed at "0"	GPIO selected	
	Resource other than above selected						Hi-Z / Internal input fixed at "0"				
	GPIO selected										
N	Analog input selected	Hi-Z	Hi-Z / Internal input fixed at "0" / Analog input enabled	Hi-Z / Internal input fixed at "0" / Analog input enabled	Hi-Z / Internal input fixed at "0" / Analog input enabled	Hi-Z / Internal input fixed at "0" / Analog input enabled	Hi-Z / Internal input fixed at "0" / Analog input enabled	Hi-Z / Internal input fixed at "0" / Analog input enabled	Hi-Z / Internal input fixed at "0" / Analog input enabled	Hi-Z / Internal input fixed at "0" / Analog input enabled	
	WKUP enabled	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Maintain previous state	WKUP input enabled	Hi-Z / WKUP input enabled	GPIO selected	
	External interrupt enabled selected							GPIO selected Internal input fixed at "0"	Hi-Z / Internal input fixed at "0"		
	Resource other than above selected										
	GPIO selected										

Pin status type	Function group	Power-on reset or low-voltage detection state	INITX input state	Device internal reset state	Run mode or SLEEP mode state	Timer mode, RTC mode, or STOP mode state		Deep standby RTC mode or Deep standby STOP mode state		Return from Deep standby mode state
		Power supply unstable	Power supply stable		Power supply stable	Power supply stable		Power supply stable		Power supply stable
		-	INITX = 0	INITX = 1	INITX = 1	INITX = 1		INITX = 1		INITX = 1
		-	-	-	-	SPL = 0	SPL = 1	SPL = 0	SPL = 1	-
O	Analog output selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	*3	*4	GPIO selected Internal input fixed at "0"	Hi-Z / Internal input fixed at "0"	GPIO selected
	Resource other than above selected	Hi-Z	Hi-Z / Input enabled	Hi-Z / Input enabled		Maintain previous state	Hi-Z / Internal input fixed at "0"			
	GPIO selected									
P	Trace selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Trace output	GPIO selected Internal input fixed at "0"	Hi-Z / Internal input fixed at "0"	GPIO selected
	Resource other than above selected	Hi-Z	Hi-Z / Input enabled	Hi-Z / Input enabled			Hi-Z / Internal input fixed at "0"			
	GPIO selected									
Q	Trace selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Trace output	GPIO selected Internal input fixed at "0"	Hi-Z / Internal input fixed at "0"	GPIO selected
	External interrupt enabled selected						Maintain previous state			
	Resource other than above selected	Hi-Z	Hi-Z / Input enabled	Hi-Z / Input enabled			Hi-Z / Internal input fixed at "0"			
	GPIO selected									
R	CEC enabled	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state
	Resource other than above selected	Hi-Z	Hi-Z / Input enabled	Hi-Z / Input enabled			Hi-Z / Internal input fixed at "0"	GPIO selected Internal input fixed at "0"	Hi-Z / Internal input fixed at "0"	GPIO selected
	GPIO selected									

Pin status type	Function group	Power-on reset or low-voltage detection state	INITX input state	Device internal reset state	Run mode or SLEEP mode state	Timer mode, RTC mode, or STOP mode state		Deep standby RTC mode or Deep standby STOP mode state		Return from Deep standby mode state
		Power supply unstable	Power supply stable		Power supply stable	Power supply stable		Power supply stable		Power supply stable
		-	INITX = 0	INITX = 1	INITX = 1	INITX = 1		INITX = 1		INITX = 1
		-	-	-	-	SPL = 0	SPL = 1	SPL = 0	SPL = 1	-
S	CEC enabled	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state
	External interrupt enabled selected							GPIO selected	Hi-Z / Internal input fixed at "0"	GPIO selected
	Resource other than above selected	Hi-Z	Hi-Z / Input enabled							
	GPIO selected									
T	CEC enabled	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state
	WKUP enabled							GPIO selected	Hi-Z / Internal input fixed at "0"	GPIO selected
	External interrupt enabled selected									
	Resource other than above selected	Hi-Z	Hi-Z / Input enabled	Hi-Z / Input enabled						
	GPIO selected									
U	WKUP enabled	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Maintain previous state	WKUP input enabled	Hi-Z / WKUP input enabled	GPIO selected
	External interrupt enabled selected							GPIO selected	Hi-Z / Internal input fixed at "0"	
	Resource other than above selected	Hi-Z	Hi-Z / Input enabled	Hi-Z / Input enabled						
	GPIO selected									

Pin status type	Function group	Power-on reset or low-voltage detection state	INITX input state	Device internal reset state	Run mode or SLEEP mode state	Timer mode, RTC mode, or STOP mode state		Deep standby RTC mode or Deep standby STOP mode state		Return from Deep standby mode state
		Power supply unstable	Power supply stable		Power supply stable	Power supply stable		Power supply stable		Power supply stable
		-	INITX = 0	INITX = 1	INITX = 1	INITX = 1		INITX = 1		INITX = 1
		-	-	-	-	SPL = 0	SPL = 1	SPL = 0	SPL = 1	-
V	GPIO selected	Hi-Z	Hi-Z / Input enabled	Hi-Z / Input enabled	Maintain previous state	Maintain previous state	Hi-Z / Internal input fixed at "0"	GPIO selected Internal input fixed at "0"	Hi-Z / Internal input fixed at "0"	GPIO selected
	USB I/O pin	Setting disabled	Setting disabled	Setting disabled		Hi-Z at transmission/ Input enabled/ Internal input fixed at "0" at reception	Hi-Z at transmission/ Input enabled/ Internal input fixed at "0" at reception	Hi-Z / Input enabled	Hi-Z / Input enabled	Hi-Z / Input enabled

*1: Oscillation is stopped at Sub timer mode, Low-speed CR timer mode, RTC mode, STOP mode, Deep standby RTC mode, and Deep standby STOP mode.

*2: Oscillation is stopped at STOP mode and Deep standby STOP mode.

*3: Maintain previous state at timer mode. GPIO selected Internal input fixed at "0" at RTC mode, STOP mode.

*4: Maintain previous state at timer mode. Hi-Z/Internal input fixed at "0" at RTC mode, STOP mode.

12. Electrical Characteristics

12.1 Absolute Maximum Ratings

Parameter	Symbol	Rating		Unit	Remarks
		Min	Max		
Power supply voltage*1, *2	V _{CC}	V _{SS} - 0.5	V _{SS} + 6.5	V	
Power supply voltage (for USB)*1, *3	USBV _{CC}	V _{SS} - 0.5	V _{SS} + 6.5	V	
Analog power supply voltage*1, *4	AV _{CC}	V _{SS} - 0.5	V _{SS} + 6.5	V	
Analog reference voltage*1, *4	AVRH	V _{SS} - 0.5	V _{SS} + 6.5	V	
Input voltage*1	V _I	V _{SS} - 0.5	V _{CC} + 0.5 (≤ 6.5V)	V	Except for USB pin
		V _{SS} - 0.5	USBV _{CC} + 0.5 (≤ 6.5 V)	V	USB pin
		V _{SS} - 0.5	V _{SS} + 6.5	V	5V tolerant
		V _{SS} - 0.5	V _{SS} + 3.63	V	5V tolerant*8
Analog pin input voltage*1	V _{IA}	V _{SS} - 0.5	AV _{CC} + 0.5 (≤ 6.5 V)	V	
Output voltage*1	V _O	V _{SS} - 0.5	V _{CC} + 0.5 (≤ 6.5 V)	V	
Clamp maximum current	I _{CLAMP}	-2	+2	mA	*9
Clamp total maximum current	Σ [I _{CLAMP}]		+20	mA	*9
"L" level maximum output current*5	I _{OL}	-	10	mA	4mA type
			20	mA	12mA type
			39	mA	P80, P81
"L" level average output current*6	I _{OLAV}	-	4	mA	4mA type
			12	mA	12mA type
			16.5	mA	P80, P81
"L" level total maximum output current	Σ I _{OL}	-	100	mA	
"L" level total average output current*7	Σ I _{OLAV}	-	50	mA	
"H" level maximum output current*5	I _{OH}	-	- 10	mA	4mA type
			- 20	mA	12mA type
			- 39	mA	P80, P81
"H" level average output current*6	I _{OHAV}	-	- 4	mA	4mA type
			- 12	mA	12mA type
			- 18	mA	P80, P81
"H" level total maximum output current	Σ I _{OH}	-	- 100	mA	
"H" level total average output current*7	Σ I _{OHAV}	-	- 50	mA	
Power consumption	P _D	-	390	mW	
Storage temperature	T _{STG}	- 55	+ 150	°C	

*1: These parameters are based on the condition that V_{SS} = AV_{SS} = 0 V.

*2: V_{CC} must not drop below V_{SS} - 0.5 V.

*3: USBV_{CC} must not drop below V_{SS} - 0.5 V.

*4: Ensure that the voltage does not exceed V_{CC} + 0.5 V, for example, when the power is turned on.

*5: The maximum output current is defined as the value of the peak current flowing through any one of the corresponding pins.

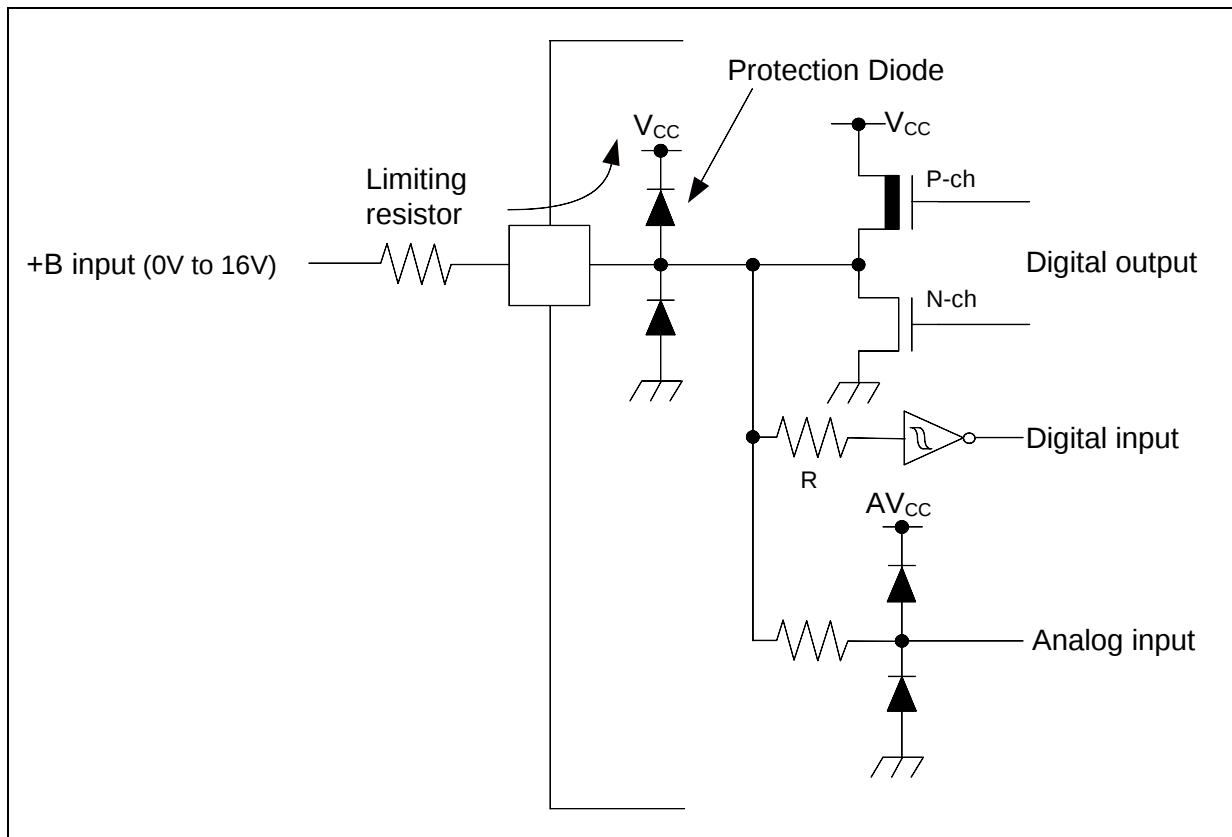
*6: The average output current is defined as the average current value flowing through any one of the corresponding pins for a 100 ms period.

*7: The total average output current is defined as the average current value flowing through all of corresponding pins for a 100 ms.

*8: V_{CC} = USBV_{CC} = AV_{CC} = AVRH = V_{SS} = AV_{SS} = AVRL = 0.0 V

*9 :

- See "List of Pin Functions" and "I/O Circuit Type" about +B input available pin.
- Use within recommended operating conditions.
- Use at DC voltage (current) the +B input.
- The +B signal should always be applied a limiting resistance placed between the +B signal and the device.
- The value of the limiting resistance should be set so that when the +B signal is applied the input current to the device pin does not exceed rated values, either instantaneously or for prolonged periods.
- Note that when the device drive current is low, such as in the low-power consumption modes, the +B input potential may pass through the protective diode and increase the potential at the VCC and AVCC pin, and this may affect other devices.
- Note that if a +B signal is input when the device power supply is off (not fixed at 0 V), the power supply is provided from the pins, so that incomplete operation may result.
- The following is a recommended circuit example (I/O equivalent circuit).



WARNING:

- Semiconductor devices may be permanently damaged by application of stress (including, without limitation, voltage, current or temperature) in excess of absolute maximum ratings.
Do not exceed any of these ratings.

12.2 Recommended Operating Conditions

(V_{SS} = AV_{SS} = 0.0V)

Parameter	Symbol	Conditions	Value		Unit	Remarks
			Min	Max		
Power supply voltage	V _{CC}	-	2.7* ⁴	5.5	V	
Power supply voltage (3V power supply) for USB	USBV _{CC}	-	3.0	3.6 (≤ V _{CC})	V	*1
			2.7	5.5 (≤ V _{CC})		*2
Analog power supply voltage	AV _{CC}	-	2.7	5.5	V	AV _{CC} = V _{CC}
Analog reference voltage	AVRH	-	2.7	AV _{CC}	V	
	AVRL	-	AV _{SS}	AV _{SS}	V	
Smoothing capacitor	C _S	-	1	10	μF	For built-in Regulator* ³
Operating temperature	T _A	-	- 40	+ 105	°C	

*1: When P81/UDP0 and P80/UDM0 pins are used as USB (UDP0, UDM0).

*2: When P81/UDP0 and P80/UDM0 pins are used as GPIO (P81, P80).

*3: See "C Pin" in "Handling Devices" for the connection of the smoothing capacitor.

*4: In between less than the minimum power supply voltage and low voltage reset/interrupt detection voltage or more, instruction execution and low voltage detection function by built-in High-speed CR(including Main PLL is used) or built-in Low-speed CR is possible to operate only.

WARNING:

- The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated under these conditions. Any use of semiconductor devices will be under their recommended operating condition. Operation under any conditions other than these conditions may adversely affect reliability of device and could result in device failure.
No warranty is made with respect to any use, operating conditions or combinations not represented on this data sheet. If you are considering application under any conditions other than listed herein, please contact sales representatives beforehand.

12.3 DC Characteristics

12.3.1 Current Rating

Parameter	Symbol (Pin name)	Conditions		Value		Unit	Remarks
				Typ*1	Max*2		
Power supply current	I _{CC}	PLL RUN mode	CPU: 60 MHz, Peripheral: 30 MHz *3 *5	29	37	mA	
			CPU: 60 MHz, Peripheral clock stops *3 *5	19	26	mA	
		High-speed CR RUN mode	CPU/ Peripheral: 4 MHz*4 *3	3.1	6.4	mA	
		Sub RUN mode	CPU/ Peripheral: 32 kHz *3 *6	170	2300	μA	
		Low-speed CR RUN mode	CPU/ Peripheral: 100 kHz *3	210	2300	μA	
	I _{CCS}	PLL SLEEP mode	Peripheral: 30 MHz *3 *5	19	26	mA	
		High-speed CR SLEEP mode	Peripheral: 4 MHz*4 *3	2.1	5.1	mA	
		Sub SLEEP mode	Peripheral: 32 kHz *3 *6	160	2200	μA	
		Low-speed CR SLEEP mode	Peripheral: 100 kHz *3	190	2200	μA	
	I _{CCH}	STOP mode	T _A = + 25°C *3	20	75	μA	
			T _A = + 105°C *3	-	1.3	mA	
	I _{CC T}	Main TIMER mode	T _A = + 25°C *3 *6	2.8	5.5	mA	
			T _A = + 105°C *3 *6	-	6.5	mA	
		Sub TIMER mode	T _A = + 25°C *3 *6	24	95	μA	
			T _A = + 105°C *3 *6	-	1.7	mA	
	I _{CCR}	RTC mode	T _A = + 25°C *3 *6	21	89	μA	
			T _A = + 105°C *3 *6	-	1.7	mA	

*1: T_A=+25°C, V_{CC}= 3.3 V

*2: T_A=+105°C, V_{CC}=5.5 V

*3: When all ports are fixed.

*4: When setting it to 4 MHz by trimming.

*5: When using the crystal oscillator of 4 MHz(Including the current consumption of the oscillation circuit)

*6: When using the crystal oscillator of 32 kHz(Including the current consumption of the oscillation circuit)

Parameter	Symbol (Pin name)	Conditions		Value		Unit	Remarks
				Typ*1	Max*2		
Power supply current	I _{CCHD}	Deep Standby STOP mode	T _A = + 25°C, When RAM is off *3	1.9	13	μA	
			T _A = + 25°C, When RAM is on(16 KB)*4 *3	4.8	17	μA	
			T _A = + 25°C, When RAM is on(32 KB) *4 *3	5.5	20	μA	
			T _A = + 105°C, When RAM is off *3	-	300	μA	
			T _A = + 105°C, When RAM is on(16 KB) *4 *3		320	μA	
			T _A = + 105°C, When RAM is on(32 KB) *4 *3		330	μA	
	I _{CCRD}	Deep Standby RTC mode	T _A = + 25°C, When RAM is off *3, *5	2.5	14	μA	
			T _A = + 25°C, When RAM is on(16 KB) *4 *3, *5	5.4	18	μA	
			T _A = + 25°C, When RAM is on(32 KB) *4 *3, *5	6.1	21	μA	
			T _A = + 105°C, When RAM is off *3, *5	-	305	μA	
			T _A = + 105°C, When RAM is on(16 KB) *4 *3, *5		325	μA	
			T _A = + 105°C, When RAM is on(32 KB) *4 *3, *5		335	μA	

*1: V_{CC} = 3.3 V

*2: V_{CC} = 5.5 V

*3: When all ports are fixed and LVD off.

*4: For more information about RAM retention area, see "Memory Map (2)" in "Memory Map".

*5: When using the crystal oscillator of 32 kHz(Including the current consumption of the oscillation circuit)

Low-Voltage Detection Current
 $(V_{CC} = 2.7V \text{ to } 5.5V, V_{SS} = 0V, T_A = -40^{\circ}C \text{ to } +105^{\circ}C)$

Parameter	Symbol (Pin name)	Conditions	Value			Unit	Remarks
			Min	Typ	Max		
Low-Voltage detection circuit (LVD) power supply current	I_{CCLVD} (VCC)	At operation	-	0.13	0.3	μA	For occurrence of reset
			-	0.13	0.3	μA	For occurrence of interrupt

Flash Memory Current
 $(V_{CC} = 2.7V \text{ to } 5.5V, V_{SS} = 0V, T_A = -40^{\circ}C \text{ to } +105^{\circ}C)$

Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
Flash memory write/erase current	$I_{CCFLASH}$ (VCC)	VCC	At ROM0 Write/Erase	-	9.9	11.8	mA	*1
			At ROM1 Write/Erase	-	9.5	11.2	mA	*1

*1: When programming or erase in flash memory, Flash Memory Write/Erase current ($I_{CCFLASH}$) is added to the Power supply current (I_{CC}).

In addition, When programming or erase in flash memory ROM0 and ROM1 at the same time, Flash Memory Write/Erase current ($I_{CCFLASH}$) of both ROM0 and ROM1 are added to the Power supply current (I_{CC}).

A/D Converter Current
 $(V_{CC} = AV_{CC} = 2.7V \text{ to } 5.5V, V_{SS} = AV_{SS} = AV_{RL} = 0V, T_A = -40^{\circ}C \text{ to } +105^{\circ}C)$

Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
Power supply current	I_{CCAD} (VCC)	AVCC	At 1unit operation	-	0.69	0.9	mA	
			At stop	-	0.6	35	μA	
Reference power supply current (AVRH)	I_{CCAVRH} (VCC)	AVRH	At 1unit operation AVRH=5.5 V	-	1.1	1.97	mA	
			At stop	-	0.2	3.4	μA	

D/A Converter Current
 $(V_{CC} = AV_{CC} = 2.7V \text{ to } 5.5V, V_{SS} = AV_{SS} = 0V, T_A = -40^{\circ}C \text{ to } +105^{\circ}C)$

Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
Power supply current*1	I_{DDA}^{*2} (VCC)	AVCC	At 1unit operation AVCC=3.3 V	250	315	380	μA	
			At 1unit operation AVCC=5.0 V	380	475	580	μA	
	I_{DSA} (VCC)		At stop	-	-	30	μA	

*1: No-load

*2: Generates the max current by the CODE about 0x200

12.3.2 Pin Characteristics

($V_{CC} = USBV_{CC} = AV_{CC} = 2.7V$ to $5.5V$, $V_{SS} = AV_{SS} = AV_{RL} = 0V$, $T_A = -40^{\circ}C$ to $+105^{\circ}C$)

Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
"H" level input voltage (hysteresis input)	V_{IHS}	CMOS hysteresis input pin, MD0, MD1	-	$V_{CC} \times 0.8$	-	$V_{CC} + 0.3$	V	
		5V tolerant input pin	-	$V_{CC} \times 0.8$	-	$V_{SS} + 5.5$	V	
"L" level input voltage (hysteresis input)	V_{ILS}	CMOS hysteresis input pin, MD0, MD1	-	$V_{SS} - 0.3$	-	$V_{CC} \times 0.2$	V	
		5V tolerant input pin	-	$V_{SS} - 0.3$	-	$V_{CC} \times 0.2$	V	
"H" level output voltage	V_{OH}	4mA type	$V_{CC} \geq 4.5V$, $I_{OH} = -4mA$	$V_{CC} - 0.5$	-	V_{CC}	V	
			$V_{CC} < 4.5V$, $I_{OH} = -2mA$					
		12mA type	$V_{CC} \geq 4.5V$, $I_{OH} = -12mA$	$V_{CC} - 0.5$	-	V_{CC}	V	
			$V_{CC} < 4.5V$, $I_{OH} = -8mA$					
		P80, P81	$USBV_{CC} \geq 4.5V$, $I_{OH} = -18.0mA$	$USBV_{CC} - 0.4$	-	$USBV_{CC}$	V	
			$USBV_{CC} < 4.5V$, $I_{OH} = -12.0mA$					
"L" level output voltage	V_{OL}	4mA type	$V_{CC} \geq 4.5V$, $I_{OL} = 4mA$	V_{SS}	-	0.4	V	
			$V_{CC} < 4.5V$, $I_{OL} = 2mA$					
		12mA type	$V_{CC} \geq 4.5V$, $I_{OL} = 12mA$	V_{SS}	-	0.4	V	
			$V_{CC} < 4.5V$, $I_{OL} = 8mA$					
		P80, P81	$USBV_{CC} \geq 4.5V$, $I_{OL} = 16.5mA$	V_{SS}	-	0.4	V	
			$USBV_{CC} < 4.5V$, $I_{OL} = 10.5mA$					
Input leak current	I_{IL}	-	-	-5	-	+5	μA	
		CEC0_0, CEC0_1, CEC1_0, CEC1_1	$V_{CC} = USBV_{CC} = AV_{CC} = AV_{RH} = V_{SS} = AV_{SS} = AV_{RL} = 0.0V$	-	-	+1.8	μA	
Pull-up resistance value	R_{PU}	Pull-up pin	$V_{CC} \geq 4.5V$	33	50	90	k Ω	
			$V_{CC} < 4.5V$	-	-	180		

Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
Input capacitance	C _{IN}	Other than VCC, USBVCC, VSS, AVCC, AVSS, AVRH, AVRL	-	-	5	15	pF	

12.4 AC Characteristics

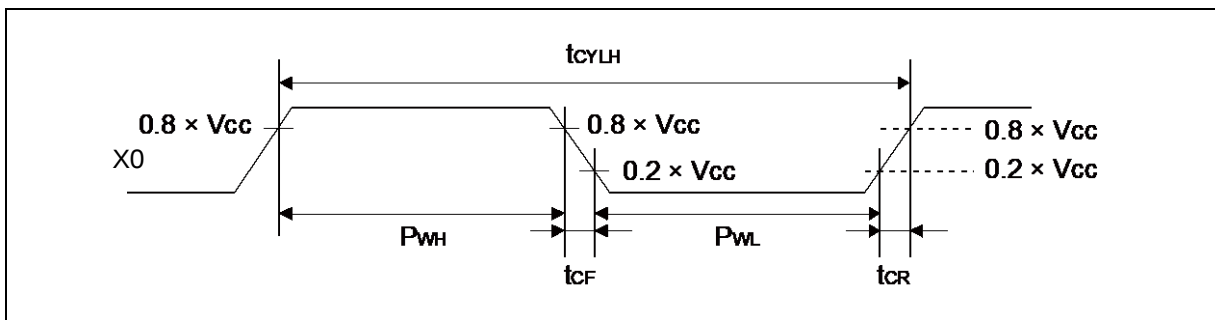
12.4.1 Main Clock Input Characteristics

($V_{CC} = 2.7V$ to $5.5V$, $V_{SS} = 0V$, $T_A = -40^{\circ}C$ to $+105^{\circ}C$)

Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Min	Max		
Input frequency	F_{CH}	X0, X1	$V_{CC} \geq 4.5V$	4	48	MHz	When crystal oscillator is connected
			$V_{CC} < 4.5V$	4	20		
			-	4	48	MHz	When using external clock
Input clock cycle	t_{CYLH}		-	20.83	250	ns	When using external clock
Input clock pulse width	-		P_{WH}/t_{CYLH} , P_{WL}/t_{CYLH}	45	55	%	When using external clock
Input clock rising time and falling time	t_{CF} , t_{CR}		-	-	5	ns	When using external clock
Internal operating clock*1 frequency	F_{CM}	-	-	-	60	MHz	Master clock
	F_{CC}	-	-	-	60	MHz	Base clock (HCLK/FCLK)
	F_{CP0}	-	-	-	32	MHz	APB0 bus clock*2
	F_{CP1}	-	-	-	32	MHz	APB1 bus clock*2
	F_{CP2}	-	-	-	32	MHz	APB2 bus clock*2
Internal operating clock*1 cycle time	t_{CYCC}	-	-	16.7	-	ns	Base clock (HCLK/FCLK)
	t_{CYCP0}	-	-	31.25	-	ns	APB0 bus clock*2
	t_{CYCP1}	-	-	31.25	-	ns	APB1 bus clock*2
	t_{CYCP2}	-	-	31.25	-	ns	APB2 bus clock*2

*1: For more information about each internal operating clock, see "CHAPTER 2-1: Clock" in "FM3 Family PERIPHERAL MANUAL".

*2: For about each APB bus which each peripheral is connected to, see "Block Diagram" in this data sheet.

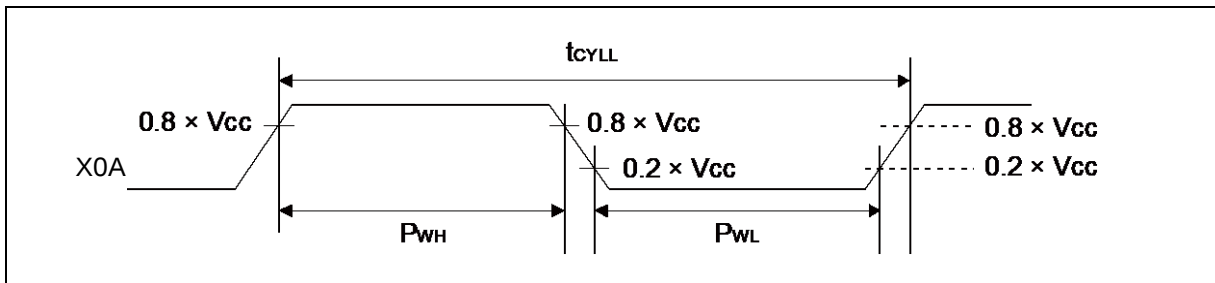


12.4.2 Sub Clock Input Characteristics

($V_{CC} = 2.7V$ to $5.5V$, $V_{SS} = 0V$, $T_A = -40^{\circ}C$ to $+105^{\circ}C$)

Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
Input frequency	$1/t_{CYLL}$	X0A, X1A	-	-	32.768	-	kHz	When crystal oscillator is connected*
			-	32	-	100	kHz	When using external clock
Input clock cycle	t_{CYLL}		-	10	-	31.25	μs	When using external clock
Input clock pulse width	-		P_{WH}/t_{CYLL} , P_{WL}/t_{CYLL}	45	-	55	%	When using external clock

*: For more information about crystal oscillator, see "Sub crystal oscillator" in "Handling Devices".



12.4.3 Built-in CR Oscillation Characteristics

Built-in High-speed CR

($V_{CC} = 2.7V$ to $5.5V$, $V_{SS} = 0V$, $T_A = -40^{\circ}C$ to $+105^{\circ}C$)

Parameter	Symbol	Conditions	Value			Unit	Remarks
			Min	Typ	Max		
Clock frequency	F_{CRH}	$T_A = +25^{\circ}C$, $3.6V < V_{CC} \leq 5.5V$	3.92	4	4.08	MHz	When trimming*1
		$T_A = 0^{\circ}C$ to $+85^{\circ}C$, $3.6V < V_{CC} \leq 5.5V$	3.9	4	4.1		
		$T_A = -40^{\circ}C$ to $+105^{\circ}C$, $3.6V < V_{CC} \leq 5.5V$	3.88	4	4.12		
		$T_A = +25^{\circ}C$, $2.7V \leq V_{CC} \leq 3.6V$	3.94	4	4.06		
		$T_A = -20^{\circ}C$ to $+85^{\circ}C$, $2.7V \leq V_{CC} \leq 3.6V$	3.92	4	4.08		When not trimming
		$T_A = -20^{\circ}C$ to $+105^{\circ}C$, $2.7V \leq V_{CC} \leq 3.6V$	3.9	4	4.1		
		$T_A = -40^{\circ}C$ to $+105^{\circ}C$, $2.7V \leq V_{CC} \leq 3.6V$	3.88	4	4.12		
		$T_A = -40^{\circ}C$ to $+105^{\circ}C$	2.8	4	5.2		
Frequency stability time	t_{CRWT}	-	-	-	30	μs	*2

*1: In the case of using the values in CR trimming area of Flash memory at shipment for frequency/temperature trimming.

*2: Frequency stable time is time to stable of the frequency of the High-speed CR clock after the trim value is set. After setting the trim value, the period when the frequency stability time passes can use the High-speed CR clock as a source clock.

Built-in Low-speed CR

($V_{CC} = 2.7V$ to $5.5V$, $V_{SS} = 0V$, $T_A = -40^{\circ}C$ to $+105^{\circ}C$)

Parameter	Symbol	Conditions	Value			Unit	Remarks
			Min	Typ	Max		
Clock frequency	F_{CRL}	-	50	100	150	kHz	

12.4.4 Operating Conditions of Main and USB PLL (In the case of using main clock for input of PLL)

 (V_{CC} = 2.7V to 5.5V, V_{SS} = 0V, TA = - 40°C to + 105°C)

Parameter	Symbol	Value			Unit	Remarks
		Min	Typ	Max		
PLL oscillation stabilization wait time* ¹ (LOCK UP time)	t _{LOCK}	100	-	-	μs	
PLL input clock frequency	F _{PLLI}	4	-	16	MHz	
PLL multiplication rate	-	5	-	37	multiplier	
PLL macro oscillation clock frequency	F _{PLLO}	75	-	150	MHz	
Main PLL clock frequency* ²	F _{CLKPLL}	-	-	60	MHz	
USB clock frequency* ³	F _{CLKSPLL}	-	-	48	MHz	After the M frequency division

*1: Time from when the PLL starts operating until the oscillation stabilizes.

*2: For more information about Main PLL clock (CLKPLL), see "CHAPTER 2-1: Clock" in "FM3 Family PERIPHERAL MANUAL".

*3: For more information about USB clock, see "CHAPTER 2-2: USB Clock Generation" in "FM3 Family PERIPHERAL MANUAL Communication Macro Part".

12.4.5 Operating Conditions of Main PLL (In the case of using built-in high-speed CR for input clock of main PLL)

($V_{CC} = 2.7V$ to $5.5V$, $V_{SS} = 0V$, $T_A = -40^{\circ}C$ to $+105^{\circ}C$)

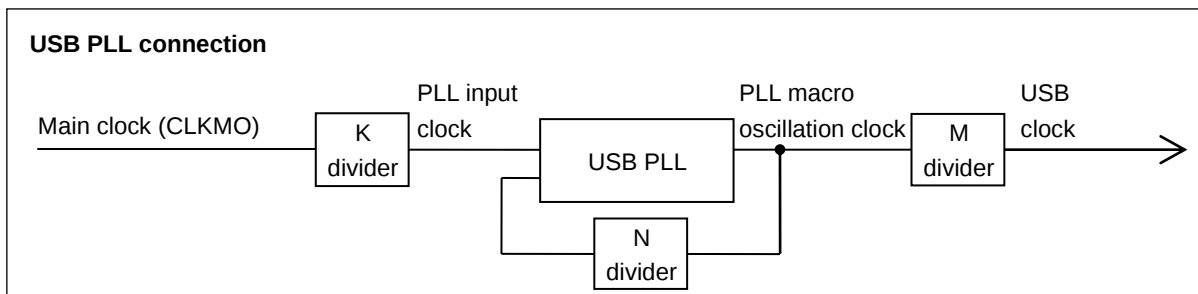
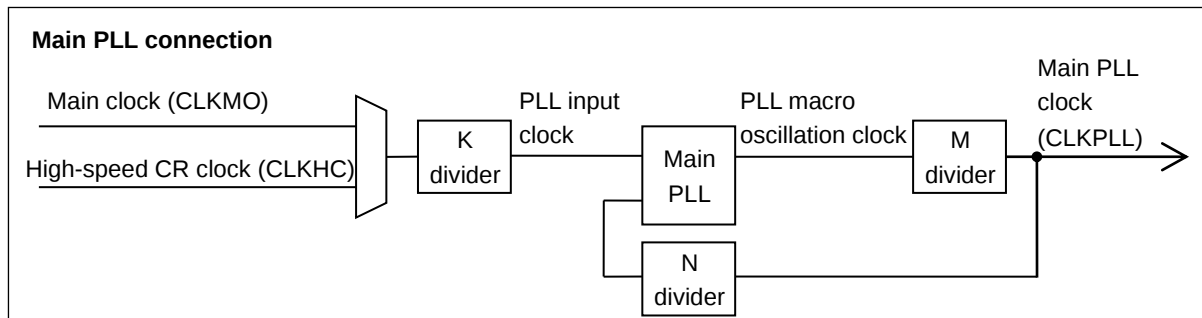
Parameter	Symbol	Value			Unit	Remarks
		Min	Typ	Max		
PLL oscillation stabilization wait time* ¹ (LOCK UP time)	t_{LOCK}	100	-	-	μs	
PLL input clock frequency	F_{PLLI}	3.8	4	4.2	MHz	
PLL multiplication rate	-	19	-	35	multiplier	
PLL macro oscillation clock frequency	F_{PLLO}	72	-	150	MHz	
Main PLL clock frequency* ²	F_{CLKPLL}	-	-	60	MHz	

*1: Time from when the PLL starts operating until the oscillation stabilizes.

*2: For more information about Main PLL clock (CLKPLL), see "CHAPTER 2-1: Clock" in "FM3 Family PERIPHERAL MANUAL".

Note:

- Make sure to input to the main PLL source clock, the high-speed CR clock (CLKHC) that the frequency/temperature has been trimmed.



12.4.6 Reset Input Characteristics

($V_{CC} = 2.7V$ to $5.5V$, $V_{SS} = 0V$, $T_A = -40^{\circ}C$ to $+105^{\circ}C$)

Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Min	Max		
Reset input time	t_{INITX}	INITX	-	500	-	ns	

12.4.7 Power-on Reset Timing

($V_{SS} = 0V$, $T_A = -40^{\circ}C$ to $+105^{\circ}C$)

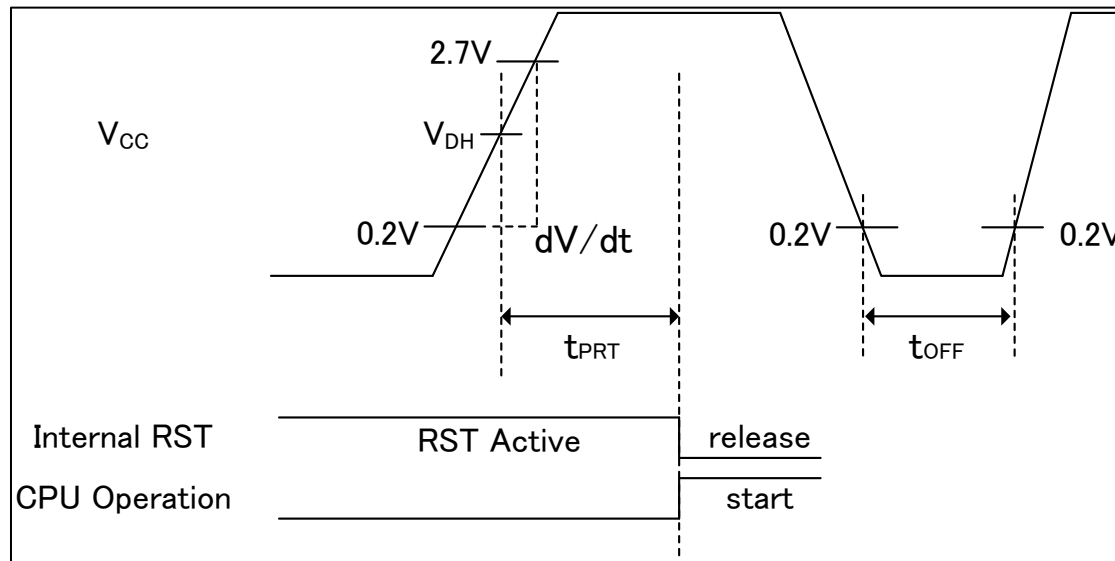
Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
Power supply shut down time	t_{OFF}	VCC	-	1		-	ms	*1
Power ramp rate	dV/dt		$V_{CC}: 0.2V$ to $2.70V$	0.9		1000	mV/ μs	*2
Time until releasing power-on reset	t_{PRT}		-	0.46		0.76	ms	

*1: V_{CC} must be held below $0.2V$ for minimum period of t_{OFF} . Improper initialization may occur if this condition is not met.

*2: This dV/dt characteristic is applied at the power-on of cold start ($t_{OFF} > 1ms$).

Note:

- If t_{OFF} cannot be satisfied designs must assert external reset (INTX) at power-up and at any brownout event per 12.4.6.



Glossary

VDH : detection voltage of Low Voltage detection reset. See "12.8. Low-Voltage Detection Characteristics"

12.4.8 External Bus Timing

External bus clock output characteristics

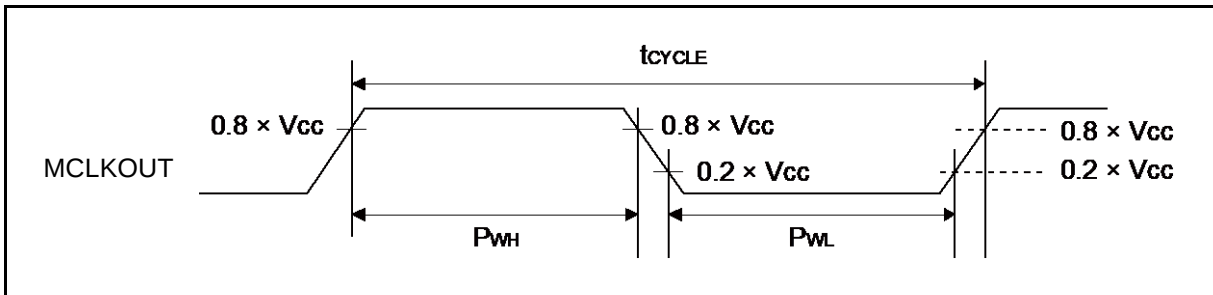
($V_{CC} = 2.7V$ to $5.5V$, $V_{SS} = 0V$, $T_A = -40^{\circ}C$ to $+105^{\circ}C$)

Parameter	Symbol	Pin name	Conditions	Value		Unit
				Min	Max	
Output frequency	t_{CYCLE}	MCLKOUT*	$V_{CC} \geq 4.5V$	-	50	MHz
			$V_{CC} < 4.5V$	-	32	MHz

*: The external bus clock (MCLKOUT) is a divided clock of HCLK.

For more information about setting of clock divider, see "CHAPTER 12: External Bus Interface" in "FM3 Family PERIPHERAL MANUAL".

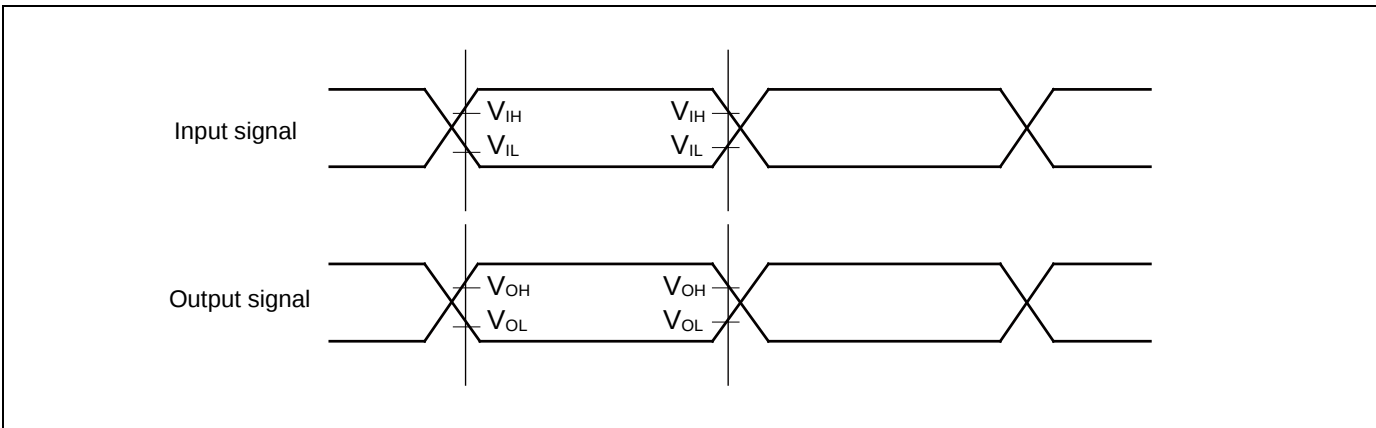
When external bus clock is not output, this characteristics does not give any effect on external bus operation.



External bus signal input/output characteristics

($V_{CC} = 2.7V$ to $5.5V$, $V_{SS} = 0V$, $T_A = -40^{\circ}C$ to $+105^{\circ}C$)

Parameter	Symbol	Conditions	Value	Unit	Remarks
Signal input characteristics	V_{IH}	-	$0.8 \times V_{CC}$	V	
	V_{IL}		$0.2 \times V_{CC}$	V	
Signal output characteristics	V_{OH}		$0.8 \times V_{CC}$	V	
	V_{OL}		$0.2 \times V_{CC}$	V	

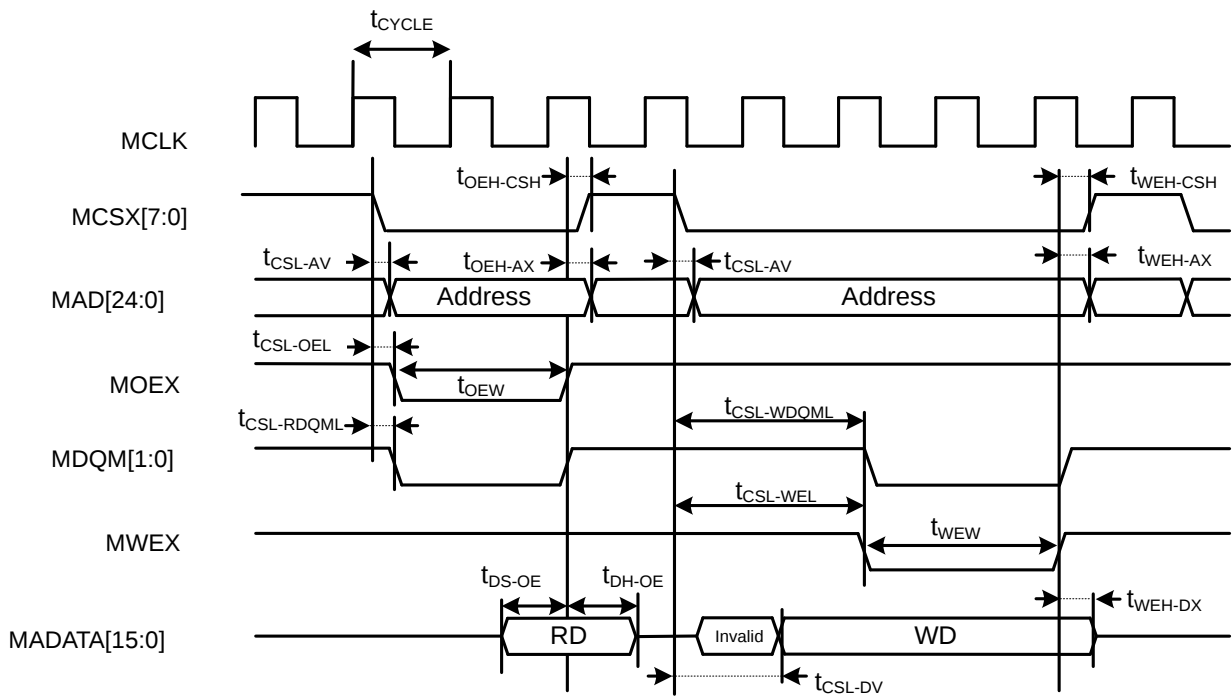


Separate Bus Access Asynchronous SRAM Mode
 $(V_{CC} = 2.7V \text{ to } 5.5V, V_{SS} = 0V, T_A = -40^{\circ}C \text{ to } +105^{\circ}C)$

Parameter	Symbol	Pin name	Conditions	Value		Unit
				Min	Max	
MOEX Min pulse width	$t_{OE\overline{W}}$	MOEX	$V_{CC} \geq 4.5V$ $V_{CC} < 4.5V$	$MCLK \times n - 3$	-	ns
MCSX $\downarrow \rightarrow$ Address output delay time	$t_{CSL - \overline{AV}}$	MCSX[7:0], MAD[24:0]	$V_{CC} \geq 4.5V$ $V_{CC} < 4.5V$	-9 -12	+9 +12	ns
MOEX $\uparrow \rightarrow$ Address hold time	$t_{OE\overline{H} - \overline{AX}}$	MOEX, MAD[24:0]	$V_{CC} \geq 4.5V$ $V_{CC} < 4.5V$	0	$MCLK \times m + 9$ $MCLK \times m + 12$	ns
MCSX $\downarrow \rightarrow$ MOEX $\downarrow$ delay time	$t_{CSL - \overline{OEL}}$	MOEX, MCSX[7:0]	$V_{CC} \geq 4.5V$ $V_{CC} < 4.5V$	$MCLK \times m - 9$ $MCLK \times m - 12$	$MCLK \times m + 9$ $MCLK \times m + 12$	ns
MOEX $\uparrow \rightarrow$ MCSX $\uparrow$ time	$t_{OE\overline{H} - \overline{CSH}}$		$V_{CC} \geq 4.5V$ $V_{CC} < 4.5V$	0	$MCLK \times m + 9$ $MCLK \times m + 12$	ns
MCSX $\downarrow \rightarrow$ MDQM $\downarrow$ delay time	$t_{CSL - \overline{RDQML}}$	MCSX, MDQM[1:0]	$V_{CC} \geq 4.5V$ $V_{CC} < 4.5V$	$MCLK \times m - 9$ $MCLK \times m - 12$	$MCLK \times m + 9$ $MCLK \times m + 12$	ns
Data set up $\rightarrow$ MOEX $\uparrow$ time	$t_{DS - \overline{OE}}$	MOEX, MADATA[15:0]	$V_{CC} \geq 4.5V$ $V_{CC} < 4.5V$	20 38	- -	ns
MOEX $\uparrow \rightarrow$ Data hold time	$t_{DH - \overline{OE}}$	MOEX, MADATA[15:0]	$V_{CC} \geq 4.5V$ $V_{CC} < 4.5V$	0	-	ns
MWEX Min pulse width	$t_{WE\overline{W}}$	MWEX	$V_{CC} \geq 4.5V$ $V_{CC} < 4.5V$	$MCLK \times n - 3$	-	ns
MWEX $\uparrow \rightarrow$ Address output delay time	$t_{WE\overline{H} - \overline{AX}}$	MWEX, MAD[24:0]	$V_{CC} \geq 4.5V$ $V_{CC} < 4.5V$	0	$MCLK \times m + 9$ $MCLK \times m + 12$	ns
MCSX $\downarrow \rightarrow$ MWEX $\downarrow$ delay time	$t_{CSL - \overline{WEL}}$	MWEX, MCSX[7:0]	$V_{CC} \geq 4.5V$ $V_{CC} < 4.5V$	$MCLK \times n - 9$ $MCLK \times n - 12$	$MCLK \times n + 9$ $MCLK \times n + 12$	ns
MWEX $\uparrow \rightarrow$ MCSX $\uparrow$ delay time	$t_{WE\overline{H} - \overline{CSH}}$		$V_{CC} \geq 4.5V$ $V_{CC} < 4.5V$	0	$MCLK \times m + 9$ $MCLK \times m + 12$	ns
MCSX $\downarrow \rightarrow$ MDQM $\downarrow$ delay time	$t_{CSL - \overline{WDQML}}$	MCSX, MDQM[1:0]	$V_{CC} \geq 4.5V$ $V_{CC} < 4.5V$	$MCLK \times n - 9$ $MCLK \times n - 12$	$MCLK \times n + 9$ $MCLK \times n + 12$	ns
MCSX $\downarrow \rightarrow$ Data output time	$t_{CSL - \overline{DV}}$	MCSX, MADATA[15:0]	$V_{CC} \geq 4.5V$ $V_{CC} < 4.5V$	$MCLK - 9$ $MCLK - 12$	$MCLK + 9$ $MCLK + 12$	ns
MWEX $\uparrow \rightarrow$ Data hold time	$t_{WE\overline{H} - \overline{DX}}$	MWEX, MADATA[15:0]	$V_{CC} \geq 4.5V$ $V_{CC} < 4.5V$	0	$MCLK \times m + 12$	ns

Note:

- When the external load capacitance $C_L = 30 \text{ pF}$ ($m = 0 \text{ to } 15, n = 1 \text{ to } 16$).

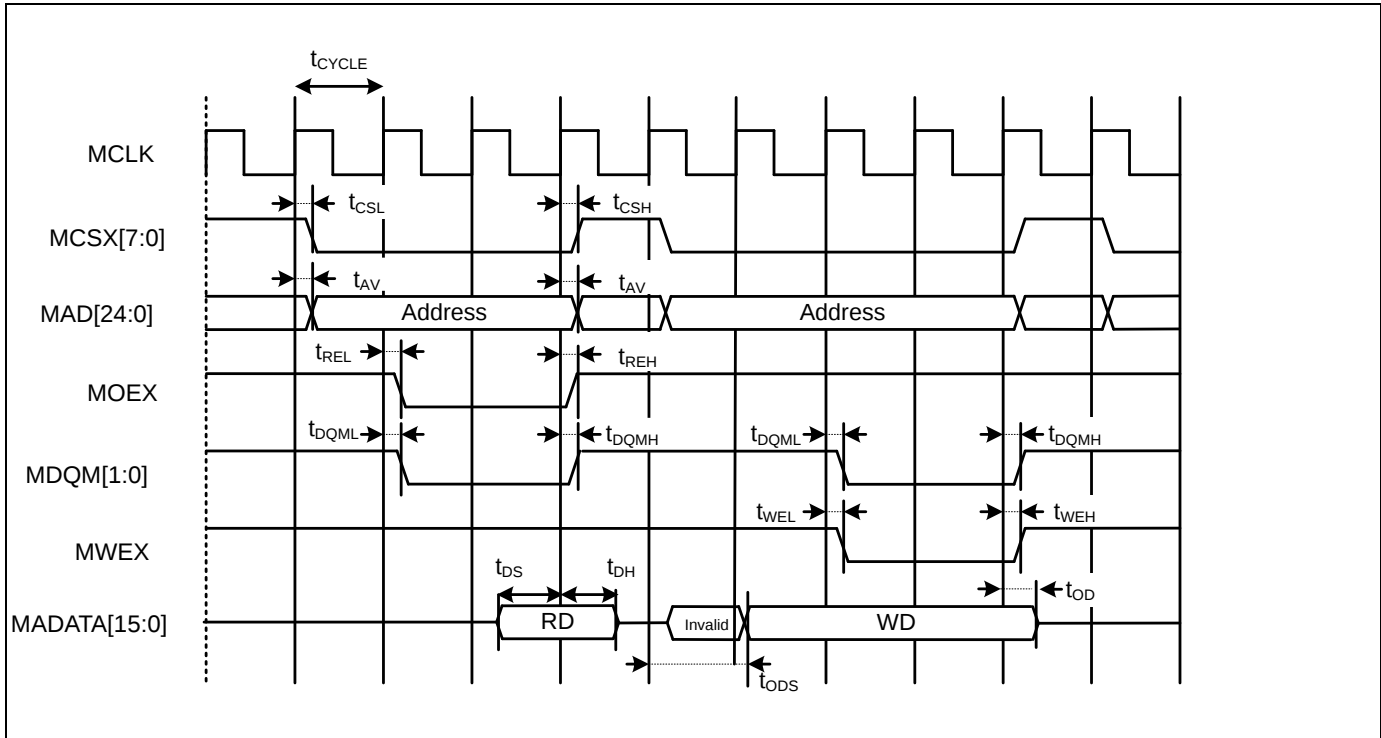


Separate Bus Access Synchronous SRAM Mode
 $(V_{CC} = 2.7V \text{ to } 5.5V, V_{SS} = 0V, T_A = -40^{\circ}C \text{ to } +105^{\circ}C)$

Parameter	Symbol	Pin name	Conditions	Value		Unit
				Min	Max	
Address delay time	t _{AV}	MCLK, MAD[24:0]	V _{CC} ≥ 4.5 V V _{CC} < 4.5 V	1	12	ns
MCSX delay time	t _{CSL}	MCLK, MCSX[7:0]	V _{CC} ≥ 4.5 V	1	9	ns
			V _{CC} < 4.5 V		12	
	t _{CSH}		V _{CC} ≥ 4.5 V	1	9	ns
			V _{CC} < 4.5 V		12	
MOEX delay time	t _{REL}	MCLK, MOEX	V _{CC} ≥ 4.5 V	1	9	ns
			V _{CC} < 4.5 V		12	
	t _{REH}		V _{CC} ≥ 4.5 V	1	9	ns
			V _{CC} < 4.5 V		12	
Data set up → MCLK ↑ time	t _{DS}	MCLK, MADATA[15:0]	V _{CC} ≥ 4.5 V V _{CC} < 4.5 V	19 37	-	ns
MCLK ↑ → Data hold time	t _{DH}	MCLK, MADATA[15:0]	V _{CC} ≥ 4.5 V V _{CC} < 4.5 V	0	-	ns
MWEX delay time	t _{WEL}	MCLK, MWEX	V _{CC} ≥ 4.5 V	1	9	ns
			V _{CC} < 4.5 V		12	
	t _{WEH}		V _{CC} ≥ 4.5 V	1	9	ns
			V _{CC} < 4.5 V		12	
MDQM[1:0] delay time	t _{DQML}	MCLK, MDQM[1:0]	V _{CC} ≥ 4.5 V	1	9	ns
			V _{CC} < 4.5 V		12	
	t _{DQMH}		V _{CC} ≥ 4.5 V	1	9	ns
			V _{CC} < 4.5 V		12	
MCLK ↑ → Data output time	t _{ODS}	MCLK, MADATA[15:0]	V _{CC} ≥ 4.5 V V _{CC} < 4.5 V	MCLK+1	MCLK+18 MCLK+24	ns
MCLK ↑ → Data hold time	t _{OD}	MCLK, MADATA[15:0]	V _{CC} ≥ 4.5 V V _{CC} < 4.5 V	1	18 24	ns

Note:

- When the external load capacitance $C_L = 30 \text{ pF}$.

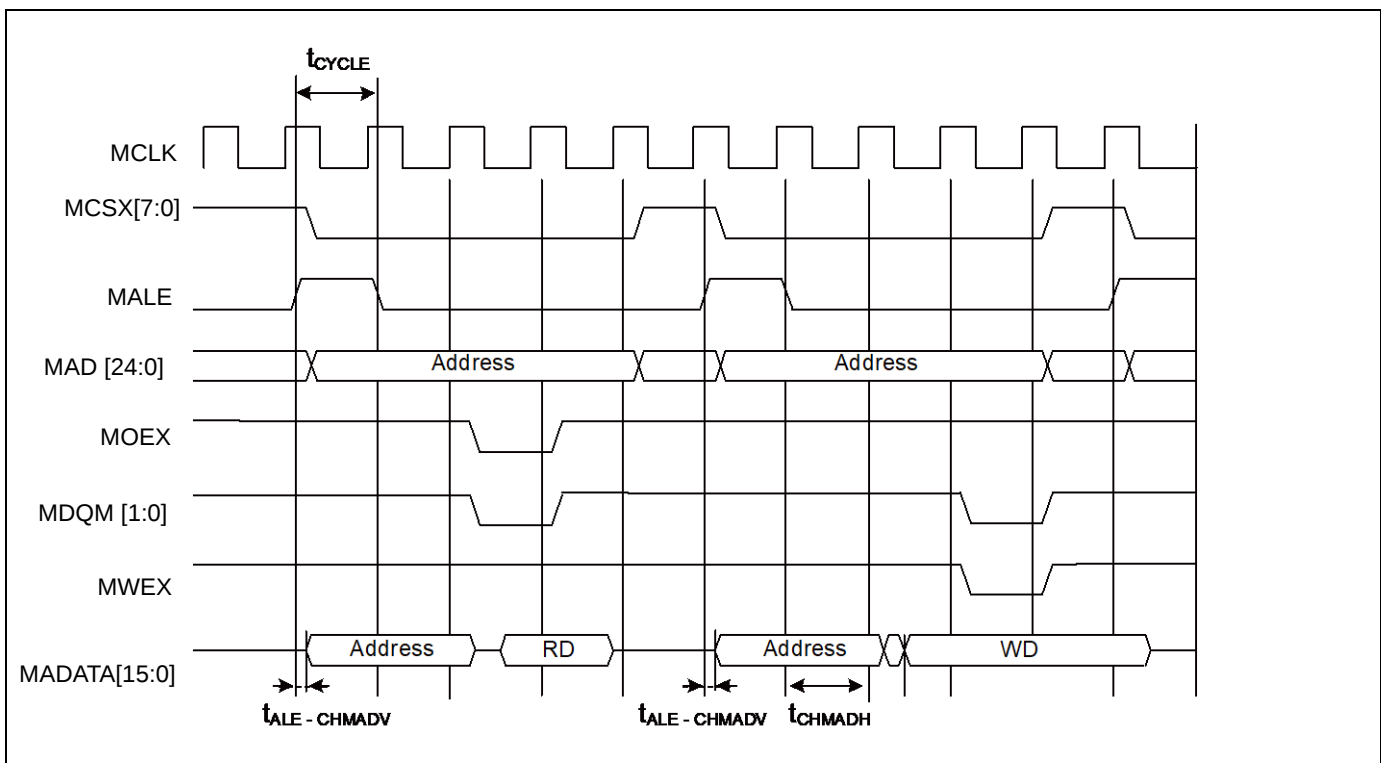


Multiplexed Bus Access Asynchronous SRAM Mode
 $(V_{CC} = 2.7V \text{ to } 5.5V, V_{SS} = 0V, T_A = -40^{\circ}C \text{ to } +105^{\circ}C)$

Parameter	Symbol	Pin name	Conditions	Value		Unit
				Min	Max	
Multiplexed address delay time	$t_{ALE-CHMADV}$	MALE, MADATA[15:0]	$V_{CC} \geq 4.5V$	0	+10	ns
			$V_{CC} < 4.5V$		+20	
Multiplexed address hold time	t_{CHMADH}	MALE, MADATA[15:0]	$V_{CC} \geq 4.5V$	$MCLK \times n + 0$	$MCLK \times n + 12$	ns
			$V_{CC} < 4.5V$	$MCLK \times n + 0$	$MCLK \times n + 20$	

Note:

- When the external load capacitance $C_L = 30 \text{ pF}$ ($m = 0 \text{ to } 15, n = 1 \text{ to } 16$).

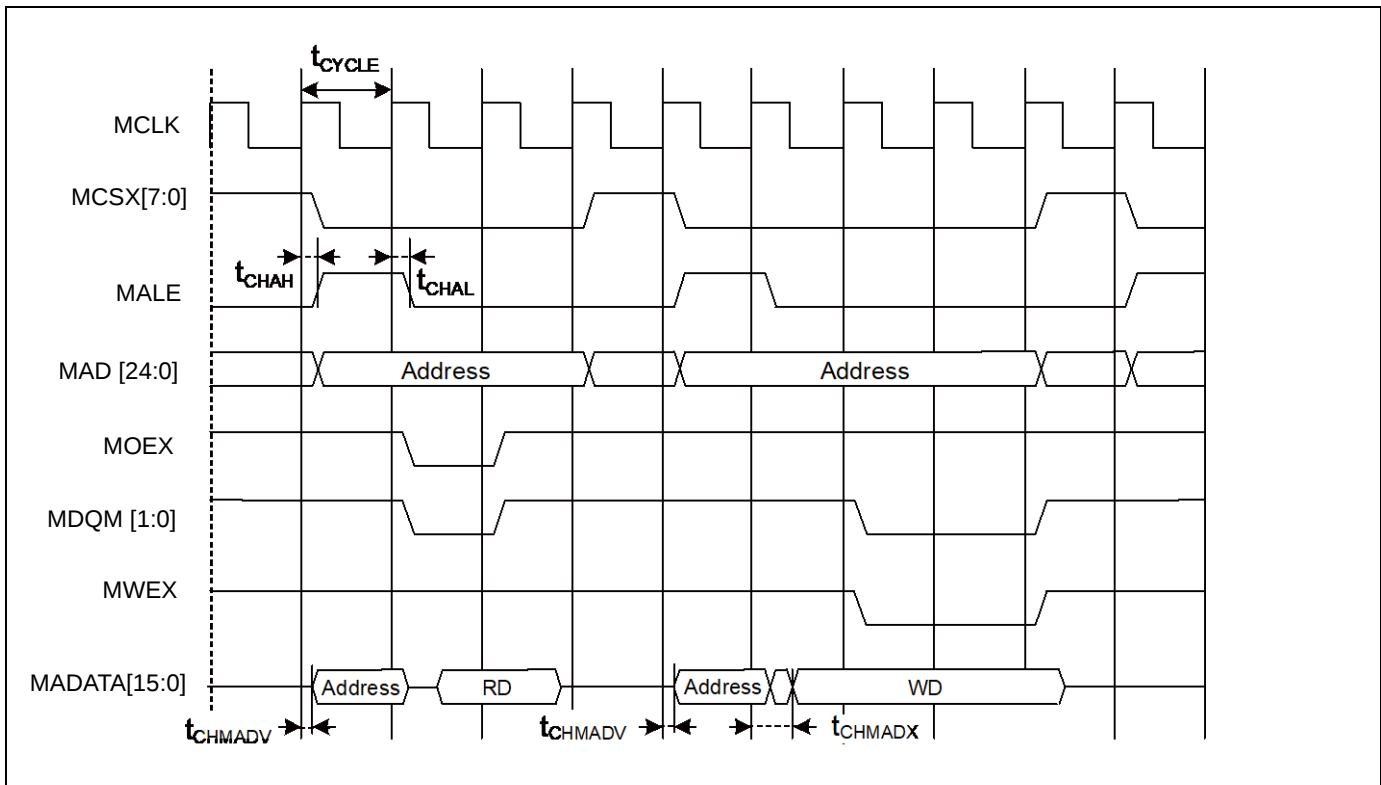


Multiplexed Bus Access Synchronous SRAM Mode
 $(V_{CC} = 2.7V \text{ to } 5.5V, V_{SS} = 0V, T_A = -40^{\circ}C \text{ to } +105^{\circ}C)$

Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Min	Max		
MALE delay time	t _{CHAL}	MCLK, ALE	V _{CC} ≥ 4.5 V	1	9	ns	
			V _{CC} < 4.5 V		12	ns	
	t _{CHAH}		V _{CC} ≥ 4.5 V	1	9	ns	
			V _{CC} < 4.5 V		12	ns	
MCLK ↑ → Multiplexed Address delay time	t _{CHMADV}	MCLK, MADATA[15:0]	V _{CC} ≥ 4.5 V	1	t _{OD}	ns	
			V _{CC} < 4.5 V				
MCLK ↑ → Multiplexed Data output time	t _{CHMADX}		V _{CC} ≥ 4.5 V	1	t _{OD}	ns	
			V _{CC} < 4.5 V				

Note:

- When the external load capacitance $C_L = 30 \text{ pF}$.



NAND Flash Memory Mode

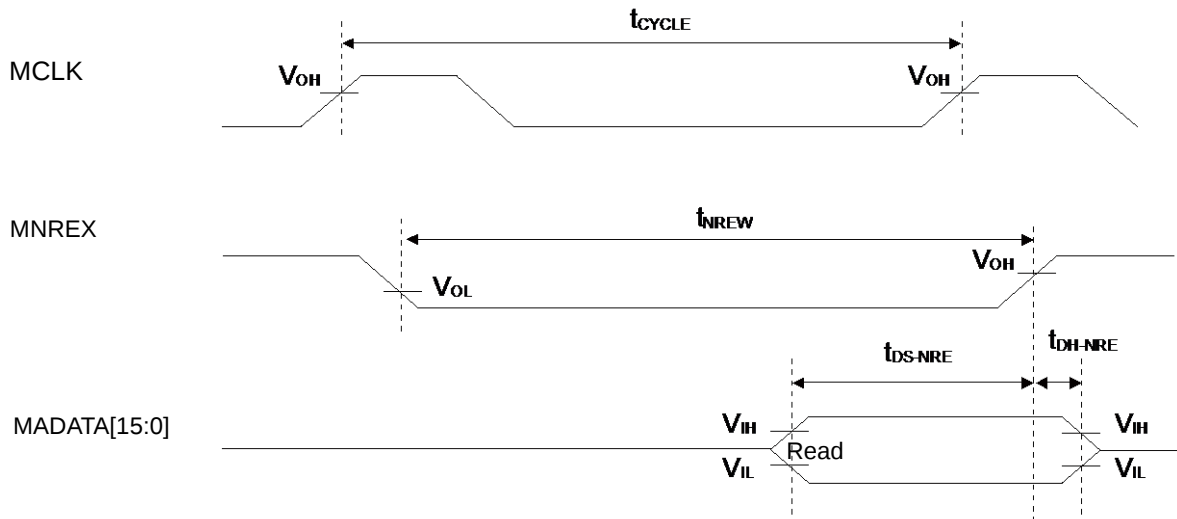
 ($V_{CC} = 2.7V$ to $5.5V$, $V_{SS} = 0V$, $T_A = -40^{\circ}C$ to $+105^{\circ}C$)

Parameter	Symbol	Pin name	Conditions	Value		Unit
				Min	Max	
MNREX Min pulse width	t_{NREW}	MNREX	$V_{CC} \geq 4.5V$ $V_{CC} < 4.5V$	$MCLK \times n - 3$	-	ns
Data setup $\rightarrow$ MNREX $\uparrow$ time	$t_{DS - NRE}$	MNREX, MADATA[15:0]	$V_{CC} \geq 4.5V$ $V_{CC} < 4.5V$	20 38	- -	ns
MNREX $\uparrow \rightarrow$ Data hold time	$t_{DH - NRE}$	MNREX, MADATA[15:0]	$V_{CC} \geq 4.5V$ $V_{CC} < 4.5V$	0	-	ns
MNALE $\uparrow \rightarrow$ MNWEX delay time	$t_{ALEH - NWEL}$	MNALE, MNWEX	$V_{CC} \geq 4.5V$ $V_{CC} < 4.5V$	$MCLK \times m - 9$ $MCLK \times m - 12$	$MCLK \times m + 9$ $MCLK \times m + 12$	ns
MNALE $\downarrow \rightarrow$ MNWEX delay time	$t_{ALEL - NWEL}$	MNALE, MNWEX	$V_{CC} \geq 4.5V$ $V_{CC} < 4.5V$	$MCLK \times m - 9$ $MCLK \times m - 12$	$MCLK \times m + 9$ $MCLK \times m + 12$	ns
MNCLE $\uparrow \rightarrow$ MNWEX delay time	$t_{CLEH - NWEL}$	MNCLE, MNWEX	$V_{CC} \geq 4.5V$ $V_{CC} < 4.5V$	$MCLK \times m - 9$ $MCLK \times m - 12$	$MCLK \times m + 9$ $MCLK \times m + 12$	ns
MNWEX $\uparrow \rightarrow$ MNCLE delay time	$t_{NWEH - CLEL}$	MNCLE, MNWEX	$V_{CC} \geq 4.5V$ $V_{CC} < 4.5V$	0	$MCLK \times m + 9$ $MCLK \times m + 12$	ns
MNWEX Min pulse width	t_{NWEW}	MNWEX	$V_{CC} \geq 4.5V$ $V_{CC} < 4.5V$	$MCLK \times n - 3$	-	ns
MNWEX $\downarrow \rightarrow$ Data output time	$t_{NWEL - DV}$	MNWEX, MADATA[15:0]	$V_{CC} \geq 4.5V$ $V_{CC} < 4.5V$	- 9 -12	+ 9 +12	ns
MNWEX $\uparrow \rightarrow$ Data hold time	$t_{NWEH - DX}$	MNWEX, MADATA[15:0]	$V_{CC} \geq 4.5V$ $V_{CC} < 4.5V$	0	$MCLK \times m + 11$ $MCLK \times m + 12$	ns

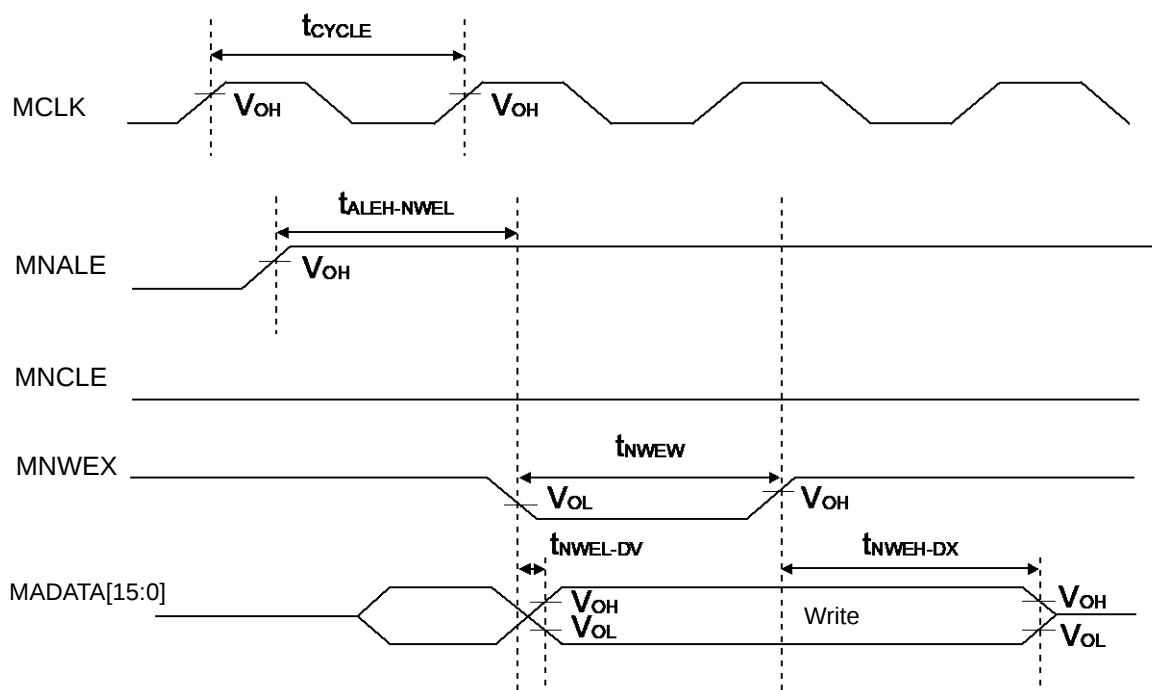
Note:

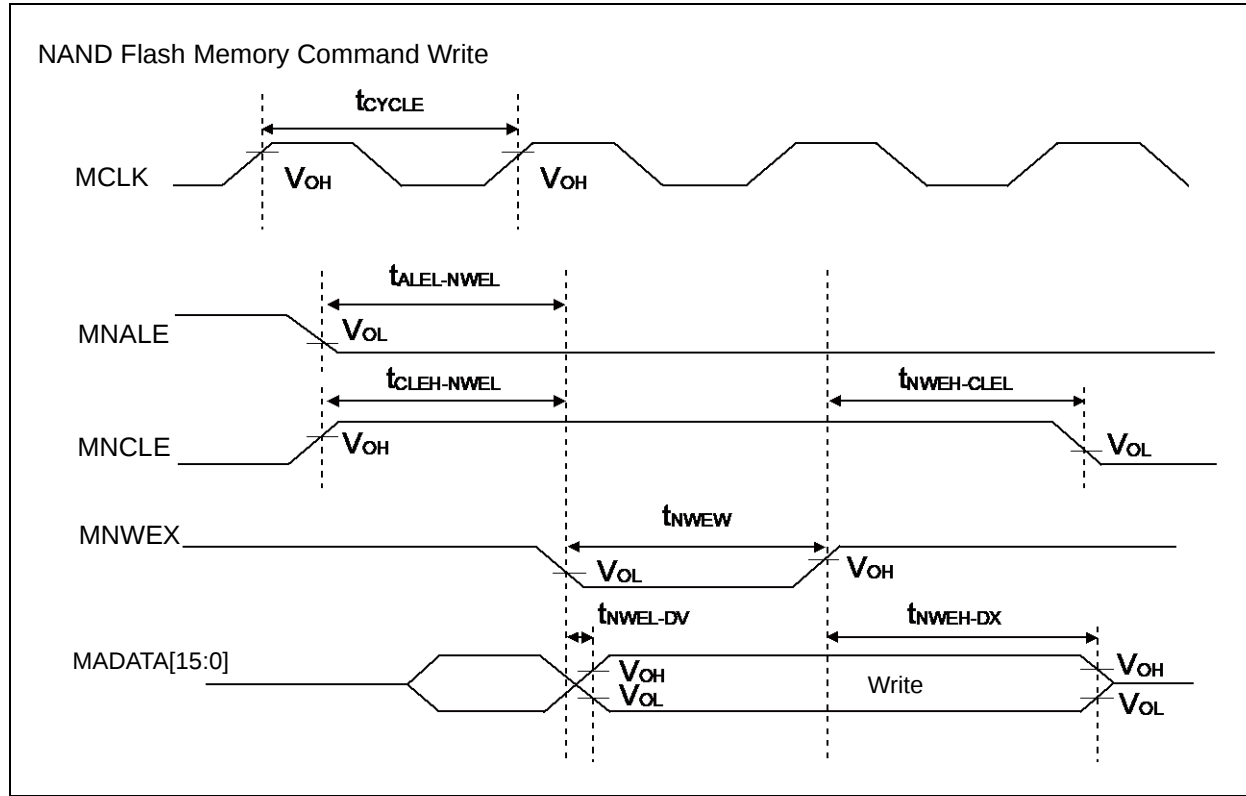
- When the external load capacitance $C_L = 30 pF$ ($m=0$ to 15 , $n=1$ to 16).

NAND Flash Memory Read



NAND Flash Memory Address Write



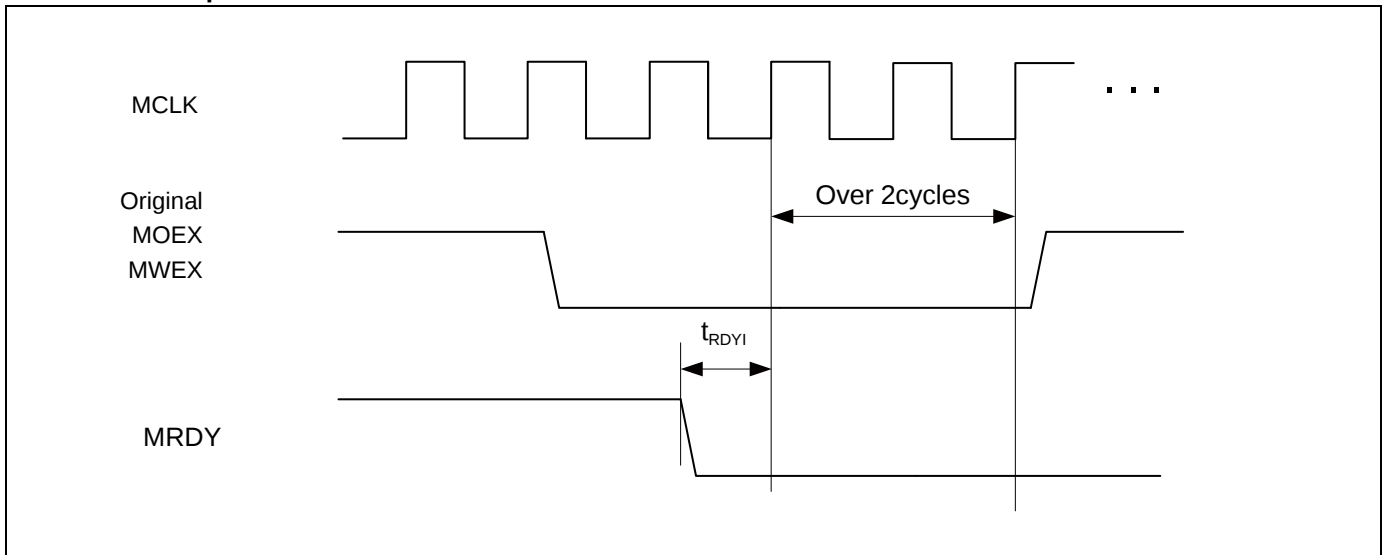


External Ready Input Timing

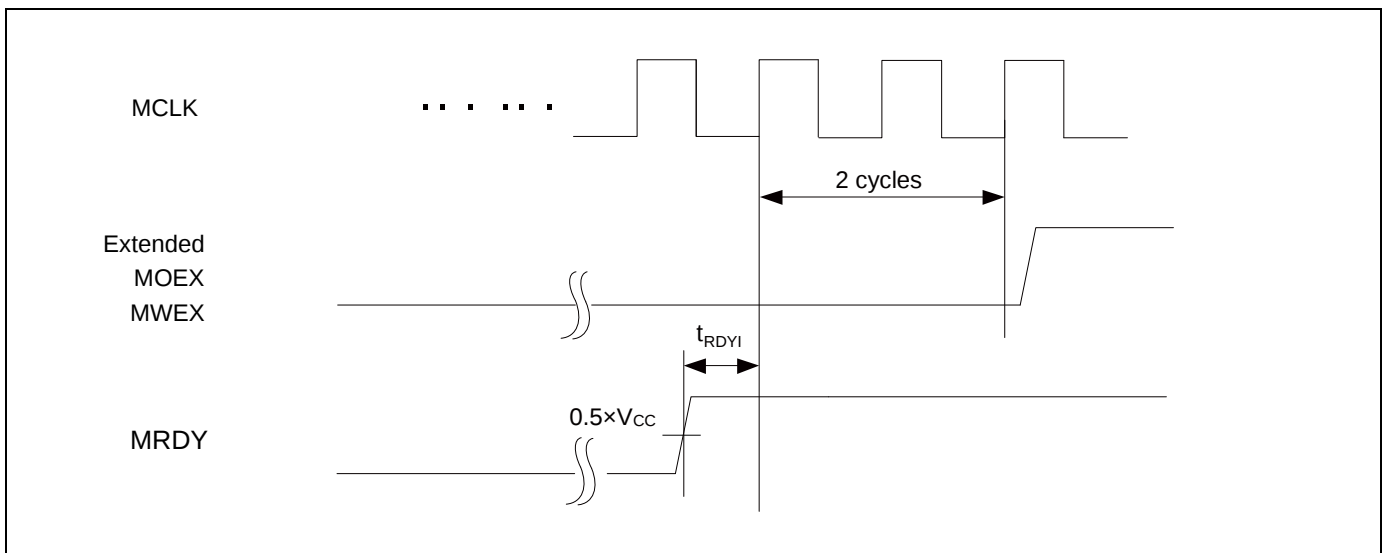
($V_{CC} = 2.7V$ to $5.5V$, $V_{SS} = 0V$, $T_A = -40^{\circ}C$ to $+105^{\circ}C$)

Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Min	Max		
MCLK ↑ MRDY input setup time	t_{RDYI}	MCLK, MRDY	$V_{CC} \geq 4.5 V$	19	-	ns	
			$V_{CC} < 4.5 V$	37			

When RDY is input



When RDY is released

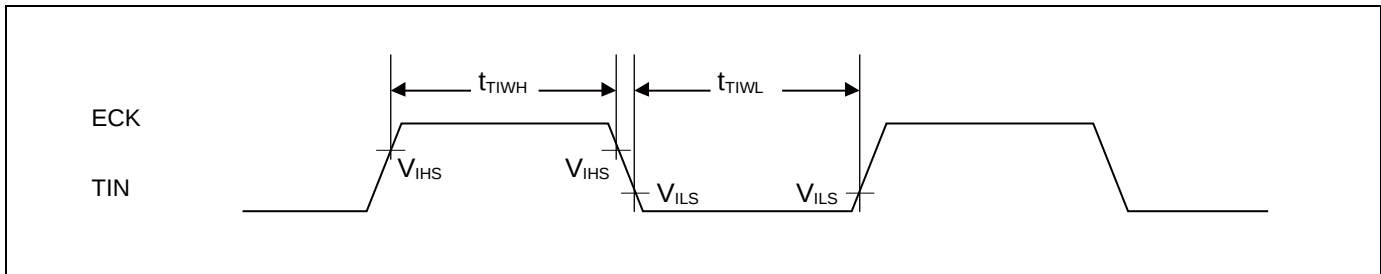


12.4.9 Base Timer Input Timing

Timer input timing

($V_{CC} = 2.7V$ to $5.5V$, $V_{SS} = 0V$, $T_A = -40^{\circ}C$ to $+105^{\circ}C$)

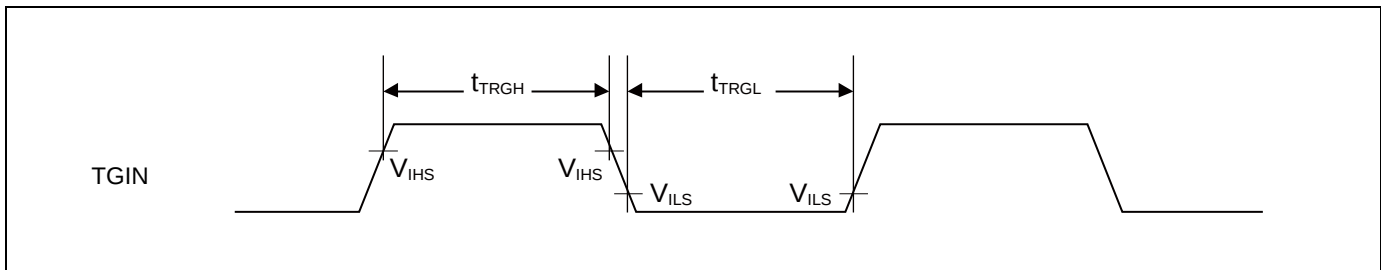
Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Min	Max		
Input pulse width	t_{TIWH} , t_{TIWL}	TIOAn/TIOBn (when using as ECK, TIN)	-	$2t_{CYCP}$	-	ns	



Trigger input timing

($V_{CC} = 2.7V$ to $5.5V$, $V_{SS} = 0V$, $T_A = -40^{\circ}C$ to $+105^{\circ}C$)

Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Min	Max		
Input pulse width	t_{TRGH} , t_{TRGL}	TIOAn/TIOBn (when using as TGIN)	-	$2t_{CYCP}$	-	ns	



Note:

- t_{CYCP} indicates the APB bus clock cycle time.
About the APB bus number which the Base Timer is connected to, see "Block Diagram" in this data sheet.

12.4.10 CSIO/UART Timing

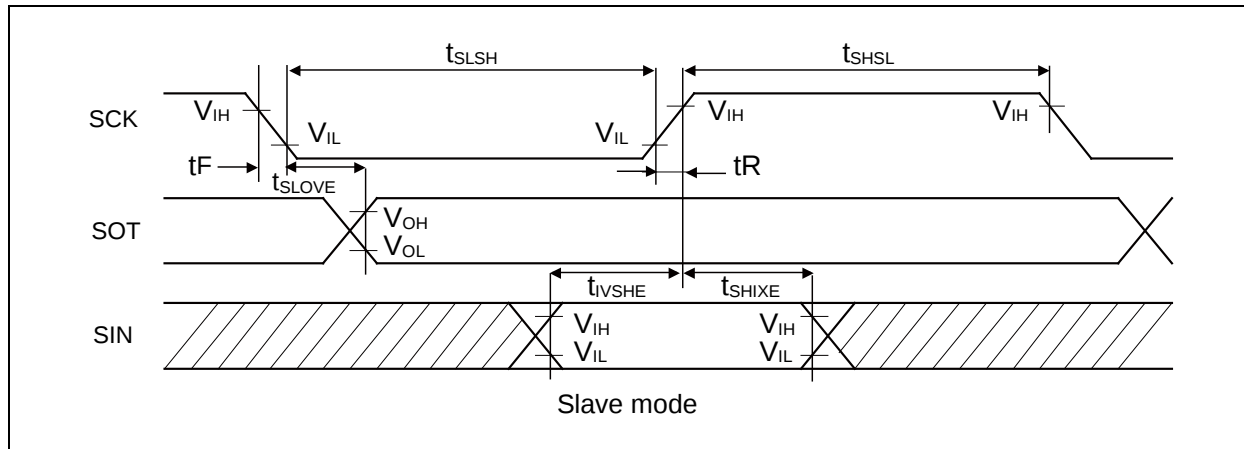
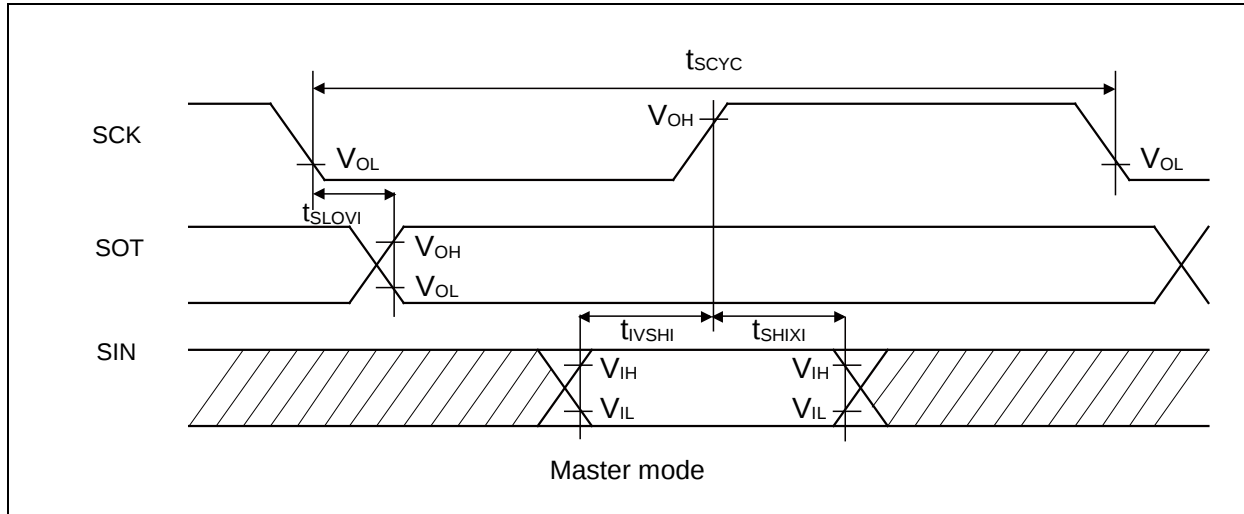
CSIO (SPI = 0, SCINV = 0)

($V_{CC} = 2.7V$ to $5.5V$, $V_{SS} = 0V$, $T_A = -40^{\circ}C$ to $+105^{\circ}C$)

Parameter	Symbol	Pin name	Conditions	$V_{CC} < 4.5 V$		$V_{CC} \geq 4.5 V$		Unit
				Min	Max	Min	Max	
Baud Rate	-	-	-	-	8	-	8	Mbps
Serial clock cycle time	t_{SCYC}	SCKx	Master mode	$4t_{CYCP}$	-	$4t_{CYCP}$	-	ns
SCK ↓ → SOT delay time	t_{SLOVI}	SCKx, SOTx		- 30	+ 30	- 20	+ 20	ns
SIN → SCK ↑ setup time	t_{IVSHI}	SCKx, SINx		50	-	30	-	ns
SCK ↑ → SIN hold time	t_{SHIXI}	SCKx, SINx		0	-	0	-	ns
Serial clock "L" pulse width	t_{SLSH}	SCKx		$2t_{CYCP} - 10$	-	$2t_{CYCP} - 10$	-	ns
Serial clock "H" pulse width	t_{SHSL}	SCKx	Slave mode	$t_{CYCP} + 10$	-	$t_{CYCP} + 10$	-	ns
SCK ↓ → SOT delay time	t_{SLOVE}	SCKx, SOTx		-	50	-	33	ns
SIN → SCK ↑ setup time	t_{IVSHE}	SCKx, SINx		10	-	10	-	ns
SCK ↑ → SIN hold time	t_{SHIXE}	SCKx, SINx		20	-	20	-	ns
SCK falling time	t_F	SCKx		-	5	-	5	ns
SCK rising time	t_R	SCKx		-	5	-	5	ns

Notes:

- The above characteristics apply to CLK synchronous mode.
- t_{CYCP} indicates the APB bus clock cycle time.
- About the APB bus number which Multi-function Serial is connected to, see "Block Diagram" in this data sheet.
- These characteristics only guarantee the same relocate port number.
For example, the combination of SCKx_0 and SOTx_1 is not guaranteed.
- When the external load capacitance $C_L = 30 pF$.

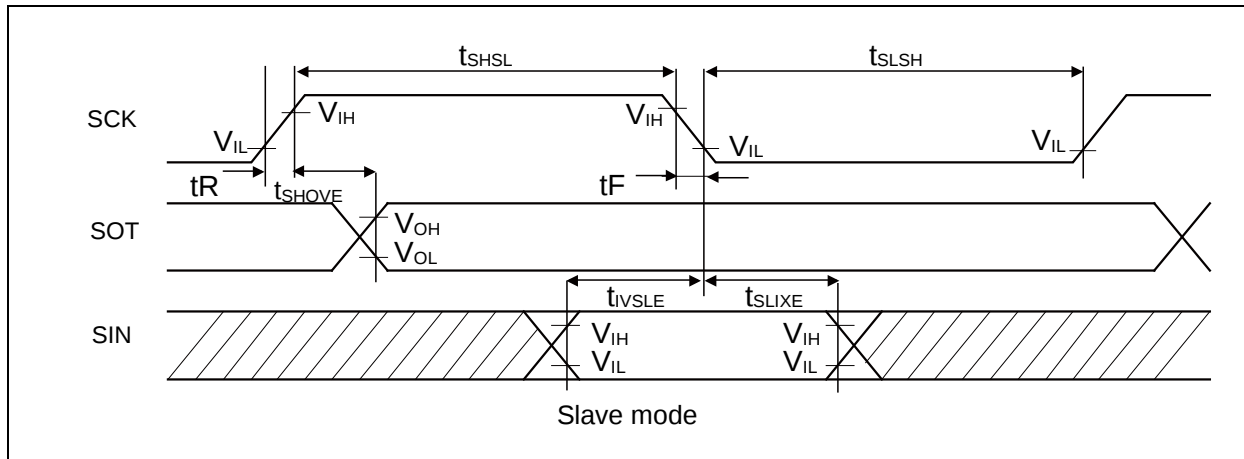
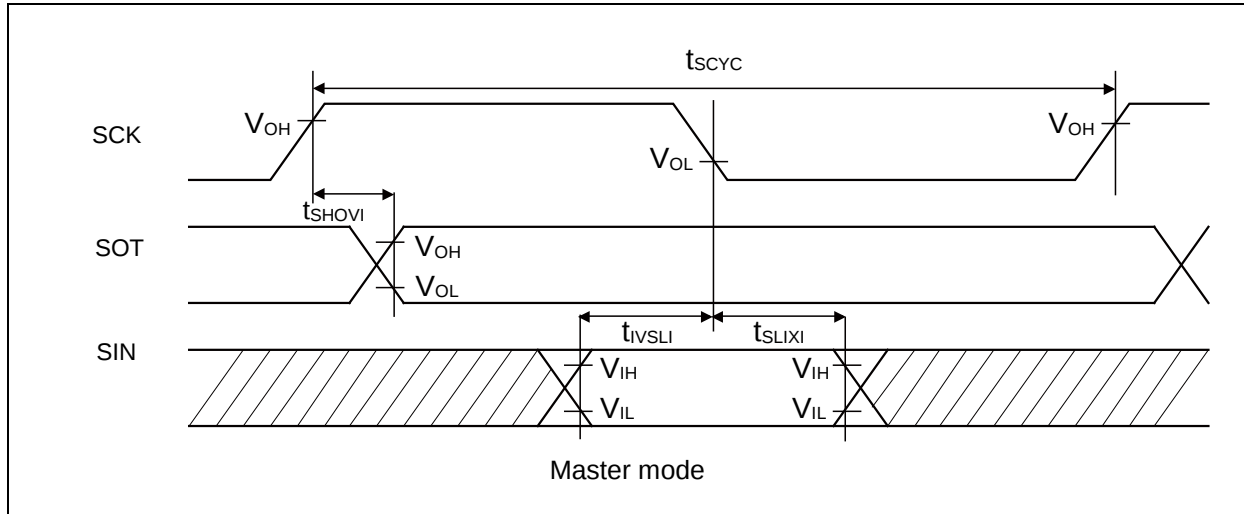


CSIO (SPI = 0, SCINV = 1)
 $(V_{CC} = 2.7V \text{ to } 5.5V, V_{SS} = 0V, T_A = -40^{\circ}C \text{ to } +105^{\circ}C)$

Parameter	Symbol	Pin name	Conditions	$V_{CC} < 4.5 V$		$V_{CC} \geq 4.5 V$		Unit
				Min	Max	Min	Max	
Baud Rate	-	-	-	-	8	-	8	Mbps
Serial clock cycle time	t_{SCYC}	SCKx	Master mode	$4t_{CYCP}$	-	$4t_{CYCP}$	-	ns
SCK $\uparrow \rightarrow$ SOT delay time	t_{SHOVI}	SCKx, SOTx		- 30	+ 30	- 20	+ 20	ns
SIN $\rightarrow$ SCK $\downarrow$ setup time	t_{IVSLI}	SCKx, SINx		50	-	30	-	ns
SCK $\downarrow \rightarrow$ SIN hold time	t_{SLIXI}	SCKx, SINx		0	-	0	-	ns
Serial clock "L" pulse width	t_{SLSH}	SCKx	Slave mode	$2t_{CYCP} - 10$	-	$2t_{CYCP} - 10$	-	ns
Serial clock "H" pulse width	t_{SHSL}	SCKx		$t_{CYCP} + 10$	-	$t_{CYCP} + 10$	-	ns
SCK $\uparrow \rightarrow$ SOT delay time	t_{SHOVE}	SCKx, SOTx		-	50	-	33	ns
SIN $\rightarrow$ SCK $\downarrow$ setup time	t_{IVSLE}	SCKx, SINx		10	-	10	-	ns
SCK $\downarrow \rightarrow$ SIN hold time	t_{SLIXE}	SCKx, SINx		20	-	20	-	ns
SCK falling time	t_F	SCKx		-	5	-	5	ns
SCK rising time	t_R	SCKx		-	5	-	5	ns

Notes:

- The above characteristics apply to CLK synchronous mode.
- t_{CYCP} indicates the APB bus clock cycle time.
- About the APB bus number which Multi-function Serial is connected to, see "Block Diagram" in this data sheet.
- These characteristics only guarantee the same relocate port number.
For example, the combination of SCKx_0 and SOTx_1 is not guaranteed.
- When the external load capacitance $C_L = 30 \text{ pF}$.

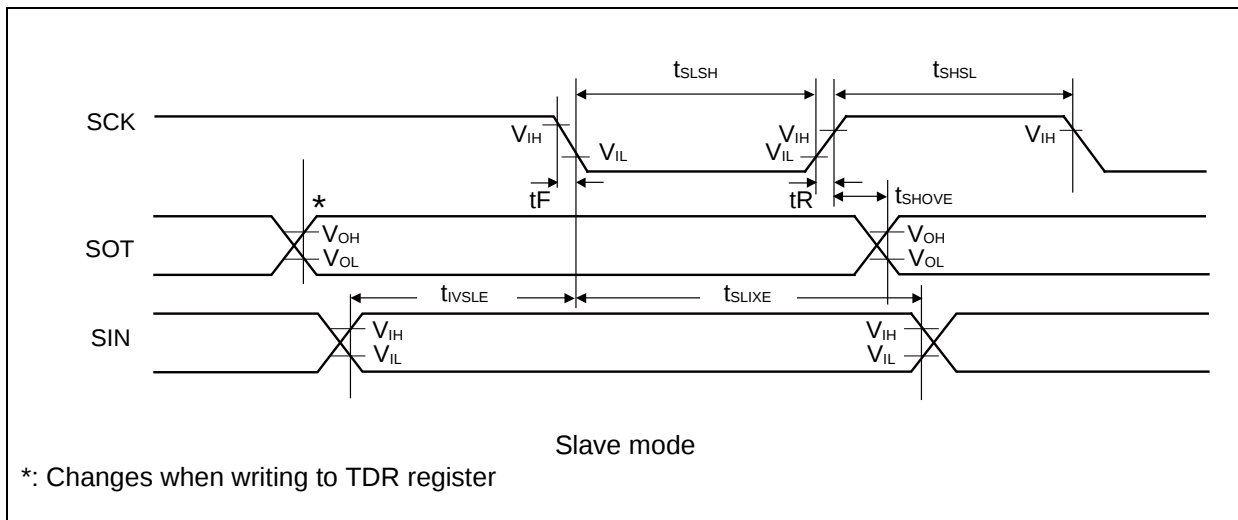
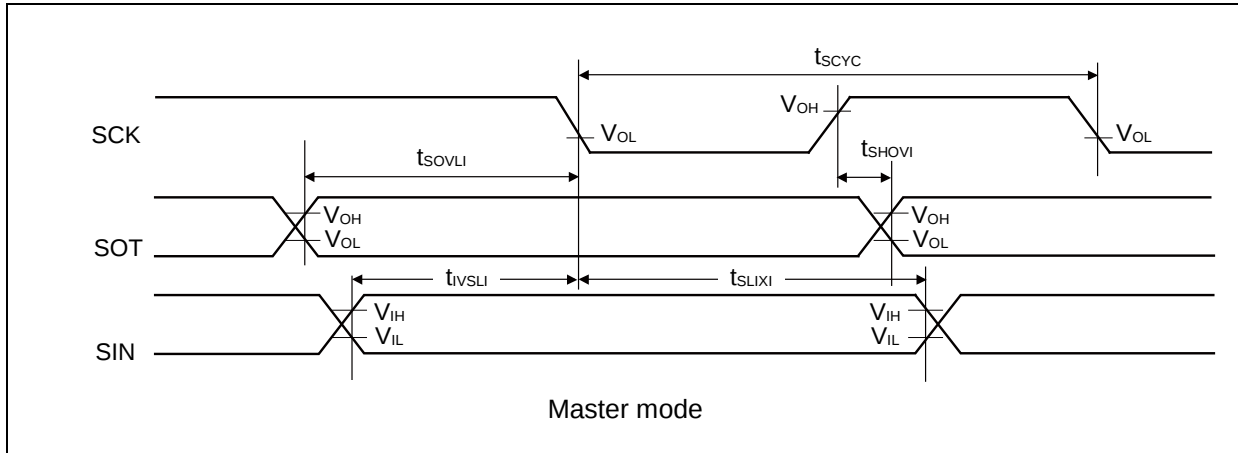


CSIO (SPI = 1, SCINV = 0)
 $(V_{CC} = 2.7V \text{ to } 5.5V, V_{SS} = 0V, T_A = -40^{\circ}C \text{ to } +105^{\circ}C)$

Parameter	Symbol	Pin name	Conditions	$V_{CC} < 4.5 V$		$V_{CC} \geq 4.5 V$		Unit
				Min	Max	Min	Max	
Baud Rate	-	-	-	-	8	-	8	Mbps
Serial clock cycle time	t_{SCYC}	SCKx	Master mode	$4t_{CYCP}$	-	$4t_{CYCP}$	-	ns
SCK $\uparrow \rightarrow$ SOT delay time	t_{SHOVI}	SCKx, SOTx		- 30	+ 30	- 20	+ 20	ns
SIN $\rightarrow$ SCK $\downarrow$ setup time	t_{IVSLI}	SCKx, SINx		50	-	30	-	ns
SCK $\downarrow \rightarrow$ SIN hold time	t_{SLIXI}	SCKx, SINx		0	-	0	-	ns
SOT $\rightarrow$ SCK $\downarrow$ delay time	t_{SOVLI}	SCKx, SOTx		$2t_{CYCP} - 30$	-	$2t_{CYCP} - 30$	-	ns
Serial clock "L" pulse width	t_{SLSH}	SCKx		$2t_{CYCP} - 10$	-	$2t_{CYCP} - 10$	-	ns
Serial clock "H" pulse width	t_{SHSL}	SCKx	Slave mode	$t_{CYCP} + 10$	-	$t_{CYCP} + 10$	-	ns
SCK $\uparrow \rightarrow$ SOT delay time	t_{SHOVE}	SCKx, SOTx		-	50	-	33	ns
SIN $\rightarrow$ SCK $\downarrow$ setup time	t_{IVSLE}	SCKx, SINx		10	-	10	-	ns
SCK $\downarrow \rightarrow$ SIN hold time	t_{SLIXE}	SCKx, SINx		20	-	20	-	ns
SCK falling time	t_F	SCKx		-	5	-	5	ns
SCK rising time	t_R	SCKx		-	5	-	5	ns

Notes:

- The above characteristics apply to CLK synchronous mode.
- t_{CYCP} indicates the APB bus clock cycle time.
- About the APB bus number which Multi-function Serial is connected to, see "Block Diagram" in this data sheet.
- These characteristics only guarantee the same relocate port number.
For example, the combination of SCKx_0 and SOTx_1 is not guaranteed.
- When the external load capacitance $C_L = 30 \text{ pF}$.

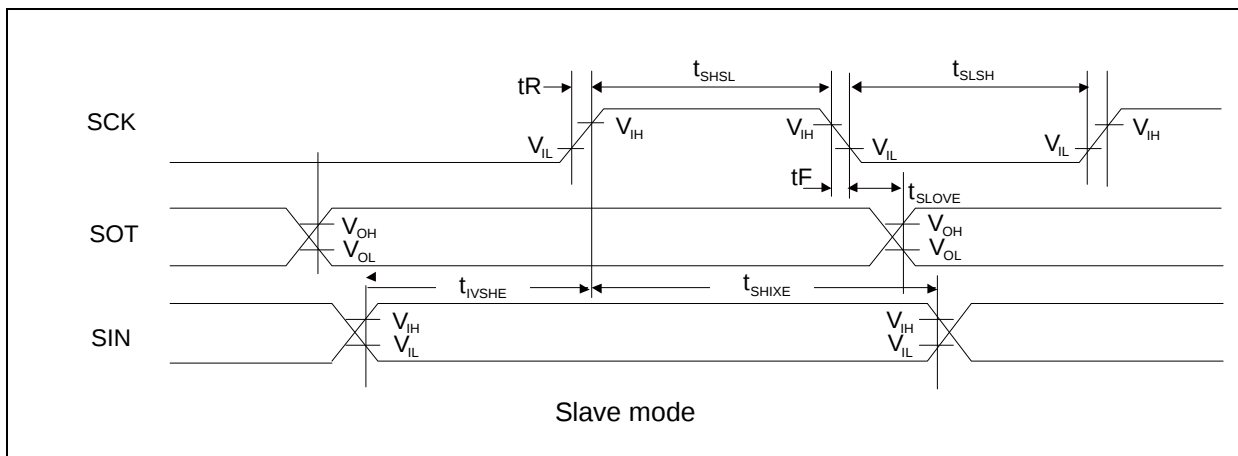
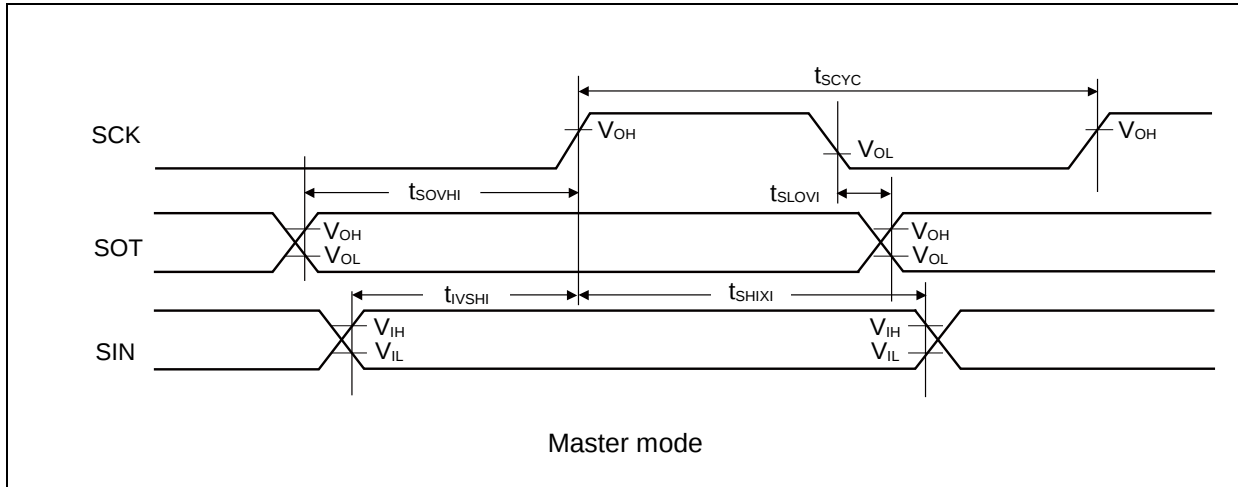


CSIO (SPI = 1, SCINV = 1)
 $(V_{CC} = 2.7V \text{ to } 5.5V, V_{SS} = 0V, T_A = -40^{\circ}C \text{ to } +105^{\circ}C)$

Parameter	Symbol	Pin name	Conditions	$V_{CC} < 4.5 V$		$V_{CC} \geq 4.5 V$		Unit
				Min	Max	Min	Max	
Baud Rate	-	-	-	-	8	-	8	Mbps
Serial clock cycle time	t_{SCYC}	SCKx	Master mode	$4t_{CYCP}$	-	$4t_{CYCP}$	-	ns
SCK ↓ → SOT delay time	t_{SLOVI}	SCKx, SOTx		- 30	+ 30	- 20	+ 20	ns
SIN → SCK ↑ setup time	t_{IVSHI}	SCKx, SINx		50	-	30	-	ns
SCK ↑ → SIN hold time	t_{SHIXI}	SCKx, SINx		0	-	0	-	ns
SOT → SCK ↑ delay time	t_{SOVHI}	SCKx, SOTx		$2t_{CYCP} - 30$	-	$2t_{CYCP} - 30$	-	ns
Serial clock "L" pulse width	t_{LSLH}	SCKx		$2t_{CYCP} - 10$	-	$2t_{CYCP} - 10$	-	ns
Serial clock "H" pulse width	t_{HSL}	SCKx	Slave mode	$t_{CYCP} + 10$	-	$t_{CYCP} + 10$	-	ns
SCK ↓ → SOT delay time	t_{SLOVE}	SCKx, SOTx		-	50	-	33	ns
SIN → SCK ↑ setup time	t_{IVSHE}	SCKx, SINx		10	-	10	-	ns
SCK ↑ → SIN hold time	t_{SHIXE}	SCKx, SINx		20	-	20	-	ns
SCK falling time	t_F	SCKx		-	5	-	5	ns
SCK rising time	t_R	SCKx		-	5	-	5	ns

Notes:

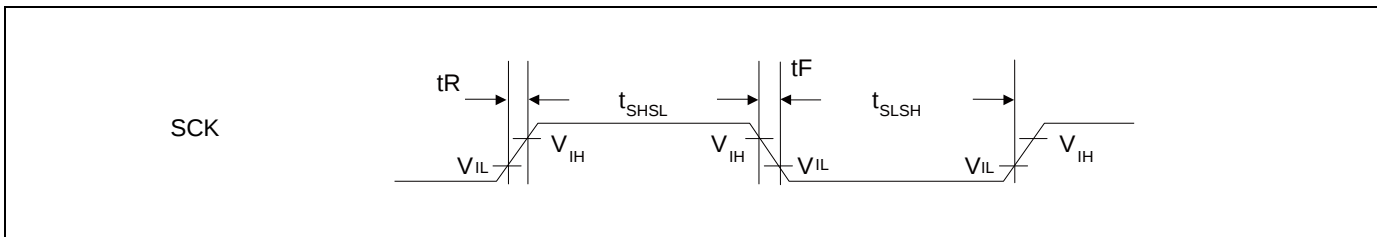
- The above characteristics apply to CLK synchronous mode.
- t_{CYCP} indicates the APB bus clock cycle time.
- About the APB bus number which Multi-function Serial is connected to, see "Block Diagram" in this data sheet.
- These characteristics only guarantee the same relocate port number.
For example, the combination of SCKx_0 and SOTx_1 is not guaranteed.
- When the external load capacitance $C_L = 30 \text{ pF}$.



UART external clock input (EXT = 1)

($V_{CC} = 2.7V$ to $5.5V$, $V_{SS} = 0V$, $T_A = -40^{\circ}C$ to $+105^{\circ}C$)

Parameter	Symbol	Conditions	Value		Unit	Remarks
			Min	Max		
Serial clock "L" pulse width	t_{SLSH}	$C_L = 30 \text{ pF}$	$t_{CYCP} + 10$	-	ns	
Serial clock "H" pulse width	t_{SHSL}		$t_{CYCP} + 10$	-	ns	
SCK falling time	t_F		-	5	ns	
SCK rising time	t_R		-	5	ns	



12.4.11 External Input Timing

($V_{CC} = 2.7V$ to $5.5V$, $V_{SS} = 0V$, $T_A = -40^{\circ}C$ to $+105^{\circ}C$)

Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Min	Max		
Input pulse width	t_{INH} , t_{INL}	ADTG	-	$2t_{CYCP}^{*1}$	-	ns	A/D converter trigger input
		FRCKx					Free-run timer input clock
		ICxx					Input capture
		DTTIXX	-	$2t_{CYCP}^{*1}$	-	ns	Waveform generator
		INTxx	*2	$2t_{CYCP} + 100^{*1}$	-	ns	External interrupt,
			*3	500	-	ns	NMI
		WKUPx	*4	500	-	ns	Deep standby wake up

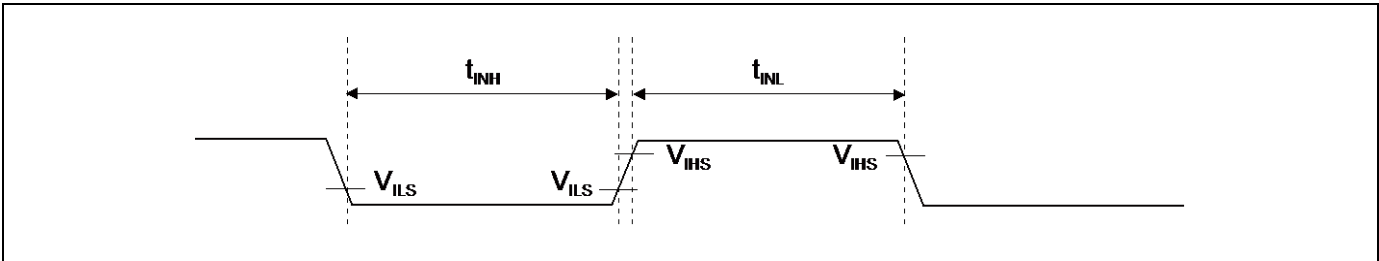
*1: t_{CYCP} indicates the APB bus clock cycle time.

About the APB bus number which the A/D converter, Multi-function Timer, External interrupt are connected to, see "Block Diagram" in this data sheet.

*2: When in RUN mode, in SLEEP mode.

*3: When in STOP mode, in TIMER mode.

*4: When in Deep standby RTC mode, in Deep standby STOP mode.



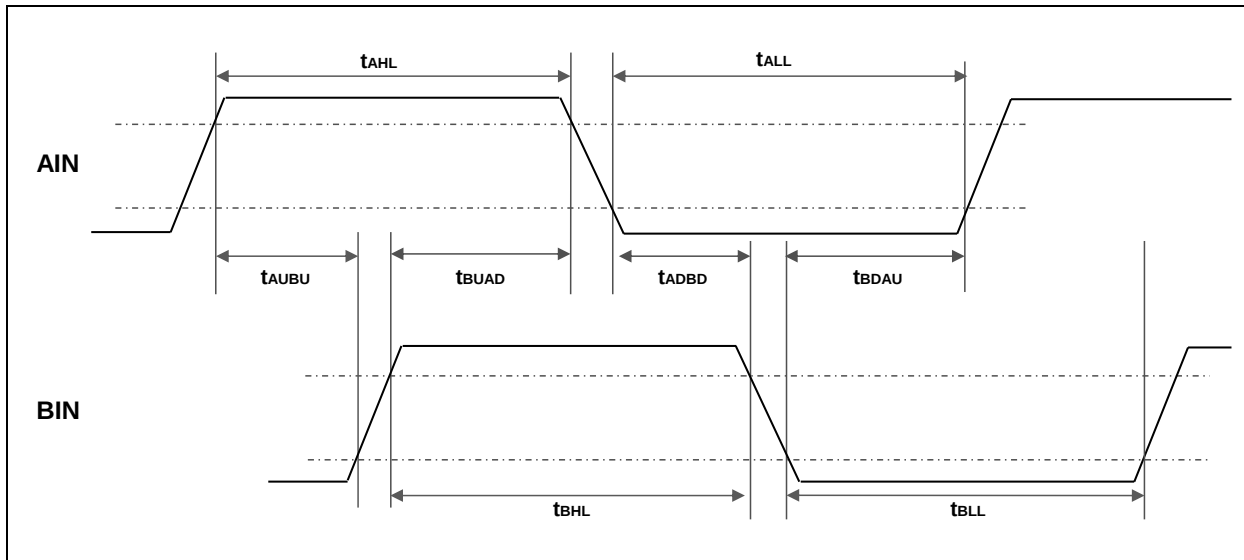
12.4.12 Quadrature Position/Revolution Counter timing

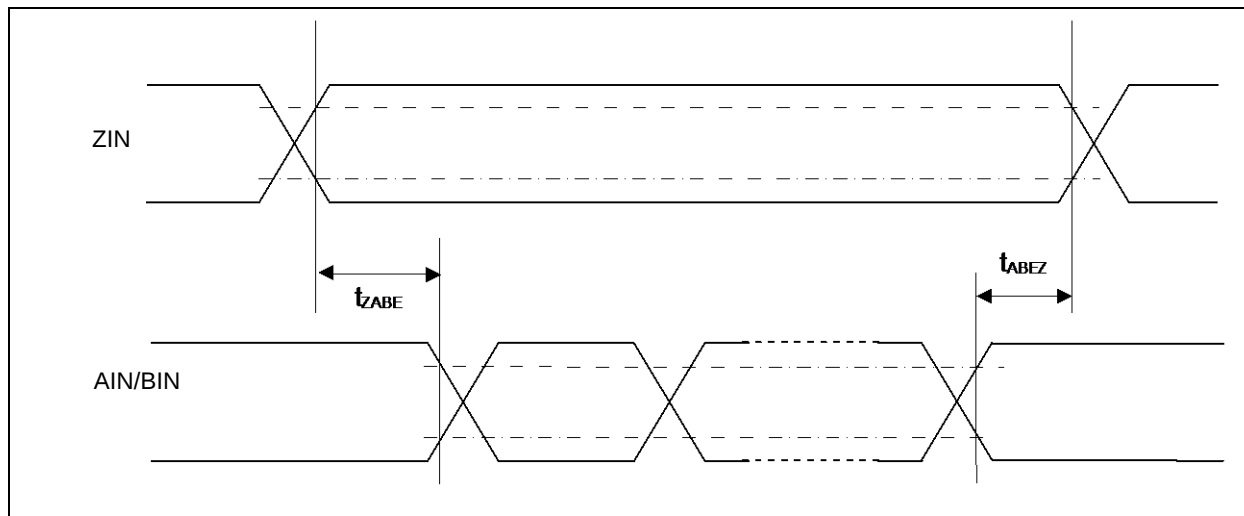
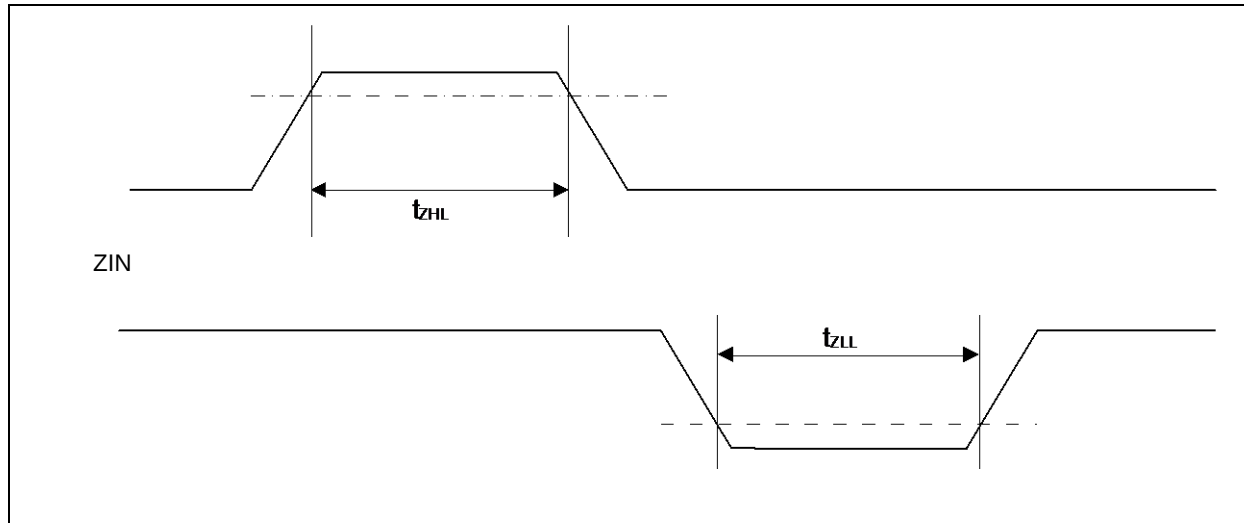
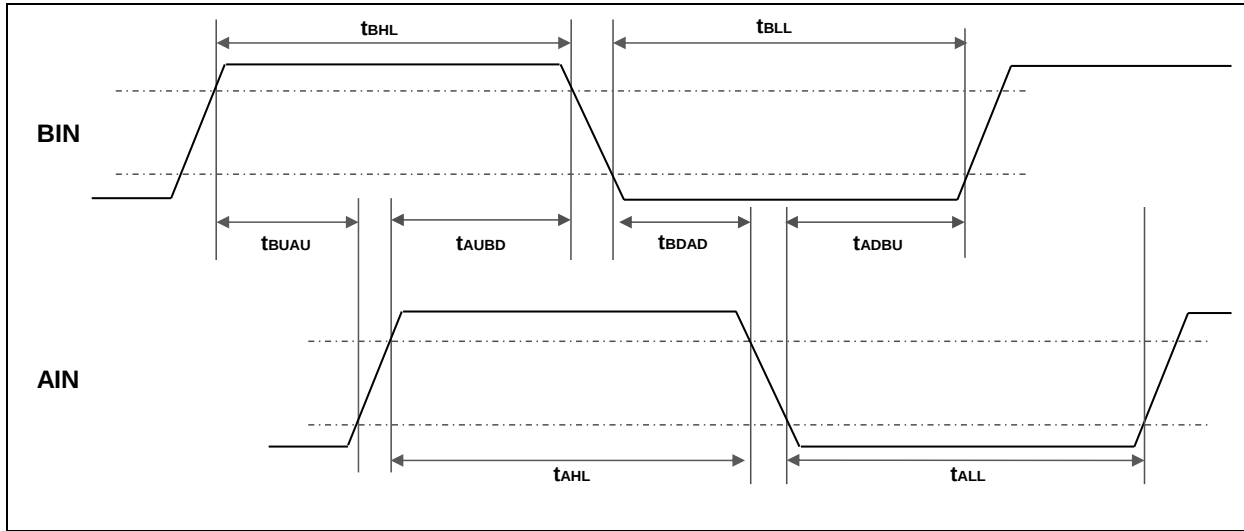
 ($V_{CC} = 2.7V$ to $5.5V$, $V_{SS} = 0V$, $T_A = -40^{\circ}C$ to $+105^{\circ}C$)

Parameter	Symbol	Conditions	Value		Unit
			Min	Max	
AIN pin "H" width	t_{AHL}	-	$2t_{CYCP}^*$	-	ns
AIN pin "L" width	t_{ALL}	-			
BIN pin "H" width	t_{BHL}	-			
BIN pin "L" width	t_{BLL}	-			
Time from AIN pin "H" level to BIN rise	t_{AUBU}	PC_Mode2 or PC_Mode3			
Time from BIN pin "H" level to AIN fall	t_{BUAD}	PC_Mode2 or PC_Mode3			
Time from AIN pin "L" level to BIN fall	t_{ADBD}	PC_Mode2 or PC_Mode3			
Time from BIN pin "L" level to AIN rise	t_{BDAU}	PC_Mode2 or PC_Mode3			
Time from BIN pin "H" level to AIN rise	t_{BUAU}	PC_Mode2 or PC_Mode3			
Time from AIN pin "H" level to BIN fall	t_{AUBD}	PC_Mode2 or PC_Mode3			
Time from BIN pin "L" level to AIN fall	t_{BDAD}	PC_Mode2 or PC_Mode3			
Time from AIN pin "L" level to BIN rise	t_{ADBU}	PC_Mode2 or PC_Mode3			
ZIN pin "H" width	t_{ZHL}	QCR:CGSC="0"			
ZIN pin "L" width	t_{ZLL}	QCR:CGSC="0"			
Time from determined ZIN level to AIN/BIN rise and fall	t_{ZABE}	QCR:CGSC="1"			
Time from AIN/BIN rise and fall to determined ZIN level	t_{ABEZ}	QCR:CGSC="1"			

*: t_{CYCP} indicates the APB bus clock cycle time.

About the APB bus number which the Quadrature Position/Revolution Counter is connected to, see "Block Diagram" in this data sheet.





12.4.13 I²C Timing

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V, T_A = - 40°C to + 105°C)

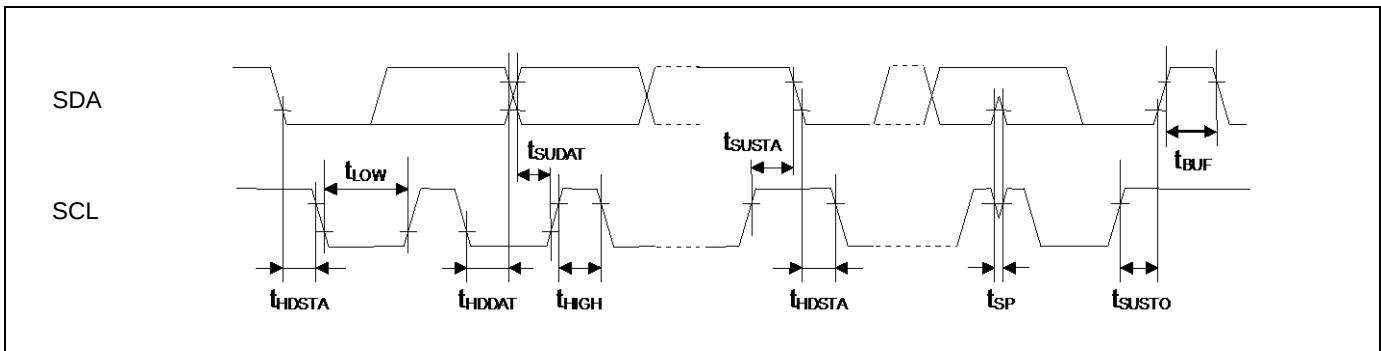
Parameter	Symbol	Conditions	Standard-mode		Fast-mode		Unit	Remarks
			Min	Max	Min	Max		
SCL clock frequency	F _{SCL}	C _L = 30 pF, R = (V _p /I _{OL})* ¹	0	100	0	400	kHz	
(Repeated) START condition hold time SDA ↓ → SCL ↓	t _{HDSTA}		4.0	-	0.6	-	μs	
SCLclock "L" width	t _{LOW}		4.7	-	1.3	-	μs	
SCLclock "H" width	t _{HIGH}		4.0	-	0.6	-	μs	
(Repeated) START condition setup time SCL ↑ → SDA ↓	t _{SUSTA}		4.7	-	0.6	-	μs	
Data hold time SCL ↓ → SDA ↓ ↑	t _{HDDAT}		0	3.45* ²	0	0.9* ³	μs	
Data setup time SDA ↓ ↑ → SCL ↑	t _{SUDAT}		250	-	100	-	ns	
STOP condition setup time SCL ↑ → SDA ↑	t _{SUSTO}		4.0	-	0.6	-	μs	
Bus free time between "STOP condition" and "START condition"	t _{BUF}		4.7	-	1.3	-	μs	
Noise filter	t _{SP}	-	2 t _{CYCP} * ⁴	-	2 t _{CYCP} * ⁴	-	ns	

*1: R and C_L represent the pull-up resistor and load capacitance of the SCL and SDA lines, respectively.
V_p indicates the power supply voltage of the pull-up resistor and I_{OL} indicates V_{OL} guaranteed current.

*2: The maximum t_{HDDAT} must satisfy that it does not extend at least "L" period (t_{LOW}) of device's SCL signal.

*3: Fast-mode I²C bus device can be used on Standard-mode I²C bus system as long as the device satisfies the requirement of "t_{SUDAT} ≥ 250 ns".

*4: t_{CYCP} is the APB bus clock cycle time.
About the APB bus number that I²C is connected to, see "Block Diagram" in this data sheet.
To use Standard-mode, set the APB bus clock at 2 MHz or more.
To use Fast-mode, set the APB bus clock at 8 MHz or more.



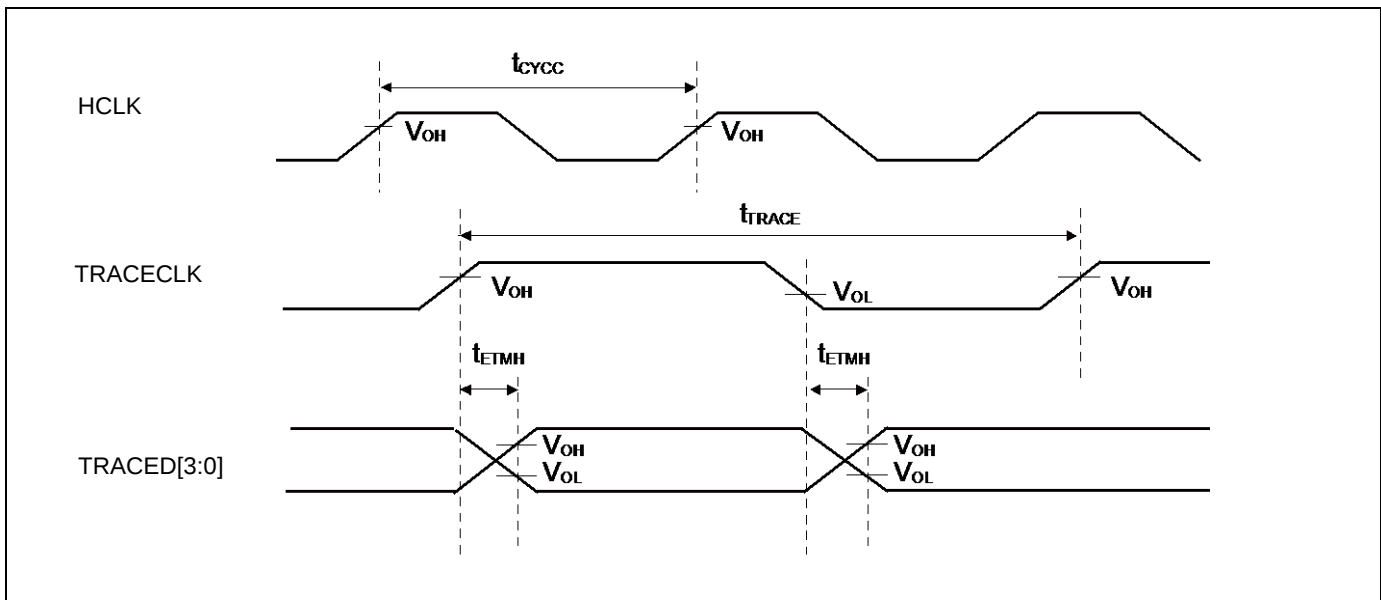
12.4.14 ETM Timing

 ($V_{CC} = 2.7V$ to $5.5V$, $V_{SS} = 0V$, $T_A = -40^{\circ}C$ to $+105^{\circ}C$)

Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Min	Max		
Data hold	t_{ETMH}	TRACECLK, TRACED[3:0]	$V_{CC} \geq 4.5 V$	2	10	ns	
			$V_{CC} < 4.5 V$	2	15		
TRACECLK frequency	$1/t_{TRACE}$	TRACECLK	$V_{CC} \geq 4.5 V$	-	40	MHz	
			$V_{CC} < 4.5 V$	-	20	MHz	
TRACECLK clock cycle	t_{TRACE}	TRACECLK	$V_{CC} \geq 4.5 V$	25	-	ns	
			$V_{CC} < 4.5 V$	50	-	ns	

Note:

- When the external load capacitance $C_L = 30 pF$.



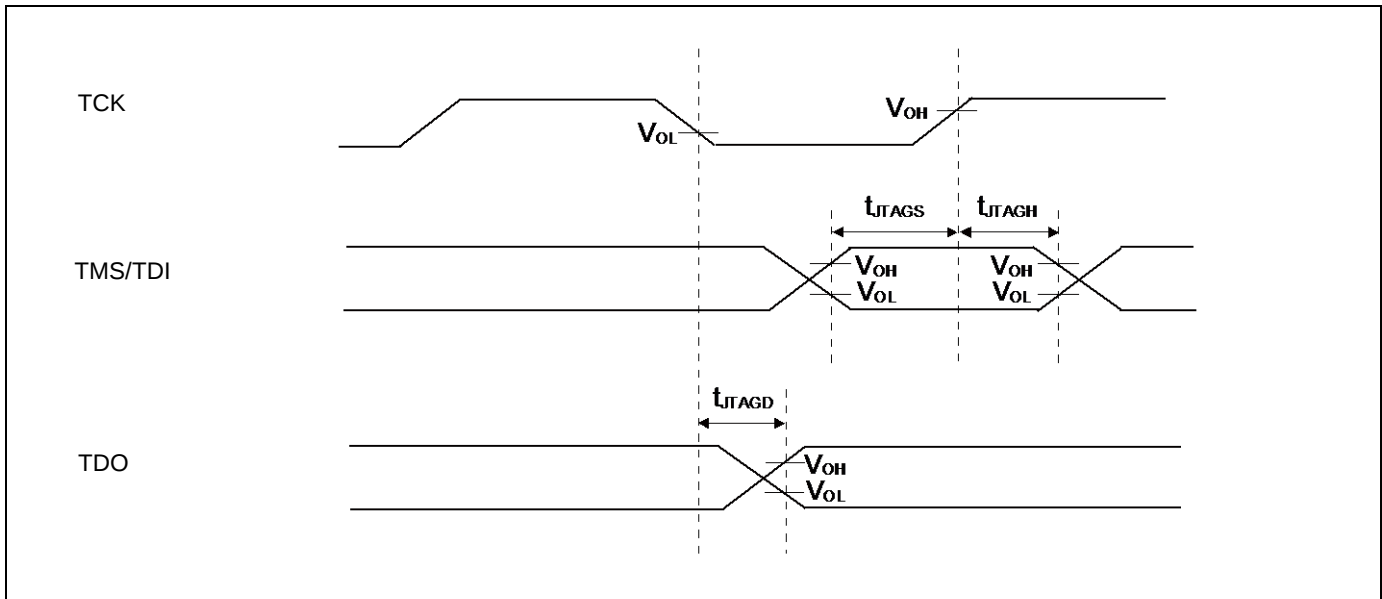
12.4.15 JTAG Timing

($V_{CC} = 2.7V$ to $5.5V$, $V_{SS} = 0V$, $T_A = -40^{\circ}C$ to $+105^{\circ}C$)

Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Min	Max		
TMS, TDI setup time	t_{JTAGS}	TCK, TMS, TDI	$V_{CC} \geq 4.5 V$ $V_{CC} < 4.5 V$	15	-	ns	
TMS, TDI hold time	t_{JTAGH}	TCK, TMS, TDI	$V_{CC} \geq 4.5 V$ $V_{CC} < 4.5 V$	15	-	ns	
TDO delay time	t_{JTAGD}	TCK, TDO	$V_{CC} \geq 4.5 V$	-	25	ns	
			$V_{CC} < 4.5 V$	-	45		

Note:

- When the external load capacitance $C_L = 30 pF$.



12.5 12-bit A/D Converter

Electrical characteristics for the A/D converter

($V_{CC} = AV_{CC} = 2.7V$ to $5.5V$, $V_{SS} = AV_{SS} = 0V$, $T_A = -40^{\circ}C$ to $+105^{\circ}C$)

Parameter	Symbol	Pin name	Value			Unit	Remarks
			Min	Typ	Max		
Resolution	-	-	-	-	12	bit	
Integral Nonlinearity	-	-	-	± 1.5	± 4.5	LSB	AVRH = 2.7V to 5.5V
Differential Nonlinearity	-	-	-	± 2.2	± 2.5	LSB	
Zero transition voltage	V_{ZT}	ANxx	-	± 6	± 15	mV	
Full-scale transition voltage	V_{FST}	ANxx	-	AVRH ± 5	AVRH ± 15	mV	
Conversion time	-	-	1.0*1	-	-	μs	
Sampling time*2	T_s	-	0.3	-	10	μs	
Compare clock cycle*3	T_{cck}	-	50	-	1000	ns	
State transition time to operation permission	T_{stt}	-	-	-	1.0	μs	
Analog input capacity	C_{AIN}	-	-	-	9.5	pF	
Analog input resistor	R_{AIN}	-	-	-	1.62	k Ω	AVCC $\geq 4.5V$
					2.35		AVCC < 4.5V
Interchannel disparity	-	-	-	-	4	LSB	
Analog port input leak current	-	ANxx	-	-	5	μA	
Analog input voltage	-	ANxx	AVRL	-	AVRH	V	
Reference voltage	-	AVRH	2.7	-	AVCC	V	
	-	AVRL	AVSS	-	AVSS	V	

*1: The conversion time is the value of sampling time (T_s) + compare time (T_c).

The condition of the minimum conversion time is when the value of sampling time: 300ns, the value of compare time: 700 ns ($AV_{CC} \geq 4.5V$).

Ensure that it satisfies the value of the sampling time (T_s) and compare clock cycle (T_{cck}).

For setting of the sampling time and compare clock cycle, see "CHAPTER 1-1: A/D Converter" in "FM3 Family PERIPHERAL MANUAL Analog Macro Part".

The register setting of the A/D Converter are reflected in the operation according to the APB bus clock timing.

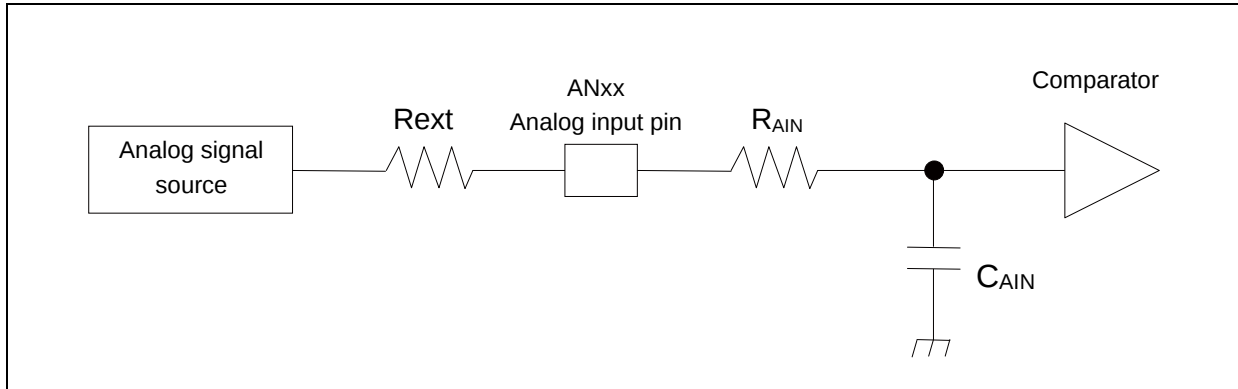
The sampling clock and compare clock is generated from the Base clock (HCLK).

About the APB bus number which the A/D Converter is connected to, see "Block Diagram" in this data sheet.

*2: A necessary sampling time changes by external impedance.

Ensure that it sets the sampling time to satisfy (Equation 1).

*3: The compare time (T_c) is the value of (Equation 2).



(Equation 1) $T_s \geq (R_{AIN} + R_{ext}) \times C_{AIN} \times 9$

T_s: Sampling time

R_{AIN}: Input resistor of A/D = 1.62 kΩ ch.0 to ch.7 at 4.5 V ≤ AV_{CC} ≤ 5.5 V
 Input resistor of A/D = 1.58 kΩ ch.8 to ch.15 at 4.5 V ≤ AV_{CC} ≤ 5.5 V
 Input resistor of A/D = 1.56 kΩ ch.16 to ch.23 at 4.5 V ≤ AV_{CC} ≤ 5.5 V
 Input resistor of A/D = 2.35 kΩ ch.0 to ch.7 at 2.7 V ≤ AV_{CC} < 4.5 V
 Input resistor of A/D = 2.3 kΩ ch.8 to ch.15 at 2.7 V ≤ AV_{CC} < 4.5 V
 Input resistor of A/D = 2.25 kΩ ch.16 to ch.23 at 2.7 V ≤ AV_{CC} < 4.5 V

C_{AIN}: Input capacity of A/D = 9.5 pF at 2.7 V ≤ AV_{CC} ≤ 5.5 V

R_{ext}: Output impedance of external circuit

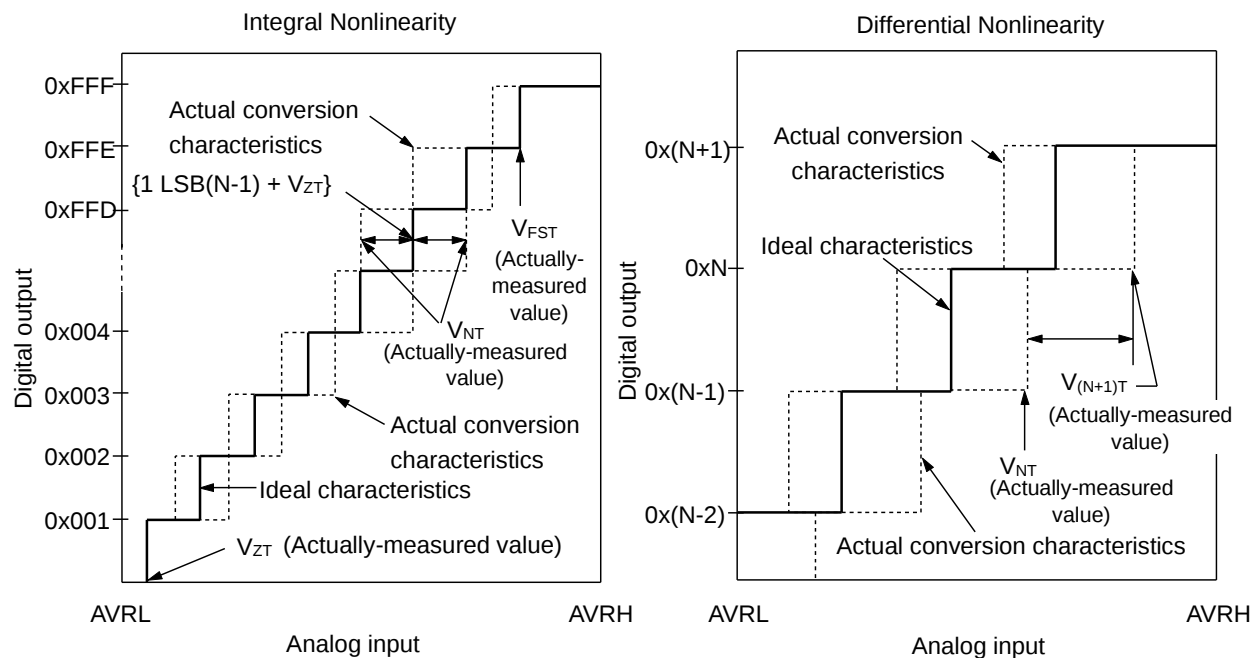
(Equation 2) $T_c = T_{cck} \times 14$

T_c: Compare time

T_{cck}: Compare clock cycle

Definition of 12-bit A/D Converter Terms

- Resolution: Analog variation that is recognized by an A/D converter.
- Integral Nonlinearity: Deviation of the line between the zero-transition point (0b000000000000 ↔ 0b000000000001) and the full-scale transition point (0b111111111110 ↔ 0b111111111111) from the actual conversion characteristics.
- Differential Nonlinearity: Deviation from the ideal value of the input voltage that is required to change the output code by 1 LSB.



$$\text{Integral Nonlinearity of digital output } N = \frac{V_{NT} - \{1\text{LSB} \times (N - 1) + V_{ZT}\}}{1\text{LSB}} [\text{LSB}]$$

$$\text{Differential Nonlinearity of digital output } N = \frac{V_{(N+1)T} - V_{NT}}{1\text{LSB}} - 1 [\text{LSB}]$$

$$1\text{LSB} = \frac{V_{FST} - V_{ZT}}{4094}$$

- N: A/D converter digital output value.
 V_{ZT} : Voltage at which the digital output changes from 0x000 to 0x001.
 V_{FST} : Voltage at which the digital output changes from 0xFFE to 0xFFF.
 V_{NT} : Voltage at which the digital output changes from 0x(N - 1) to 0xN.

12.6 10-bit D/A Converter

Electrical Characteristics for the D/A Converter

($V_{CC} = AV_{CC} = 2.7V$ to $5.5V$, $V_{SS} = AV_{SS} = AV_{RL} = 0V$, $T_A = -40^{\circ}C$ to $+105^{\circ}C$)

Parameter	Symbol	Pin name	Value			Unit	Remarks
			Min	Typ	Max		
Resolution	-	DAX	-	-	10	bit	
Conversion time	tc20		0.47	0.58	0.69	μs	Load 20 pF
	tc100		2.37	2.90	3.43	μs	Load 100 pF
Integral Nonlinearity*1	INL		- 4.0	-	+ 4.0	LSB	
Differential Nonlinearity*1,*2	DNL		- 0.9	-	+ 0.9	LSB	
Output Voltage offset	V _{OFF}		-	-	10.0	mV	Code is 0x000
			- 20.0	-	+ 5.4	mV	Code is 0x3FF
Analog output impedance	R _O		3.10	3.80	4.50	kΩ	D/A operation
			2.0	-	-	MΩ	D/A stop
Output undefined period	t _R	-	-	70	ns		

*1: No-load

*2: Generates the max current by the CODE about 0x200

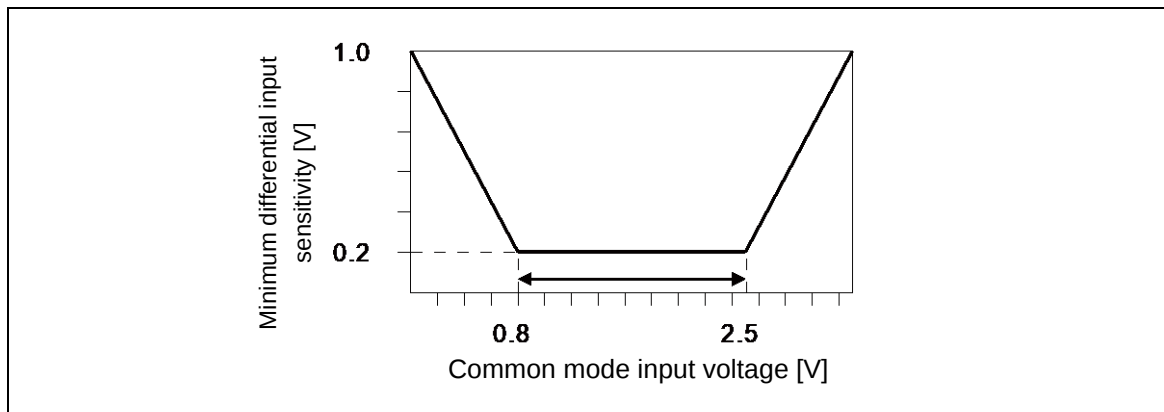
12.7 USB Characteristics

($V_{CC} = 2.7V$ to $5.5V$, $USBV_{CC} = 3.0V$ to $3.6V$, $V_{SS} = 0V$, $T_A = -40^{\circ}C$ to $+105^{\circ}C$)

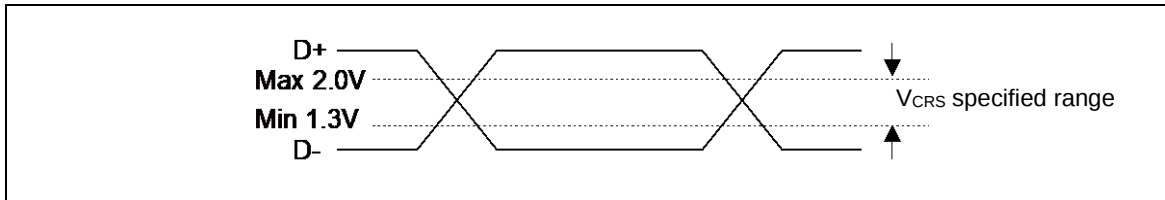
Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Min	Max		
Input characteristics	Input "H" level voltage	V_{IH}	-	2.0	$USBV_{CC} + 0.3$	V	*1
	Input "L" level voltage	V_{IL}	-	$V_{SS} - 0.3$	0.8	V	*1
	Differential input sensitivity	V_{DI}	-	0.2	-	V	*2
	Different common mode range	V_{CM}	-	0.8	2.5	V	*2
Output characteristics	Output "H" level voltage	V_{OH}	External pull-down resistor = 15 k Ω	2.8	3.6	V	*3
	Output "L" level voltage	V_{OL}	External pull-up resistor = 1.5 k Ω	0.0	0.3	V	*3
	Crossover voltage	V_{CRS}	-	1.3	2.0	V	*4
	Rising time	t_{FR}	Full-Speed	4	20	ns	*5
	Falling time	t_{FF}	Full-Speed	4	20	ns	*5
	Rising/falling time matching	t_{FRFM}	Full-Speed	90	111.11	%	*5
	Output impedance	Z_{DRV}	Full-Speed	28	44	Ω	*6
	Rising time	t_{LR}	Low-Speed	75	300	ns	*7
	Falling time	t_{LF}	Low-Speed	75	300	ns	*7
	Rising/falling time matching	t_{LRFM}	Low-Speed	80	125	%	*7

*1: The switching threshold voltage of the Single-End-Receiver of USB I/O buffer is set as within V_{IL} (Max) = 0.8 V, V_{IH} (Min) = 2.0 V (TTL input standard).
There are some hysteresis to lower noise sensitivity.

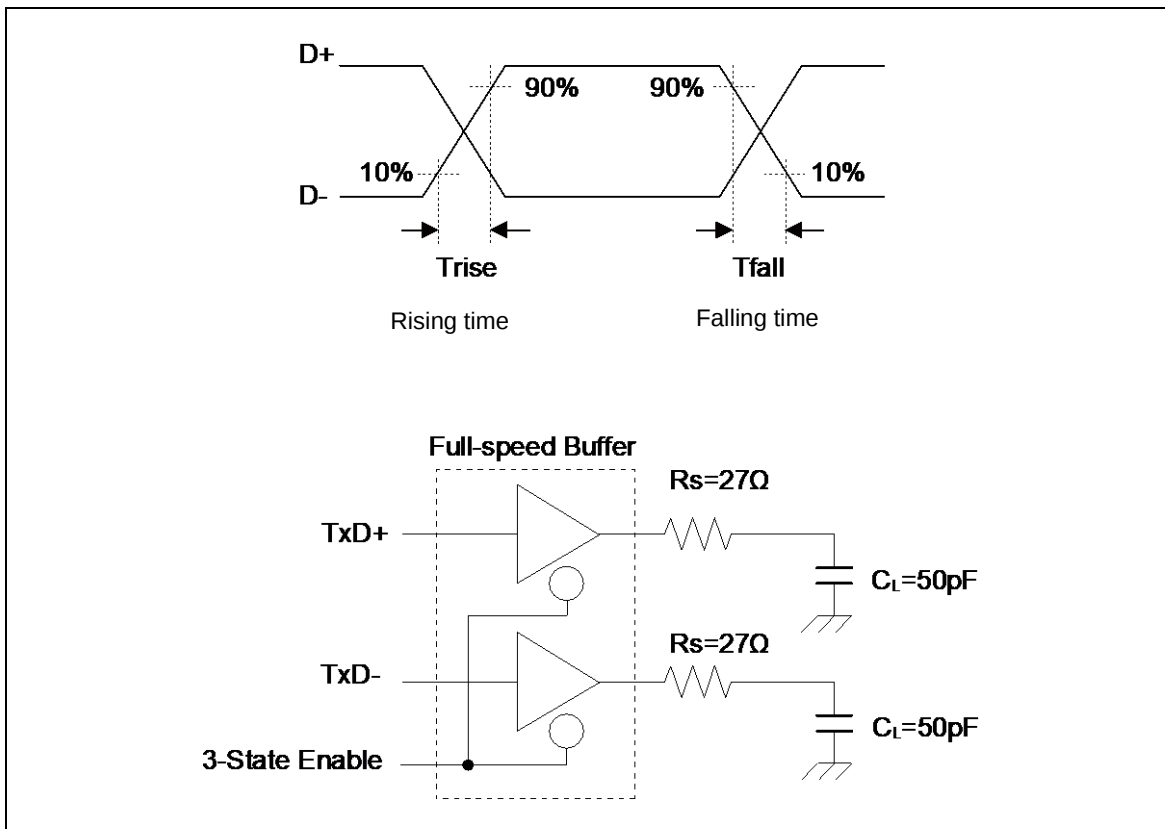
*2: Use the differential-Receiver to receive the USB differential data signal.
The Differential-Receiver has 200 mV of differential input sensitivity when the differential data input is within 0.8 V to 2.5 V to the local ground reference level.
The voltage range above is said to be the common mode input voltage range.



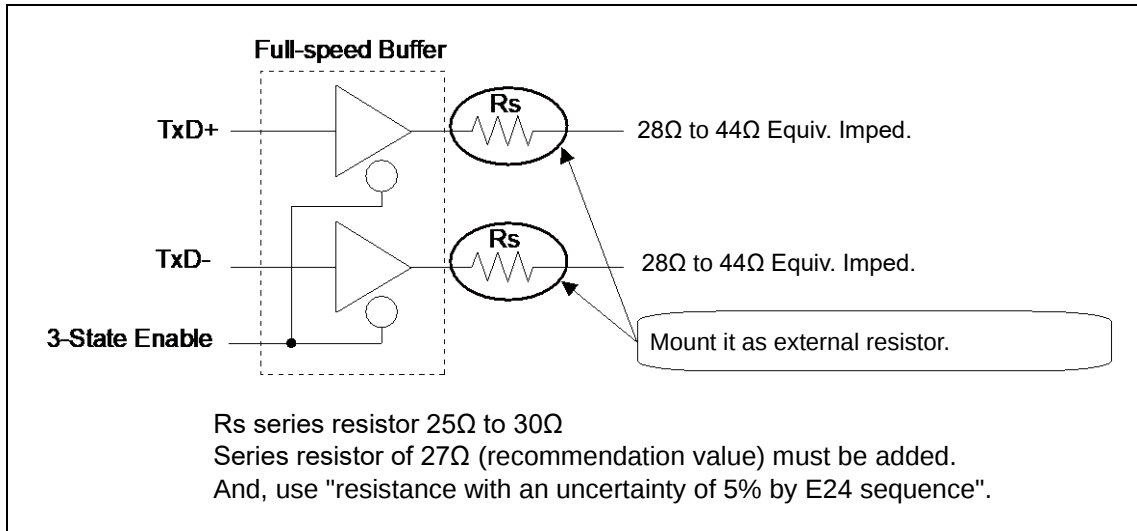
- *3: The output drive capability of the driver is below 0.3 V at Low-State (V_{OL}) (to 3.6 V and 1.5 k Ω load), and 2.8 V or above (to ground and 15 k Ω load) at High-State (V_{OH}).
- *4: The cross voltage of the external differential output signal ($D + / D -$) of USB I/O buffer is within 1.3 V to 2.0 V.



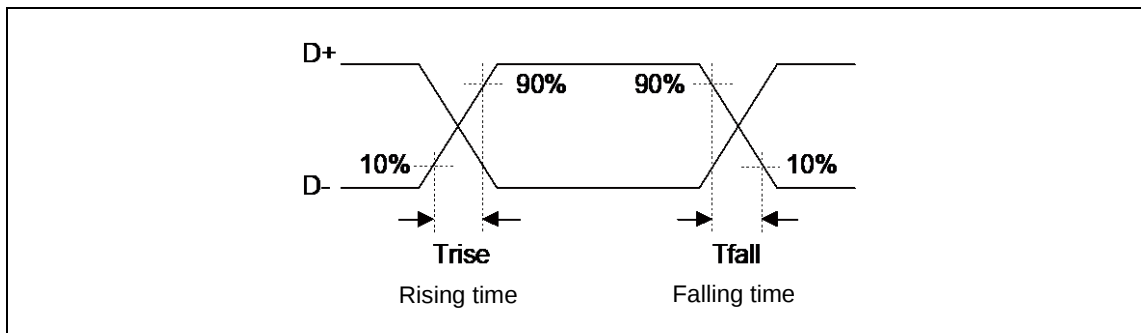
- *5: They indicate rising time (T_{rise}) and falling time (T_{fall}) of the full-speed differential data signal. They are defined by the time between 10% and 90% of the output signal voltage. For full-speed buffer, T_r/T_f ratio is regulated as within $\pm 10\%$ to minimize RFI emission.



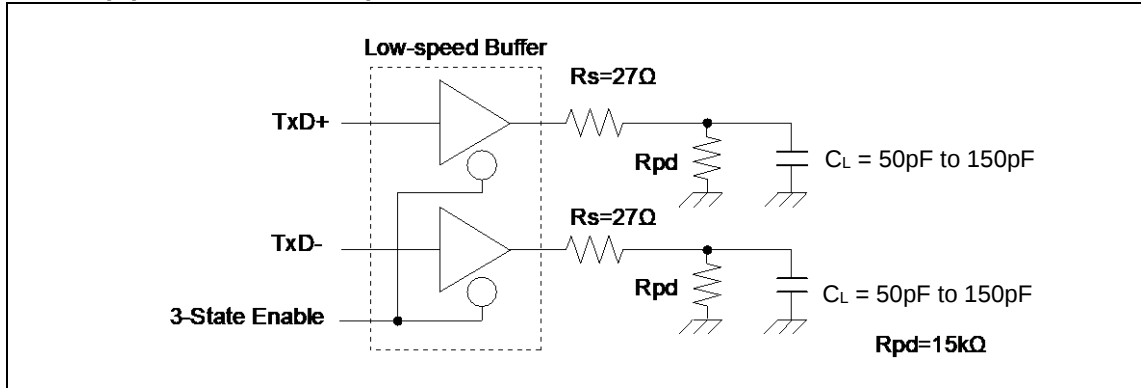
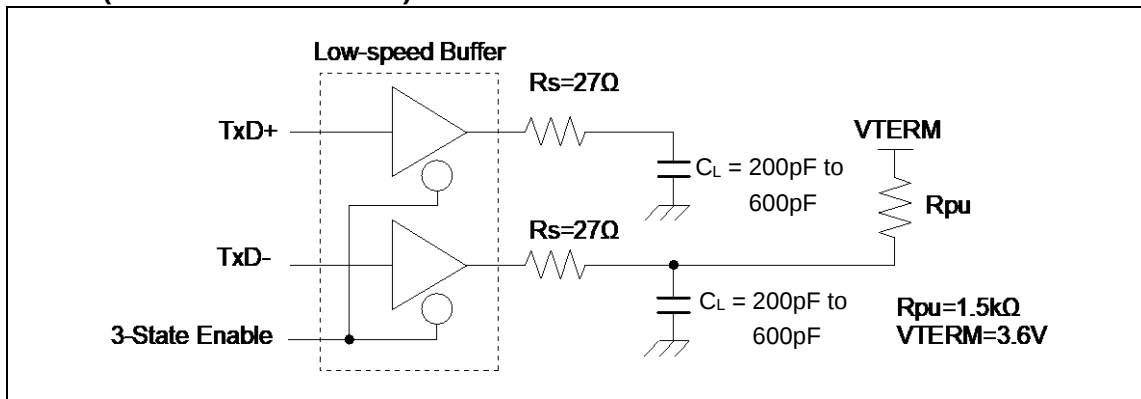
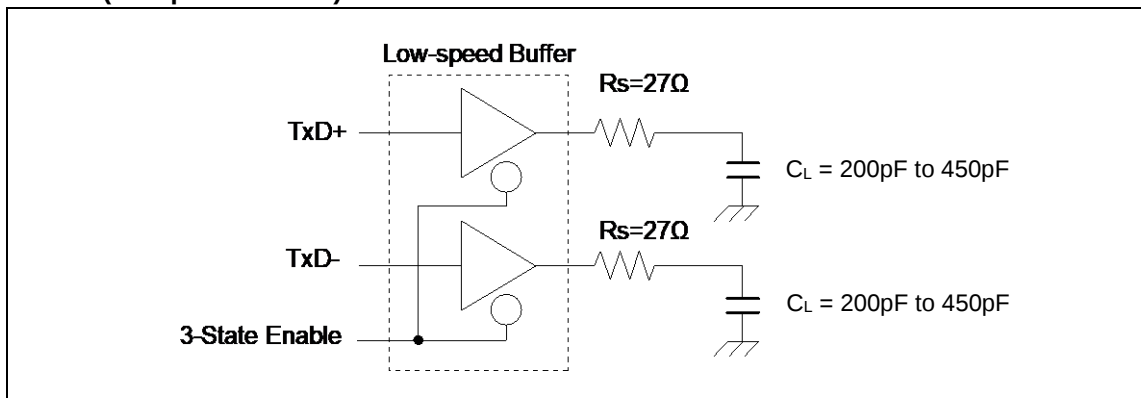
*6: USB Full-speed connection is performed via twist pair cable shield with $90\Omega \pm 15\%$ characteristic impedance (Differential Mode). USB standard defines that output impedance of USB driver must be in range from 28Ω to 44Ω . So, discrete series resistor (R_s) addition is defined in order to satisfy the above definition and keep balance. When using this USB I/O, use it with 25Ω to 30Ω (recommendation value 27Ω) Series resistor R_s .



*7: They indicate rising time (T_{rise}) and falling time (T_{fall}) of the low-speed differential data signal. They are defined by the time between 10% and 90% of the output signal voltage.



See "Low-Speed Load (Compliance Load)" for conditions of the external load.

Low-Speed Load (Upstream Port Load) - Reference 1

Low-Speed Load (Downstream Port Load) - Reference 2

Low-Speed Load (Compliance Load)


12.8 Low-Voltage Detection Characteristics

12.8.1 Low-Voltage Detection Reset

 (T_A = - 40°C to + 105°C)

Parameter	Symbol	Conditions	Value			Unit	Remarks
			Min	Typ	Max		
Detected voltage	VDL	SVHR ^{*1} = 00000	2.25	2.45	2.65	V	When voltage drops
Released voltage	VDH		2.30	2.50	2.70	V	When voltage rises
Detected voltage	VDL	SVHR ^{*1} = 00001	2.39	2.60	2.81	V	When voltage drops
Released voltage	VDH		Same as SVHR = 00000 value			V	When voltage rises
Detected voltage	VDL	SVHR ^{*1} = 00010	2.48	2.70	2.92	V	When voltage drops
Released voltage	VDH		Same as SVHR = 00000 value			V	When voltage rises
Detected voltage	VDL	SVHR ^{*1} = 00011	2.58	2.80	3.02	V	When voltage drops
Released voltage	VDH		Same as SVHR = 00000 value			V	When voltage rises
Detected voltage	VDL	SVHR ^{*1} = 00100	2.76	3.00	3.24	V	When voltage drops
Released voltage	VDH		Same as SVHR = 00000 value			V	When voltage rises
Detected voltage	VDL	SVHR ^{*1} = 00101	2.94	3.20	3.46	V	When voltage drops
Released voltage	VDH		Same as SVHR = 00000 value			V	When voltage rises
Detected voltage	VDL	SVHR ^{*1} = 00110	3.31	3.60	3.89	V	When voltage drops
Released voltage	VDH		Same as SVHR = 00000 value			V	When voltage rises
Detected voltage	VDL	SVHR ^{*1} = 00111	3.40	3.70	4.00	V	When voltage drops
Released voltage	VDH		Same as SVHR = 00000 value			V	When voltage rises
Detected voltage	VDL	SVHR ^{*1} = 01000	3.68	4.00	4.32	V	When voltage drops
Released voltage	VDH		Same as SVHR = 00000 value			V	When voltage rises
Detected voltage	VDL	SVHR ^{*1} = 01001	3.77	4.10	4.43	V	When voltage drops
Released voltage	VDH		Same as SVHR = 00000 value			V	When voltage rises
Detected voltage	VDL	SVHR ^{*1} = 01010	3.86	4.20	4.54	V	When voltage drops
Released voltage	VDH		Same as SVHR = 00000 value			V	When voltage rises
LVD stabilization wait time	T _{LVDW}	-	-	-	6432 × t _{CYCP} ^{*2}	μs	
LVD detection delay time	T _{LVDL}	-	-	-	200	μs	

*1: The SVHR bit of Low-voltage Detection Voltage Control Register (LVD_CTL) is initialized to "00000" by low-voltage detection reset.

*2: t_{CYCP} indicates the APB2 bus clock cycle time.

12.8.2 Interrupt of Low-Voltage Detection

 (T_A = - 40°C to + 105°C)

Parameter	Symbol	Conditions	Value			Unit	Remarks
			Min	Typ	Max		
Detected voltage	VDL	SVHI = 00011	2.58	2.80	3.02	V	When voltage drops
Released voltage	VDH		2.67	2.90	3.13	V	When voltage rises
Detected voltage	VDL	SVHI = 00100	2.76	3.00	3.24	V	When voltage drops
Released voltage	VDH		2.85	3.10	3.35	V	When voltage rises
Detected voltage	VDL	SVHI = 00101	2.94	3.20	3.46	V	When voltage drops
Released voltage	VDH		3.04	3.30	3.56	V	When voltage rises
Detected voltage	VDL	SVHI = 00110	3.31	3.60	3.89	V	When voltage drops
Released voltage	VDH		3.40	3.70	4.00	V	When voltage rises
Detected voltage	VDL	SVHI = 00111	3.40	3.70	4.00	V	When voltage drops
Released voltage	VDH		3.50	3.80	4.10	V	When voltage rises
Detected voltage	VDL	SVHI = 01000	3.68	4.00	4.32	V	When voltage drops
Released voltage	VDH		3.77	4.10	4.43	V	When voltage rises
Detected voltage	VDL	SVHI = 01001	3.77	4.10	4.43	V	When voltage drops
Released voltage	VDH		3.86	4.20	4.54	V	When voltage rises
Detected voltage	VDL	SVHI = 01010	3.86	4.20	4.54	V	When voltage drops
Released voltage	VDH		3.96	4.30	4.64	V	When voltage rises
LVD stabilization wait time	T _{LVDW}	-	-	-	6432 × t _{CYCP} *	μs	
LVD detection delay time	T _{LVDL}	-	-	-	200	μs	

 *: t_{CYCP} indicates the APB2 bus clock cycle time.

12.9 Flash Memory Write/Erase Characteristics

12.9.1 Write / Erase time

($V_{CC} = 2.7V$ to $5.5V$, $T_A = -40^{\circ}C$ to $+105^{\circ}C$)

Parameter		Value		Unit	Remarks
		Typ	Max		
Sector erase time	Large Sector	1.1	2.7	s	Includes write time prior to internal erase
	Small Sector	0.3	0.9		
Half word (16-bit) write time		20	317	μs	Not including system-level overhead time
Chip erase time		31	79	s	Includes write time prior to internal erase

*: The typical value is immediately after shipment, the maximum value is guarantee value under 10,000 cycle of erase/write.

12.9.2 Write cycles and data hold time

Erase/write cycles (cycle)	Data hold time (year)	Remarks
1,000	20*	
10,000	10*	

*: At average $+85^{\circ}C$

12.10 Return Time from Low-Power Consumption Mode

12.10.1 Return Factor: Interrupt/WKUP

The return time from Low-Power consumption mode is indicated as follows. It is from receiving the return factor to starting the program operation.

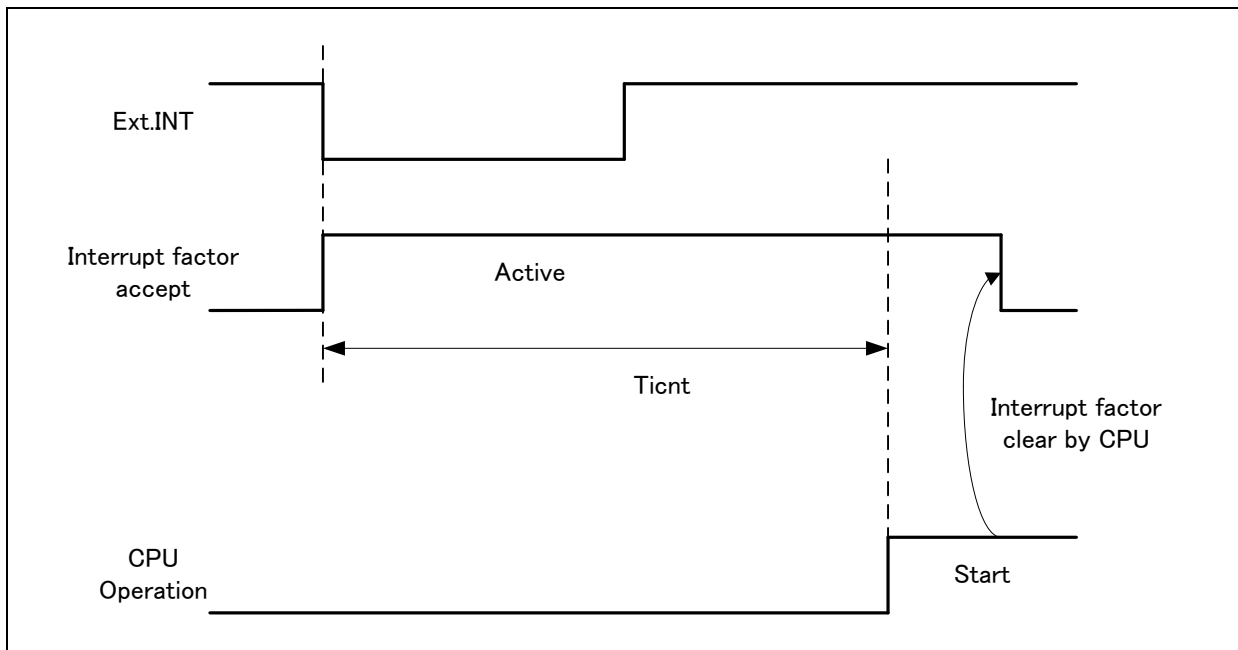
Return Count Time

($V_{CC} = 2.7V$ to $5.5V$, $T_A = -40^{\circ}C$ to $+105^{\circ}C$)

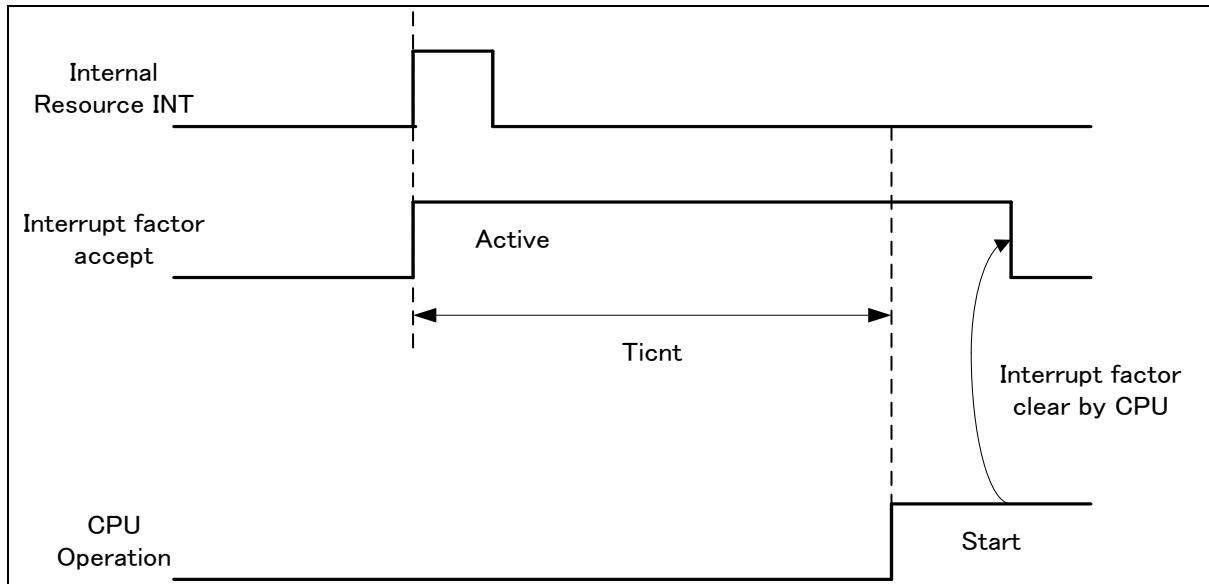
Parameter	Symbol	Value		Unit	Remarks
		Typ	Max*		
SLEEP mode	Ticnt	tcvcc		ns	
High-speed CR TIMER mode, Main TIMER mode, PLL TIMER mode		43	83	μs	
Low-speed CR TIMER mode		310	620	μs	
Sub TIMER mode		534	724	μs	
RTC mode, STOP mode		278	479	μs	
Deep Standby RTC mode, Deep Standby STOP mode		298	543	μs	When RAM is off
		288	523	μs	When RAM is on

*: The maximum value depends on the accuracy of built-in CR.

Operation example of return from Low-Power consumption mode (by external interrupt*)



*: External interrupt is set to detecting fall edge.

Operation example of return from Low-Power consumption mode (by internal resource interrupt*)


*: Internal resource interrupt is not included in return factor by the kind of Low-Power consumption mode.

Notes:

- The return factor is different in each Low-Power consumption modes.
See "CHAPTER 6: Low Power Consumption Mode" and "Operations of Standby Modes" in FM3 Family PERIPHERAL MANUAL about the return factor from Low-Power consumption mode.
- When interrupt recovers, the operation mode that CPU recovers depends on the state before the Low-Power consumption mode transition. See "CHAPTER 6: Low Power Consumption Mode" in "FM3 Family PERIPHERAL MANUAL".

12.10.2 Return Factor: Reset

The return time from Low-Power consumption mode is indicated as follows. It is from releasing reset to starting the program operation.

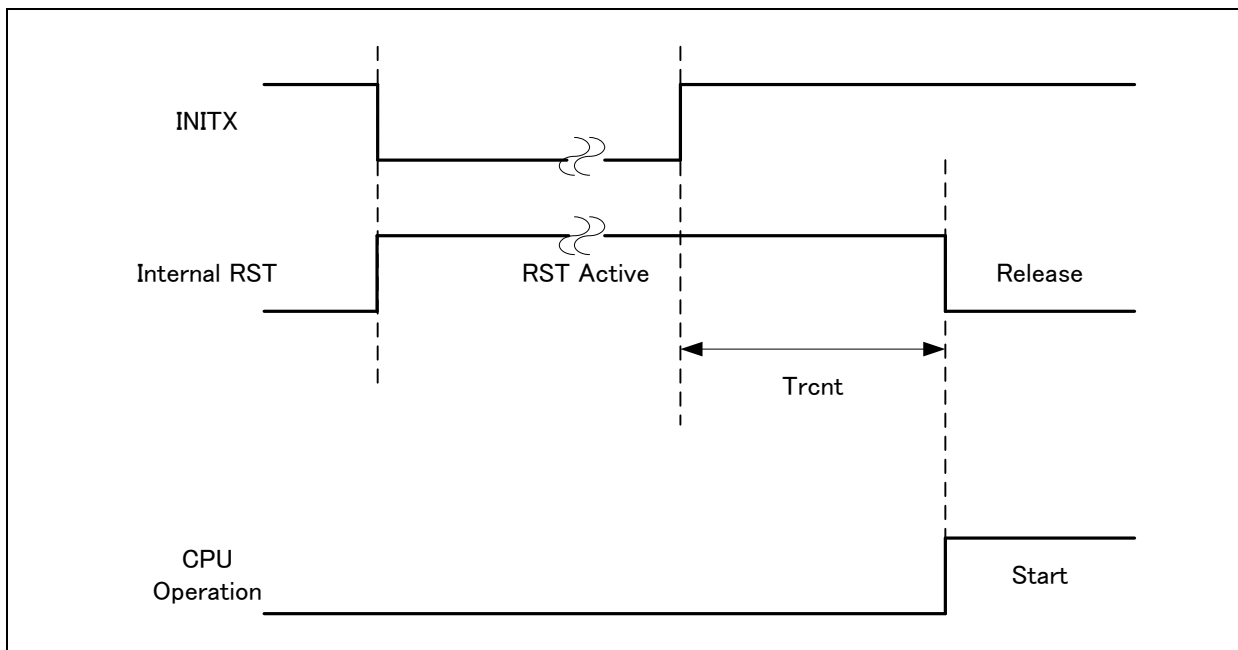
Return Count Time

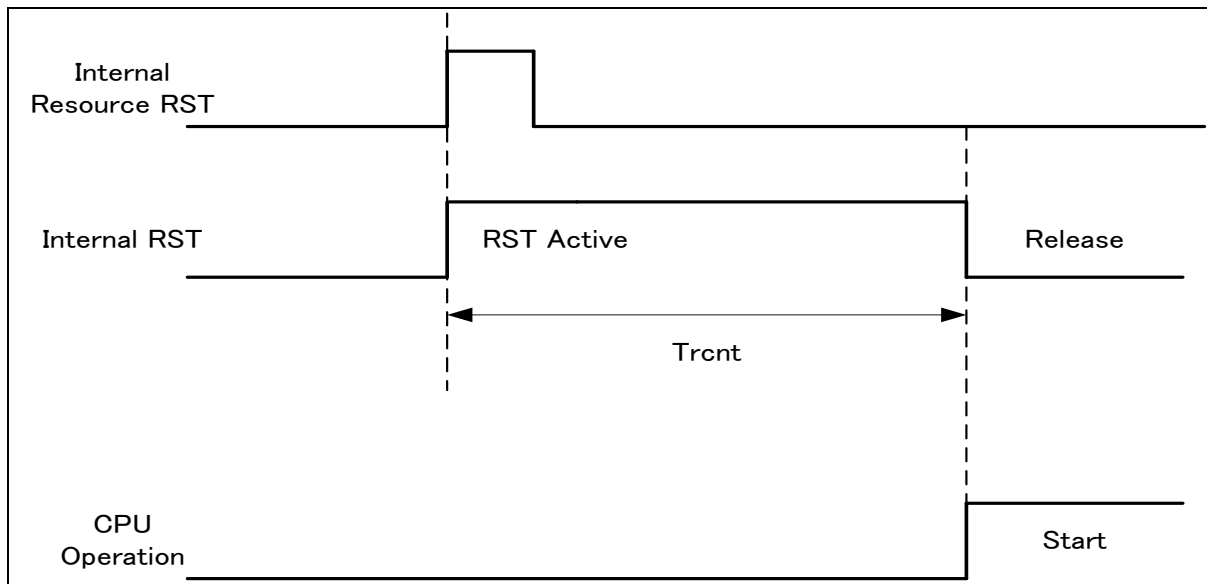
($V_{CC} = 2.7V$ to $5.5V$, $T_A = -40^{\circ}C$ to $+105^{\circ}C$)

Parameter	Symbol	Value		Unit	Remarks
		Typ	Max*		
SLEEP mode	Trcnt	149	264	μs	
High-speed CR TIMER mode, Main TIMER mode, PLL TIMER mode		149	264	μs	
Low-speed CR TIMER mode		318	603	μs	
Sub TIMER mode		308	583	μs	
RTC/STOP mode		248	443	μs	
Deep Standby RTC mode, Deep Standby STOP mode		298	543	μs	When RAM is off
		288	523	μs	When RAM is on

*: The maximum value depends on the accuracy of built-in CR.

Operation example of return from Low-Power consumption mode (by INITX)



Operation example of return from low power consumption mode (by internal resource reset*)


*: Internal resource reset is not included in return factor by the kind of Low-Power consumption mode.

Notes:

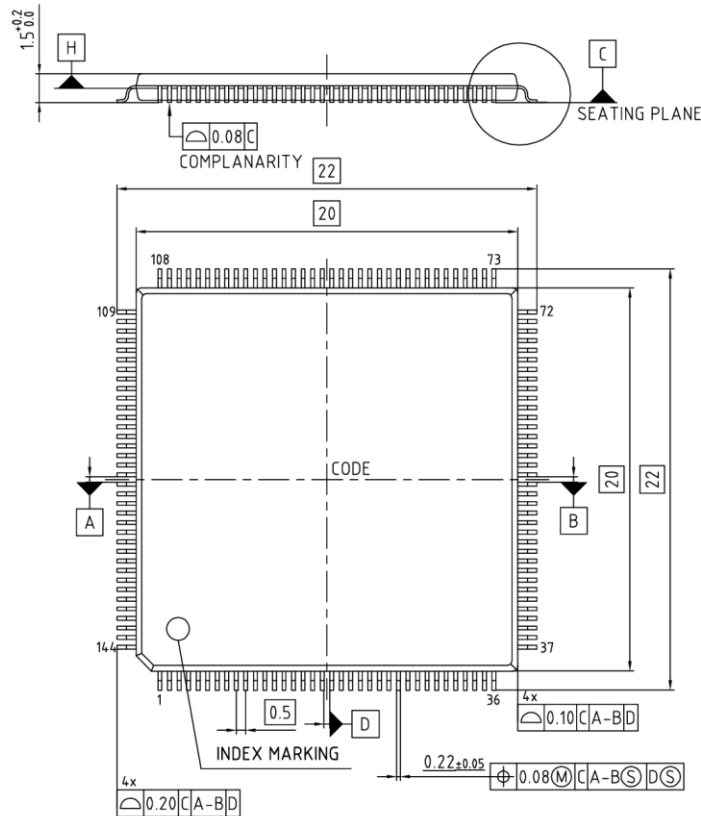
- The return factor is different in each Low-Power consumption modes. See "CHAPTER 6: Low Power Consumption Mode" and "Operations of Standby Modes" in FM3 Family PERIPHERAL MANUAL.
- When interrupt recoveries, the operation mode that CPU recovers depends on the state before the Low-Power consumption mode transition. See "CHAPTER 6: Low Power Consumption Mode" in "FM3 Family PERIPHERAL MANUAL".
- The time during the power-on reset/low-voltage detection reset is excluded. See "(6) Power-on Reset Timing in 4. AC Characteristics in Electrical Characteristics" for the detail on the time during the power-on reset/low -voltage detection reset.
- When in recovery from reset, CPU changes to the high-speed CR run mode. When using the main clock or the PLL clock, it is necessary to add the main clock oscillation stabilization wait time or the main PLL clock stabilization wait time.
- The internal resource reset means the watchdog reset and the CSV reset.

13. Ordering Information

Part number	On-chip Flash memory	On-chip SRAM	Package	Packing
CY9BF328SAPMC-GK7CGE2	Main: 1 Mbyte Work: 64 Kbyte	160 Kbyte	Plastic • LQFP, 144-pin (0.5mm pitch) (LQS144)	Tray
CY9BF329TABGL-GK7E1	Main: 1.5 Mbyte Work: 64 Kbyte	192 Kbyte	Plastic • LFBGA, 192-pin (0.8mm pitch) (LBE192)	

14. Package Dimensions

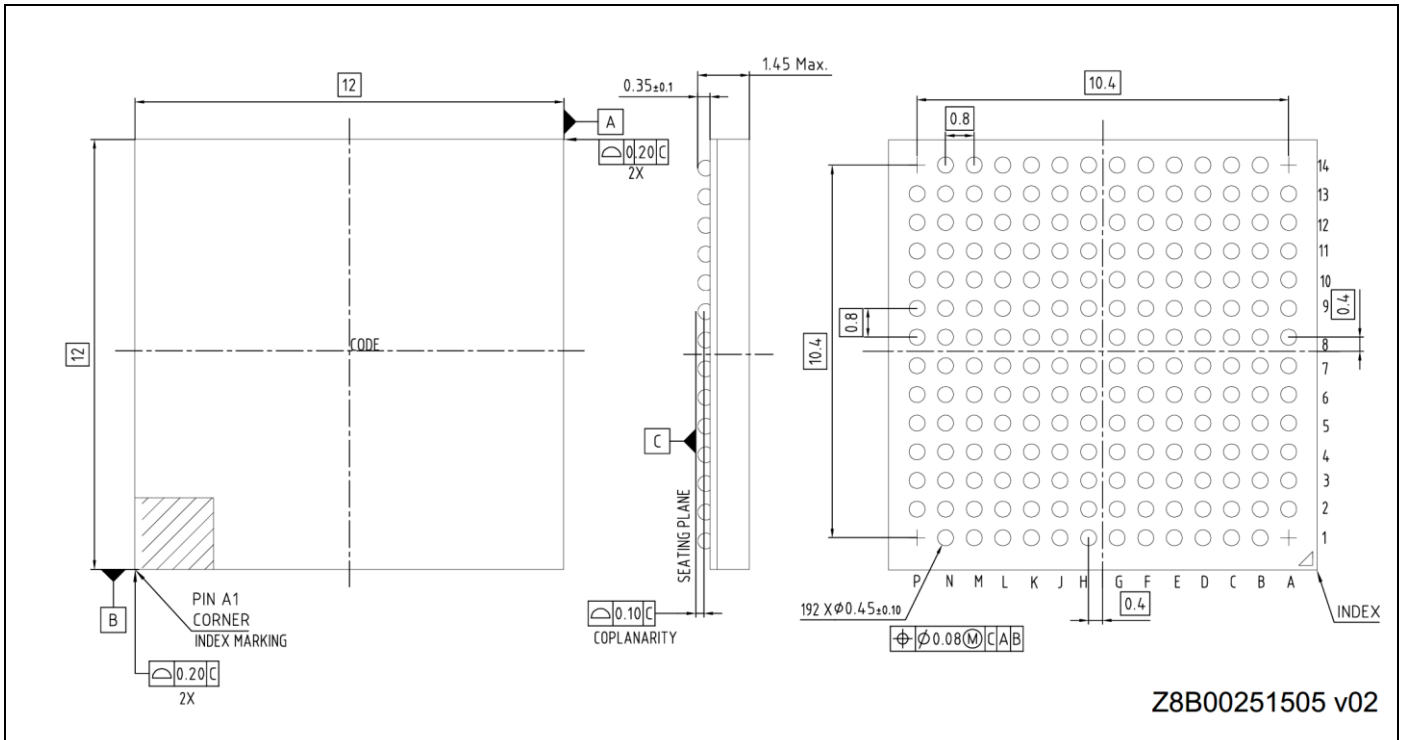
Package Type	Package Code
LQFP 144	LQS144



- 1) DOES NOT INCLUDE PLASTIC OR METAL PROTRUSION OF 0.25 MAX. PER SIDE
 2) DOES NOT INCLUDE DAMBAR PROTRUSION OF 0.08 MAX. PER SIDE AT MAX. MATERIAL CONDITION

Z8B00255984 v02

Package Type	Package Code
BGA 192	LBE192



15. Errata

This chapter describes the errata for MB9B320T series. Details include errata trigger conditions, scope of impact, available workaround, and silicon revision applicability.

Contact your local Cypress Sales Representative if you have questions.

15.1 Part Numbers Affected

Part Number
Initial Revision
MB9BF328TPMC-GE2, MB9BF329TPMC-GE2, MB9BF328TBGL-GE1, MB9BF329TBGL-GE1, MB9BF328SPMC-GE2, MB9BF329SPMC-GE2 MB9BF328TPMC-GK7E2, MB9BF329TPMC-GK7E2, MB9BF328TBGL-GK7E1, MB9BF329TBGL-GK7E1, MB9BF328SPMC-GK7E2, MB9BF329SPMC-GK7E2

15.2 Qualification Status

Product Status: In Production – Qual.

15.3 Errata Summary

This table defines the errata applicability to available devices.

Items	Part Number	Silicon Revision	Fix Status
[1] HDMI-CEC polling message issue	Refer to 15.1	Initial rev.	Fixed in Rev. A

15.4 Errata Detail

15.4.1 HDMI-CEC polling message issue

■ PROBLEM DEFINITION

Error#1) While MCU sends a Polling Message, it always returns a NACK to a message coming to the MCU from another node.

Error#2) MCU always waits for 7-bit signal free on CEC line before it drives the line even when the last line initiator was another node.

■ PARAMETERS AFFECTED

N/A

■ TRIGGER CONDITION(S)

This error always happens.

■ SCOPE OF IMPACT

MCU does not reply properly to another node.

■ WORKAROUND

The software workaround is applied to Error #1.

1. Store 0x0 to SFREE register.
2. Monitor CEC line with GPIO and wait until 1 lasts for the signal free time.
3. Store frame data to TXDATA register and store 0x0F to RCADR1 or RCADR2 register.

It sends a message after 3~4 clocks of 32.768 kHz clock when TXDATA is stored 0x0F.

If the device receives a frame from another node within 2~3 clocks after storing TXDATA, the bus error occurs and if the device receives a frame from another node within 3~4 clocks after storing TXDATA, the arbitration lost occurs. In these cases:

4-A-1. Set RCADR1 or RCADR2 to former value from 0x0F to reply ACK

4-A-2. Return back to step 2 above

If the device receives a frame from another node within 1~2 clocks after storing TXDATA, take these steps.

4-B-1. Monitor CEC line with GPIO after 50us from storing TXDATA

4-B-2. Set TXEN to 1 -> 0 -> 1 immediately when GPIO finds state low on the CEC line

4-B-3. Set RCADR1 or RCADR2 to former value from 0x0F to reply ACK

4-B-4. Return back to step 2 above

For Error #2, there is no software workaround, but signal free time of fixed 7-bit does not violate HDMI-CEC specification. The specification says signal free time must be more than and equals to 5-bit.

■ **FIX STATUS**

This issue was fixed in Rev. A.

16. Major Changes

Spanion Publication Number: DS706-00062

Page	Section	Change Results
Revision 0.1		
-	-	Initial release
Revision 0.2		
-	-	Company name and layout design change
Revision 1.0		
-	-	Preliminary → Full Production
2	FEATURES External Bus Interface	Added the descriptions as follows • Maximum area size : Up to 256 Mbytes
3	FEATURES A/D Converter	Corrected conversion time
5	FEATURES Multi-function Timer	Corrected the channel count of "A/D activation compare"
8	PRODUCT LINEUP Function	Added the footnote
64	HANDLING DEVICES • Power supply pins	Added the description
66	BLOCK DIAGRAM	Corrected the figure
67	MEMORY MAP • Memory Map(1)	Corrected the Address of "External Device Area"
77	ELECTRICAL CHARACTERISTICS 1. Absolute Maximum Ratings	Added the Item of "Input Voltage"
79	2. Recommended Operating Conditions	Added the footnote
80 - 82	3.DC Characteristics (1) Current Rating	• Corrected the Condition • Corrected the Value • Corrected the Remarks • Added the footnote
84	(2) Pin Characteristics	Added the Item of "Input leak current"
89	4. AC Characteristics (6) Power-on Reset Timing	• Revised the values of "Time until releasing Power-on reset" • Corrected the figure • Corrected the Glossary
108	(9) CSIO Timing • Synchronous serial (SPI=1, SCINV=1)	Corrected the figure of "MS bit=1"
	• External clock (EXT=1):asynchronous only	Corrected the figure
115	5.12-bit A/D Converter • Electrical characteristics for the A/D converter	• Corrected the Pins name AN00 - AN23 → ANxx • Corrected the Min Vale of "Conversion time" • Corrected the Min Vale of "Sampling time" • Corrected the Min Value of "Compare clock cycle" • Corrected the "State Transition time to operation permission" • Corrected the footnote
125	9. Electrical characteristics for the A/D converter (1) Write / Erase time	Revised the values of "TBD"
126	10. Return Time from Low-Power Consumption Mode (1) Return Factor: Interrupt/WKUP • Return Count Time	Revised the values of "TBD"
128	(2) Return Factor: Reset • Return Count Time	Revised the values of "TBD"

Page	Section	Change Results
Revision 2.0		
-	-	Changed the series name. MB9B320T Series -> MB9B320TA Series
-	-	Changed the product name as follows. MB9BF328SA, MB9BF329SA, MB9BF328TA, MB9BF329TA
2	Features USB Interface	Added the description of PLL for USB
42 to 49	List of Pin Functions · List of pin functions	Added LIN to the description of SOTxx
56, 57	I/O Circuit Type	Added about +B input
68	Memory Map · Memory map(2)	Added the summary of Flash memory sector
77, 78	Electrical Characteristics 1. Absolute Maximum Ratings	· Added the Clamp maximum current · Added about +B input
80, 81	Electrical Characteristics 3. DC Characteristics (1) Current rating	· Changed the expression of condition · Added Main TIMER mode current
88	Electrical Characteristics 4. AC Characteristics (4-1) Operating Conditions of Main and USB PLL (4-2) Operating Conditions of Main PLL	· Added the figure of Main PLL connection and USB PLL connection
101 to 108	Electrical Characteristics 4. AC Characteristics (7) CSIO/UART Timing	· Modified from UART Timing to CSIO/UART Timing · Changed from Internal shift clock operation to Master mode · Changed from External shift clock operation to Slave mode
115	Electrical Characteristics 5. 12bit A/D Converter	· Added the typical value of Integral Nonlinearity, Differential Nonlinearity, Zero transition voltage and Full-scale transition voltage
130	Ordering Information	Change to full part number

NOTE: Please see “Document History” about later revised information.

Document History

Document Title: MB9B320TA Series, 32-bit Arm® Cortex®-M3 FM3 Microcontroller

Document Number: 002-05665

Revision	ECN	Submission Date	Description of Change								
**	-	01/30/2015	Migrated to Cypress and assigned document number 002-05665. No change to document contents or format.								
*A	5207566	04/05/2016	Updated to Cypress template.								
*B	5653479	03/10/2017	Corrected the package codes the following chapters as the table below. 2. Packages 3. Pin Assignment 13. Ordering Information 14. Package Dimensions <table><tr><th>Before</th><th>After</th></tr><tr><td>FPT-144P-M08</td><td>LQS144</td></tr><tr><td>FPT-176P-M07</td><td>LQP176</td></tr><tr><td>BGA-192P-M06</td><td>LBE192</td></tr></table> Corrected the following statement USB Function → USB Device in chapter Features (Page 1) 1. Product Lineup (Page 7) 4. List of Pin Functions (Page 50) 8. Block Diagram (Page 64) Modified RTC description in chapter Features Before The interrupt function with specifying date and time (Year/Month/Day/Hour/Minute/Second/A day of the week.) is available. After The interrupt function with specifying date and time (Year/Month/Day/Hour/Minute.) is available. Corrected a word “J-TAG” to “JTAG” in 4. List of Pin Functions (Page 32) Added a note of “TAP Controller” in 4. List of Pin Functions (Page 52) Corrected sector size of Memory Map (2) in 10. Memory Map. ROM1_SA8_15(8KBx8) → ROM1_SA8_15(64KBx8) Replace a word “Ta” to “T_A” in the following chapters. 12.2. Recommended Operating Conditions 12.3. DC Characteristics 12.4. AC Characteristics 12.5. 12-bit A/D Converter 12.6. 10-bit D/A Converter 12.7. USB Characteristics 12.8. Low-Voltage Detection Characteristics 12.9. Flash Memory Write/Erase Characteristics 12.10. Return Time from Low-Power Consumption Mode Updated 12.4.7. Power-on Reset Timing Added the Baud rate spec in 12.4.10 CSIO Timing (Page 103, 105, 107, 109) Corrected the following statement Analog port input current → Analog port input leak current in chapter 12.5. 12-bit A/D Converter (Page 117) Corrected the Part numbers	Before	After	FPT-144P-M08	LQS144	FPT-176P-M07	LQP176	BGA-192P-M06	LBE192
Before	After										
FPT-144P-M08	LQS144										
FPT-176P-M07	LQP176										
BGA-192P-M06	LBE192										

Revision	ECN	Submission Date	Description of Change
			MB9BF328SAPMC-GE1 → MB9BF328SAPMC-GK7E2 MB9BF329SAPMC-GE1 → MB9BF329SAPMC-GK7E2 MB9BF328TAPMC-GE1 → MB9BF328TAPMC-GK7E2 MB9BF329TAPMC-GE1 → MB9BF329TAPMC-GK7E2 MB9BF328TABGL-GE1 → MB9BF328TABGL-GK7E1 MB9BF329TABGL-GE1 → MB9BF329TABGL-GK7E1 In chapter 13. Ordering Information (Page 132) Updated 14. Package Dimensions Added 15. Errata Updated to new template.
*C	5790535	07/03/2017	Updated Cypress Logo and Copyright.
*D	6013729	01/12/2018	Updated 14. Package Dimensions : Updated figure of LBE192 (spec 002-13493 – Changed revision from ** to *A). Updated to new template. Completing Sunset Review.
*E	6623528	07/15/2019	Updated Ordering Information: Updated part numbers. Updated to new template.
*F	8094577	12/16/2024	Updated Product Lineup, List of Pin Functions, Memory Map and Ordering Information. Replaced package diagram spec 002-13015 by Z8B00255984 and 002-13493 by Z8B00251505. Completing ECN Sunset Review.

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